

# Quantum-transport analysis of transistors based on nanoribbons of novel 2D materials

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University of Zagreb

FACULTY OF ELECTRICAL ENGINEERING AND COMPUTING

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**QUANTUM-TRANSPORT ANALYSIS OF  
TRANSISTORS BASED ON  
NANORIBBONS OF NOVEL 2D MATERIALS**

DOCTORAL THESIS

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Sveučilište u Zagrebu  
FAKULTET ELEKTROTEHNIKE I RAČUNARSTVA

Mislav Matić

**KVANTNOTRANSPORTNA ANALIZA  
TRANZISTORA TEMELJENIH NA  
NANOVRPCAMA NOVIH 2D MATERIJALA**

DOKTORSKI RAD

Mentor: izv. prof. dr. sc. Mirko Poljak

Zagreb, 2024.

The doctoral thesis was completed at the University of Zagreb Faculty of Electrical Engineering and Computing, Department of Electronics, Microelectronics, Computers and Intelligent Systems, Zagreb, Croatia.

Supervisor: Associate Professor Mirko Poljak, PhD

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## About the Supervisor

Mirko Poljak is an Associate Professor at the Faculty of Electrical Engineering and Computing, University of Zagreb (UNIZG-FER). At this institution, he received the PhD degree in the field of nanoelectronics in May 2013 under the supervision of Prof. Tomislav Suligoj, PhD (UNIZG-FER) and Prof. Kang L. Wang, PhD (University of California Los Angeles, UCLA). In summer 2009 he attended the European School on Nanosciences and Nanotechnologies in Grenoble (France). In the academic year 2011/2012 he was a Visiting Researcher - Fulbright Fellow - in the Device Research Lab, Department of Electrical Engineering, UCLA (USA). In December 2014 and June 2015 he did research visits at the Atomistic Simulation Centre, Queen's University Belfast, Belfast (UK).

Prof. Poljak's research is focused on theoretical understanding and developing models and numerical simulators for the design, analysis and optimization of electron devices at the nanoscale. During his doctoral studies, he worked on carrier transport in low-dimensional nanoelectronic devices such as UTB SOI, FinFET and UTB InGaAs-OI. During his stay at UCLA, he investigated electronic and transport properties of graphene and graphene nanoribbons, both experimentally and theoretically. His current research interests include the development of an atomistic quantum-transport numerical tool (TCAD) for the analysis of nanodevices based on 2D/1D materials for applications in nanoelectronics. Prof. Poljak has authored more than 30 papers in international journals and more than 50 conference papers.

He serves as reviewer for Nature Electronics, IEEE Electron Device Letters, IEEE Transactions on Electron Devices, Applied Physics Letters, 2D Materials, Nanoscale, Journal of Applied Physics, Solid-State Electronics, etc. Prof. Poljak is a Senior Member of IEEE since 2019, and member of IEEE Electron Devices Society and Croatian Society MIPRO since 2007. In the period 2018-2021 he was Chair, in 2022-2023 Vice-Chair, and from 2024 again Chair of the Joint ED/SSC Chapter, IEEE Croatia Section. He is member of the Program Committee for MIPRO-MEET from 2021. Prof. Poljak was awarded the National Science Award (2017), Annual Science Award by the Association of University Professors in Zagreb (2017), FER's Science Award for World-Class Research Achievement (2016), Vera Johanides Award by the

Croatian Academy of Engineering (2014), FER's Silver Medal and "Josip Lončar" Award for Outstanding PhD Thesis (2013), FER's Science Award for Outstanding Research Achievements (2013) and the prestigious Fulbright Fellowship by the US Government (2011). He is the author of the university textbook "Quantum Transport on the Nanoscale" (Element, Zagreb, 2023).

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- <https://scholar.google.hr/citations?user=vTvsOCIAAAAJ&hl>
- [https://www.researchgate.net/profile/Mirko\\_Poljak](https://www.researchgate.net/profile/Mirko_Poljak)
- <https://www.scopus.com/authid/detail.uri?authorId=24344736100>
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## O mentoru

Mirko Poljak je izvanredni profesor na Fakultetu elektrotehnike i računarstva Sveučilišta u Zagrebu (UNIZG-FER). Na ovoj instituciji je doktorirao u svibnju 2013. u području nanoelektronike pod mentorstvom prof. dr. sc. Tomislava Suligoja (UNIZG-FER) i prof. dr. sc. Kanga L. Wanga (University of California Los Angeles, UCLA). U ljeto 2009. usavršavao se na European School on Nanosciences and Nanotechnologies u Grenobleu (Francuska). U akad. god. 2011./2012. bio je gostujući istraživač - Fulbright Fellow - u grupi Device Research Lab, Department of Electrical Engineering, UCLA (SAD). U prosincu 2014. i lipnju 2015. je bio na dva jednodnevna usavršavanja u Atomistic Simulation Centre, Queen's University Belfast, Belfast (UK).

Znanstveni rad profesora Poljaka fokusiran je na teorijsko razumijevanje te razvoj modela i numeričkih simulatora za projektiranje, analizu i optimizaciju elektroničkih komponenti na nanoskali. Za vrijeme doktorskog studija, bio je fokusiran na transport nosilaca u niskodimenzionalnim nanoelektroničkim strukturama poput UTB SOI, FinFET i UTB InGaAs-OI. Za vrijeme boravka na UCLA-u, istraživao je transportna i elektronska svojstva grafena i grafenskih nanovrpca, eksperimentalno i teorijski. Trenutni fokus je na razvoju atomističkog kvantnotransportnog simulatora za nanoelektroničke komponente s 2D/1D materijalima za primjene u elektronici na nanoskali. Prof. Poljak je autor preko 30 radova u međunarodnim časopisima i preko 50 znanstvenih radova na međunarodnim konferencijama.

Recenzent je časopisa Nature Electronics, IEEE Electron Device Letters, IEEE Transactions on Electron Devices, 2D Materials, Nanoscale, Applied Physics Letters, Journal of Applied Physics, Solid-State Electronics itd. Prof. Poljak je IEEE Senior Member od 2019., te član IEEE Electron Devices Society i Hrvatske udruge MIPRO od 2007. godine. U periodu 2018.-2021. bio je predsjednik, u periodu 2022.-2023. dopredsjednik te od 2024. godine ponovno predsjednik Zajedničkog odjela ED/SSC Hrvatske sekcije IEEE. Od 2021. godine član je programskog odbora međunarodne konferencije MIPRO-MEET. Prof. Poljak je dobitnik Državne nagrade za znanost (2017.), Godišnje nagrade Društva sveučilišnih nastavnika i



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- [https://www.researchgate.net/profile/Mirko\\_Poljak](https://www.researchgate.net/profile/Mirko_Poljak)
- <https://www.scopus.com/authid/detail.uri?authorId=24344736100>
- <https://publons.com/researcher/2532146/mirko-poljak/>

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First of all, I would like to thank my supervisor, Assoc. Prof. Mirko Poljak, for his invaluable guidance, support and patience during my doctoral journey. His insights and expertise were fundamental to the successful completion of this research, and I am incredibly fortunate to have had the opportunity to learn under his mentorship in the CONAN2D project (Computational design of nanotransistors based on novel 2D materials, Grant. No. UIP-2019-04-3493, sponsored by the Croatian Science Foundation).

Furthermore, I would like to thank two people who guided me long before I started my doctoral studies and significantly influenced my academic path: Prof. Petar Pervan and my primary school teacher for mathematics and physics Tanja Djaković.

I am deeply grateful to my colleagues and friends in the Department of Electronics, Microelectronics, Computer and Intelligent Systems (ZEMRIS), especially in room D352, where Lovro, Filip, Ivan, Borina, Azra and Dario have been a constant source of support and inspiration. I would also like to thank my students with whom I worked during my doctoral studies: Tin, Karolina, Ivan, Josip and Tomo.

I owe special thanks to my friends who have stood by me through every challenge and celebrated every small victory.

From the bottom of my heart, I owe the biggest thanks to my family whose unwavering support and belief in me has motivated me along the way. To my parents, Tomislav and Nedjeljka, my sister Marija, her husband Frane and my nieces Lucija and Karla. Also, to my godparents, godchildren, grandparents, aunts, uncles and cousins. Thank you all for your love and encouragement.

Finally, I thank God for giving me the strength to overcome all the challenges. Thank you, God, for this path you have led me on and for all the wonderful people you have placed in my life.

# Abstract

The continuous miniaturization of transistors has been driving the semiconductor industry for more than six decades. However, current silicon-based semiconductor technology is reaching its limits due to the strong quantum confinement and short-channel effects present in downscaled silicon devices. One of the potential solutions is to use new channel materials that could replace silicon, such as two-dimensional (2D) materials that have an atomic thickness and a dangling-bond-free surface and, therefore, have the potential for excellent device performance. The characteristics of 2D materials can be further engineered and optimized by patterning them into quasi-one-dimensional (1D) nanostructures called nanoribbons, which could potentially be employed as channel material in future state-of-the-art gate-all-around (GAA) field-effect transistors (FETs) that currently utilize ultrathin semiconductor nanosheets. However, the fabrication of 2D materials and nanoribbons is complex and an experimental demonstration is currently limited to only a few materials. Fabrication efforts are still in an early experimental stage, however, thousands of 2D materials have been theoretically predicted to exist with characteristics promising for applications in ultra-scaled FETs. Due to the large number of 2D materials and complex physics governing carrier transport at the nanoscale, potential candidates for future logic devices need to be investigated numerically using advanced theoretical formalisms and atomistic simulations.

This thesis presents an *ab initio* quantum transport study of nanoribbons of novel 2D materials using the density functional theory (DFT) to obtain the electronic band structure and maximally localized Wannier functions (MLWFs) to transform the DFT Hamiltonians into a spatially localized basis suitable for quantum transport simulation. The MLWF Hamiltonians are coupled with the non-equilibrium Green's function (NEGF) formalism-based quantum transport solver called QUDEN (from Quantum-Transport Device Engineering in Nanoelectronics), which was developed in-house in MATLAB. QUDEN is used to obtain the electronic and transport parameters of the analyzed nanostructures, while the top-of-the-barrier (TOB) ballistic FET model and under-the-barrier (UTB) tunneling leakage current model are

employed to calculate and analyze the device performance of nanoribbon-based FETs (NR FETs). The nanoribbons of novel 2D materials investigated in this thesis include: (i) armchair (AC) and zigzag (ZZ) nanoribbons of  $\text{MX}_2$ -enes ( $\text{MX}_2\text{NRs}$ ) with  $M = \{\text{Hf}, \text{Zr}\}$  and  $X = \{\text{S}, \text{Se}\}$ ; (ii) AC and ZZ nanoribbons of monolayer germanium-sulfide ( $\text{GeSNRs}$ ); (iii) nanoribbons of monolayer molybdenum-disulfide ( $\text{MoS}_2\text{NRs}$ ). For all the examined devices, nanoribbon widths ( $W$ ) range from  $\sim 7$  nm down to only  $\sim 0.8$  nm.

A detailed analysis is performed concerning quantum mechanical and scaling effects on the electronic and transport properties as well as on the performance of nanoribbon-based FETs using *ab initio* quantum transport calculations. The results presented in this thesis demonstrate a strong influence of the nanoribbon material, nanoribbon width, crystal phase and edge configuration on the characteristics of the investigated materials and, consequently, on the performance of nanoribbon-based devices. Although scaling down the nanoribbon width decreases the ON-state performance of most NR FETs, there are some surprising exceptions where the device performance is boosted by width downscaling. Such devices are AC- $\text{MX}_2\text{NR}$  PFETs, ZZ- $\text{MX}_2\text{NR}$  NFETs, and ZZ-GeSNR PFETs, where the maximum ON-state current is reported in devices with  $\sim 2$  nm-wide nanoribbon channels. This is surprising because usually the widest NR FETs exhibit the best figures-of-merit. All studied devices are compared against the requirements set by the IEEE International Roadmap for Devices and Systems (IRDS) for future semiconductor logic technology nodes. This work reports that all Hf-based ZZ- $\text{MX}_2\text{NRs}$ , ZZ-ZrS<sub>2</sub>NRs with  $W < 3$  nm, ZZ-ZrSe<sub>2</sub>NRs with  $W < 6$  nm, and AC-GeSNRs with  $W > 1.1$  nm fulfill the IEEE IRDS requirements on the ON-state performance for both N- and P-type FETs. In contrast, it is shown that MoS<sub>2</sub>NR FETs do not meet the goals defined in IEEE IRDS. While future work must address the impact of carrier scattering, this thesis clearly demonstrates that nanostructured Hf- and Zr-based  $\text{MX}_2$ -enes and GeS are promising channel materials for future ultra-scaled GAA FETs.

**Keywords:** two-dimensional (2D) materials, one-dimensional (1D), quasi-1D, nanoribbon, density functional theory (DFT), maximally localized Wannier functions (MLWFs), quantum transport, non-equilibrium Green's function (NEGF) formalism, ballistic transport, top-of-the-barrier (TOB) model

# Kvantnotransportna analiza tranzistora temeljenih na nanovrpcama novih 2D materijala

Kontinuirana minijaturizacija tranzistora već više od šest desetljeća pokreće industriju poluvodičke elektronike. Međutim, trenutna poluvodička tehnologija temeljena na siliciju doseže svoje granice zbog snažnih efekata kvantnog ograničenja i efekata kratkog kanala prisutnih u ultra-skaliranim silicijskim elektroničkim elementima. Jedno od mogućih rješenja je korištenje novih materijala za kanal tranzistora koji bi mogli zamijeniti silicij, kao što su dvodimenzijski (2D) materijali s atomskom debljinom i površinom bez nezasićenih kemijskih veza, stoga elementi temeljeni na 2D materijalima imaju potencijalno balističke performanse. Karakteristike 2D materijala mogu se dodatno projektirati i optimizirati oblikovanjem 2D materijala u kvazi-jednodimenzionalne (1D) nanostrukture zvane nanovrpcama (engl. *nanoribbon*, NR) koje bi se potencijalno mogle koristiti kao materijal kanala tranzistora u budućim tranzistorima s efektom polja (engl. *field effect transistor*, FET) s *gate all around* (GAA) strukturom koji koriste ultra-tanke poluvodičke nanolistove. Međutim, procesiranje 2D materijala i nanovrpci složeno je, a demonstracija je trenutno ograničena na nekoliko materijala te je još uvijek u ranoj eksperimentalnoj fazi, dok su tisuće potencijalnih 2D materijala teoretski predviđene, ali još nisu eksperimentalno potvrđene. Zbog velikog broja 2D materijala i kompleksne fizike transporta nosilaca na nanoskali, potencijalni kandidati za buduće logičke elemente moraju se numerički analizirati korištenjem naprednih teorijskih formalizama i atomističkih simulacija.

Cilj ove doktorske disertacije je razviti metodu temeljenu na *ab initio* kvantnotransportnom izračunu za analizu elektronskih i transportnih svojstava nanovrpci temeljenih na novim 2D materijalima te istražiti performanse FET-ova temeljenih na nanovrpcama 2D materijala. *Ab initio* istraživanje kvantnog transporta nanovrpci novih 2D materijala temelji se na teoriji funkcionala gustoće (engl. *density functional theory*, DFT) za dobivanje elektronske strukture i maksimalno lokaliziranih Wannierovih funkcija (engl. *maximally localized Wannier functions*, MLWF) za transformaciju DFT hamiltonijana u

prostorno lokaliziranu bazu prikladnu za simulaciju kvantnog transporta. MLWF hamiltonijani povezani su s našim internim *solverom* za kvantni transport temeljenim na formalizmu Greenove funkcije izvan ravnoteže (engl. *non-equilibrium Green's function*, NEGF) zvanim QUDEN (od engl. *Quantum-Transport Device Engineering in Nanoelectronics*) za dobivanje elektronskih i transportnih svojstava ovih nanostrukture, dok se balistički FET model vrha barijere (engl. *top-of-the-barrier*, TOB) i model ispod barijere (engl. *under-the-barrier*, UTB) koriste za izračun i analizu performansi FET-ova temeljenih na nanovrhcama.

Doktorska disertacija strukturirana je na sljedeći način: prvo poglavlju daje uvod u temu disertacije s naglaskom na motivaciju te ciljeve koji se žele postići; u drugom poglavlju dan je pregled novih 2D materijala otkrivenih nakon grafena i nanovrpci te njihov potencijal za primjene u budućim FET-ovima na nanoskali; u trećem poglavlju opisan je pregled teorije koja stoji iza *ab initio* simulacija kvantnog transporta korištenih u ovoj disertaciji za proučavanje FET-ova temeljenih na nanovrhcama; četvrto poglavlje razrađuje glavne doprinose rada i povezuje ih s publikacijama uvezenim u disertaciju; peto poglavlje sadrži sve publikacije u časopisima i konferencijama predane kao dio disertacije i daje sažetak autorova doprinosa publikacijama; a posljednje, šesto poglavlje daje sažetak rada te ga zaključuje najvažnijim nalazima.

Znanstveni doprinos ovog rada može se podijeliti u tri glavna dijela. Prvi dio bavi se *ab initio* metodom kvantnog transporta razvijenom za proučavanje FET-ova temeljenih na nanovrhcama, od atomističke definicije materijala do potpuno kvantnomehaničkih simulacija transporta. Drugi dio bavi se primjenom razvijene metode za proučavanje utjecaja kvantnomehaničkih efekata i skaliranja dimenzija na elektronska i transportna svojstva te na performanse FET-ova temeljenih na nanovrhcama novih 2D materijala. Posljednji dio daje optimalne konfiguracije novih FET-ova temeljenih na nanovrhcama i procjenjuje njihov potencijal za buduće logičke tranzistore. Sljedeći pododjeljci ukratko opisuju tri komponente znanstvenog doprinosa ove disertacije.

## **1. Samokonzistentna metoda za simulacije kvantnog transporta u nanoelektroničkim elementima temeljenim na nanovrhcama novih 2D materijala**

Kako bi se pravilno analizirali nanoelektronički elementi, proces simulacije mora uključiti svu relevantnu fiziku. Stoga je razvijena metoda koja koristi više naprednih teorijskih i računskih tehnika koje se mogu podijeliti u dva dijela. Prvi dio su atomistička konstrukcija proučavanih nanovrpci novih 2D materijala te dobivanje elektronske strukture i hamiltonijana materijala. Drugi dio predstavlja simulaciju kvantnog transporta tranzistora koja kao ulaz

koristi spomenuti hamiltonijan. Prvi dio postupka počinje definiranjem inicijalne strukture gdje se jedinična ćelija 2D materijala koristi za konstruiranje nanovrpce različitih širina i konfiguracija rubova. Potom se rubovi nanovrpce pasiviziraju, čime je nanovrpca konstruirana. Inicijalna struktura predstavlja ulaz u DFT izračune koji se koriste za dobivanje hamiltonijana i pripadajuće elektronske strukture, odnosno strukture energijskih vrpce. Nadalje, dobiveni DFT hamiltonijan transformira se u prostorno lokaliziranu bazu pomoću MLWF-a, što je jedan od glavnih ulaza u simulacije kvantnog transporta. Simulacije kvantnog transporta koriste NEGF u kombinaciji s TOB modelom za samokonzistentno izračunavanje strujno-naponskih karakteristika tranzistora. Oba modula, NEGF i TOB, prilagođena su i optimizirana za kvazi-1D materijale s DFT-MLWF hamiltonijanima kao ulazima. NEGF se koristi u ravnoteži za dobivanje transmisije i gustoće stanja, a te dvije veličine pak služe kao ulaz u TOB modul. TOB se koristi za modeliranje FET-a s jednom upravljačkom elektrodom s trima točkama potencijala ili energije, odnosno Fermijevom razinom uvoda i odvoda te TOB potencijalom koji predstavlja visinu potencijalne barijere između uvoda i odvoda u kanalu tranzistora. Iako je ovaj model jednostavan, za tranzistore s kanalima duljim od 15 nanometara pokazao je slične rezultate u usporedbi s naprednijom metodom koja rješava i višedimenzionalnu Poissonovu jednadžbu za elektrostatiku, kako je navedeno u [Pub 5]. Jedna od najvećih prednosti razvijenog i implementiranog DFT-MLWF-NEGF-TOB pristupa je kratko vrijeme izračuna, koje je nekoliko redova veličine kraće u usporedbi s punom 3D simulacijom u komercijalnom softveru. Kao rezultat, implementirana metoda može se koristiti za brzo pretraživanje različitih novih 2D materijala oblikovanih u nanovrpce s fizičkom ispravnošću transporta na nanoskali i visokom točnošću u usporedbi s naprednijim simulatorima.

## **2. Analiza kvantnomehaničkih efekata i efekata skaliranja na elektronska i transportna svojstva te na performanse tranzistora temeljenih na nanovrpceama novih 2D materijala korištenjem *ab initio* proračuna strukture energijskih vrpce**

Zbog svoje veličine, na karakteristike proučavanih nanovrpce snažno djeluje kvantno ograničenje koje mijenja svojstva materijala, što posljedično utječe na performanse tranzistora temeljenih na takvim nanostrukturama. Provedena je analiza kvantnomehaničkih efekata i efekata skaliranja na elektronska i transportna svojstva te na performanse tranzistora temeljenih na nanovrpceama tranzistora. Neke od fizičkih varijabli i opservabli proučenih u ovom radu uključuju strukturu energijskih vrpce, efektivnu masu elektrona i šupljina za paraboličku aproksimaciju strukture energijskih vrpce, širinu zabranjenog pojasa, gustoću stanja, transmisiju, injekcijsku brzinu elektrona i šupljina, ukupnu gustoću naboja u kanalu, efektivnu

transportnu masu elektrona i šupljina te energijsku gustoću struje. Sve te veličine zasebno se analiziraju za određeni materijal nanovrpce, širinu i tip nosioca, dok zajedno pružaju jasnu sliku o fizici utjecaja kvantnomehaničkih efekata i efekata skaliranja. U ovom radu proučavaju se nanovrpce novih 2D materijala, posebno *armchair* i *zig-zag*  $\text{MX}_2\text{NR}$  nanovrpce gdje je  $M = \{\text{Hf}, \text{Zr}\}$  i  $X = \{\text{S}, \text{Se}\}$  u [Pub 1], [Pub 2] i [Pub 5]; *armchair* i *zig-zag* GeSNR nanovrpce u [Pub 2] i [Pub 3]; i  $\text{MoS}_2\text{NR}$  nanovrpce u [Pub 6] i [Pub 7]. Nanovrpce su atomski tanke, sa širinama u rasponu od oko 0,8 do 7 nanometara. Analiza struje aktivnog stanja ( $I_{ON}$ ) pokazuje da se za većinu elemenata  $I_{ON}$  pogoršava sa smanjenjem širine nanovrpce, i to za 50 do 95 posto u odnosu na najšire promatrane nanovrpce. Međutim, neki od analiziranih FET-ova pokazuju neočekivano povećanje  $I_{ON}$  sa smanjenjem širine nanovrpce, s povećanjem do 70 posto za *zig-zag*  $\text{MX}_2\text{NR}$  NFET-ove, do 20 posto za *armchair*  $\text{MX}_2\text{NR}$  PFET-ove i do 6 puta za *zig-zag* GeSNR PFET-ove. Zanimljivo je da  $I_{ON}$  svih tranzistora čije se performanse povećavaju sa smanjenjem širine nanovrpce doseže maksimum kada se širina nanovrpce smanji na približno 2 nanometra.

### **3. Optimalne konfiguracije tranzistora temeljenih na nanovrpcama novih 2D materijala za buduće ekstremno skalirane poluvodičke elektroničke tehnologije**

Optimalne konfiguracije tranzistora temeljenih na nanovrpcama novih 2D materijala pronalaze se usporedbom sa zahtjevima koji su definirani u IEEE IRDS-u (engl. *International Roadmap for Devices and Systems*) za buduće tehnološke čvorove ili generacije. Glavni zahtjevi iz IRDS-a relevantni za ovu disertaciju su balistički  $I_{ON}$  i injekcijska brzina nosilaca ( $v_{inj}$ ) koji uključuju sve fizikalne karakteristike materijala i geometriju tranzistora. Sastav materijala, kristalna faza i konfiguracija ruba unaprijed određuju svojstva materijala, stoga se optimizacija performansi NR FET-ova može postići podešavanjem širine nanovrpce, dopiranjem uvoda i odvoda te odabirom materijala i debljine oksida upravljačke elektrode. Međutim, sva podesiva svojstva u simulacijskom okruženju moraju ostati unutar ostvarivih granica mogućih konfiguracija u budućim tranzistorima. Usporedba performansi analiziranih NR FET-ova sa zahtjevom IRDS-a za  $I_{ON}$  od  $\sim 2 \text{ mA}/\mu\text{m}$  za buduće tehnološke čvorove pokazuje da većina *zig-zag*  $\text{MX}_2\text{NR}$ -a zadovoljava zahtjev za NFET i PFET tranzistore. Od *zig-zag*  $\text{MX}_2\text{NR}$ -ova u [Pub 1], ZZ-HfS<sub>2</sub>NR i ZZ-HfSe<sub>2</sub>NR ispunjavaju zahtjeve IRDS-a za sve širine nanovrpce, dok je za *zig-zag*  $\text{MX}_2\text{NR}$ -ove temeljene na cirkoniju kriterij zadovoljen samo za ZZ-ZrS<sub>2</sub>NR sa širinom manjom od 3 nanometra i ZZ-ZrSe<sub>2</sub>NR sa širinom manjom od 6 nanometara. Nasuprot tome, samo performanse PFET-ova s kanalom *armchair*  $\text{MX}_2\text{NR}$ -a dovoljno su visoke da zadovolje zahtjev IRDS-a. Nadalje, AC-GeSNR sa širinom većom od



1,86 nanometara u [Pub 3] zadovoljavaju  $I_{ON}$  kriterij za oba NFET i PFET elemenata, dok  $\text{MoS}_2\text{NR}$  ne zadovoljava zahtjev IRDS-a za  $I_{ON}$  za bilo koju konfiguraciju, kao što je detaljno analizirano u [Pub 6]. Iako budući rad mora analizirati utjecaj raspršenja nosioca, ova disertacija jasno pokazuje da su nanostrukture GeS-a i  $\text{MX}_2$ -ena temeljenih na hafniju i cirkoniju materijali s potencijalom za kanale budućih ultra-skaliranih GAA FET-ova.

**Ključne riječi:** dvodimenzionalni (2D) materijali, jednodimenzionalno (1D), kvazi-1D, nanovrpca, teorija funkcionala gustoće (DFT), maksimalno lokalizirane Wannierove funkcije (MLWF), kvantni transport, formalizam Greenovih funkcija izvan ravnoteže (NEGF), balistički transport, model vrha barijere (TOB)

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# Chapter 1

## Introduction

### 1.1. Background and Motivation

The growth of the high-tech industry over the last 60 years has been driven by continued miniaturization of transistors. In addition to miniaturization, the performance of transistors has also been enhanced by the introduction of metal gates, high- $k$  gate dielectrics and strain of the crystal lattice within the channel. Current state-of-the-art devices in production are gate-all-around (GAA) field effect transistors (FETs) with bulk-silicon nanosheets or nanowires whose active region is no more than a few 10s of nanometers in all directions [1], [2], [3]. At such a scale, manufacturing is complex, and quantum mechanical effects are strong, with tunnelling deteriorating the digital switching performance [4]. Although GAA FETs provide high control over device electrostatics, maintaining good electrostatic properties and suppressing short channel effects has become hard at ultra-short gate lengths, i.e. for  $L_g \leq 20$  nm [5]. Two paths are being considered to extend the development in the semiconductor industry [6], [7]: “More Moore”, which focuses on the miniaturization of transistor size while suppressing short channel effects; and “More than Moore”, which focuses on functional diversification of electronic systems. One of the research areas on the “More Moore” path includes FETs based on 2D materials (2DMs). 2DMs consist of one or a few atomically thin layers in which in-layer atoms are connected by covalent bonds while adjacent layers are connected by the Van der Waals force. Due to their atomically thin thickness and dangling-bond-free surface, 2D materials offer exceptional electrostatic properties, i.e. nearly perfect control by the gate electrode [8], [9]. On the other hand, 2D materials have high source and drain (S/D) contact resistances in the range of  $\sim \text{k}\Omega\cdot\mu\text{m}$  which limits the performance of such devices [10], [11], [12]. Besides contact resistance, structural defects [13], surface optical phonon scattering [14], and interactions with

charged impurities [15] are further limiting factors for the use of 2D materials in electronics, but it is expected that these defects will become negligible with the improvement of the production methods. 2DMs have already been included in plans for future GAA technology nodes by leading semiconductor companies with first samples already been showcased in [16], as shown in Figure 1.1, and projected consumer products as early as the late 2020s in the form of the multi-bridge channel (MBC) FETs [17] and Ribbon FETs [16], [18], [19] which provides further motivation for studying these devices.

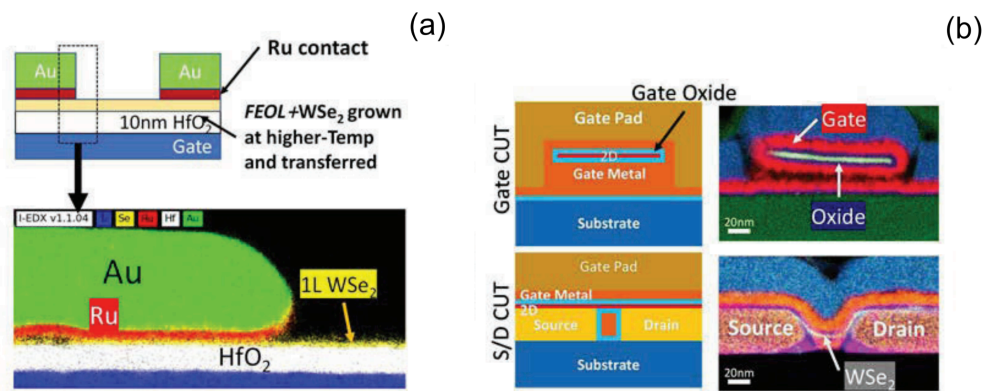


Figure 1.1 Schematic and TEM image with elemental mapping of (a) single gate FET and (b) GAA FET with WSe<sub>2</sub> channel [16].

More than 1800 2D materials have been shown to be theoretically stable [20], and several dozen of them are currently considered possible candidates for future FETs, with a focus on transition metal dichalcogenides (TMDs), e.g. MoS<sub>2</sub>, MoTe<sub>2</sub>, MoSe<sub>2</sub>, WS<sub>2</sub>, WSe<sub>2</sub>, SnS<sub>2</sub>, etc. [21], [22], [23], group-IV monolayers (graphene, silicene, germanene, stanene) [24], [25], [26], group-V monolayers (phosphorene, arsenene, antimonene, bismuthene) [27], [28], [29], and many others. These 2D materials can be configured into various nanostructures such as nanoribbons [30], [31], [32], nanosheets [1], and nanowires [33], with each of them providing excellent electrostatic control over the channel and thus reducing the short-channel effects. These nanostructures could be integrated in current GAA FETs, as shown in Figure 1.2a, where channel material are nanoribbons [34] with top view and side view shown in Figure 1.2b and Figure 1.2c, respectively. Moreover, the patterning of 2D materials into nanostructures provides an additional way of tuning the electronic, transport and device properties that include e.g.

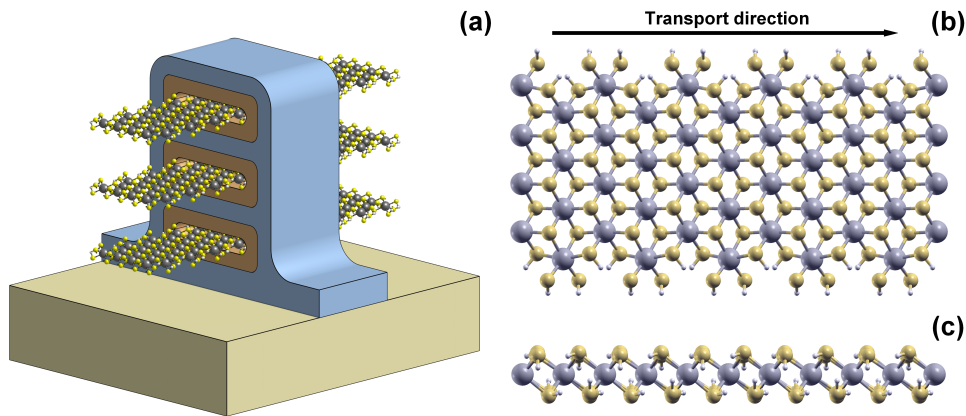


Figure 1.2 (a) Model of a MBC FET with nanoribbon channel. (b) Top view, and (c) side view of nanoribbon. [34]

bandgap, effective mass, injection velocity, etc., due to strong quantum mechanical effects in such extremely scaled material systems. Therefore, due to the trade-off between improved electrostatic control over the channel and altered electronic and transport properties, we need systematic physics-based modeling and simulation within an advanced physical framework for accurate design, analysis and optimization of nanoscale devices.

## 1.2. Objective of the Thesis

Although many 2D materials have been considered and studied both theoretically and numerically [1], most of them have not yet been produced experimentally. With such a large number of options available for future FETs, advanced modeling and simulation are crucial for the development of future transistors based on 2D materials [35]. Advanced physical and numerical models must incorporate the underlying electronic transport physics. The most advanced method to study low-dimensional materials is by obtaining the electronic structure using *ab initio* calculations performed using density functional theory (DFT) [36], where the accuracy depends on the exchange-correlation (XC) functional. The DFT calculations come with a downside of the high computational cost that consequently limits the calculations to structures consisting of at most dozens of atoms. In addition, the electronic structure is described with a Hamiltonian that, in the case of the DFT output, is a large and dense matrix that is not suitable for quantum transport simulations. To enable simulations of devices of realistic size, which can contain up to thousands of atoms [37], [38], while preserving the accuracy of DFT simulations, maximally localized Wannier functions (MLWFs) [39] are used

to transform DFT Hamiltonians into a localized basis, resulting in tight-binding (TB) like sparse matrices that are more suitable for quantum transport simulations in terms of memory consumption and simulation time.

Quantum transport simulations used in this work are based on the non-equilibrium Green's function (NEGF) formalism [40], [41], [42], [43]. The NEGF formalism is used to directly solve Schrödinger's equation with open boundary conditions (OBCs). The FET device can be simulated by employing a self-consistent NEGF-Poisson solver, or in the case of a ballistic device, a simplified top-of-the-barrier (TOB) model [37] can be used in combination with NEGF. In the TOB model, a FET is defined by three potential or energy points, i.e. S/D quasi-Fermi levels and the self-consistently calculated barrier height in the channel, which is called the TOB potential. The main inputs for TOB are the density of states (DOS) and transmission calculated in equilibrium using NEGF, the gate oxide material and thickness, and the S/D Fermi levels due to doping. The NEGF-based quantum transport simulations are well-established and widely used in the device research community, both in academia and industry. Many 2D materials have already been considered and related devices simulated [5], however, there is a limited number of studies dealing with devices based on nanoribbons of novel 2D materials discovered after graphene. Therefore, this research aims to fill the knowledge gap by investigating the electronic, transport and device characteristics of various 2D material nanostructures by employing the advanced *ab initio* quantum transport technique.

In summary, novel materials and device architectures are required for the further development and optimization of future electronic technologies. The 2D materials exhibit promising electronic and transport properties and patterning them into quasi-1D nanostructures called nanoribbons facilitates their potential usage in GAA FETs and, additionally, allows the tuning of material properties by quantum confinement, which can also enable the optimization of nanotransistor performance. The aim of this dissertation is to provide evidence about the suitability of quasi-1D materials such as armchair (AC) and zigzag (ZZ) nanoribbons of MX<sub>2</sub>-enes (MX<sub>2</sub>NRs) with M = {Hf, Zr} and X = {S, Se}, AC and ZZ nanoribbons of monolayer germanium-sulfide (GeSNRs), as well as nanoribbons of monolayer molybdenum-disulfide (MoS<sub>2</sub>NRs) for future GAA FETs using the quantum transport method in conjunction with *ab initio* calculations of the electronic bandstructure of such nanostructures.

The scientific contribution of this thesis is as follows:

1. Self-consistent method for simulations of quantum transport in nanoelectronic devices based on nanoribbons of novel 2D materials

2. Analysis of quantum-mechanical and scaling effects on the electronic and transport properties and on the performance of transistors based on nanoribbons of novel 2D materials using *ab initio* bandstructure calculations
3. Optimum configurations of transistors based on nanoribbons of novel 2D materials for future extremely scaled semiconductor electronic technologies

### **1.3. Structure of the Thesis**

The thesis is structured as follows:

- Chapter 2 provides a review of novel 2D materials and nanoribbons and their potential for future nano-scale FETs
- Chapter 3 reviews the theory behind the *ab initio* quantum transport simulations used in this thesis to study nanoribbon-based FETs for future logic devices
- Chapter 4 elaborates on the main contributions of the paper and links them to the publications
- Chapter 5 provides all journal and conference publications submitted as part of the thesis and summarizes the author's contribution to the publications
- Chapter 6 summarizes the work and concludes the thesis with the most important findings



# Chapter 2

## 2D Materials for Future Nanoelectronics

### 2.1. Overview of 2D Materials

The first theoretical concepts for 2D materials emerged as early as the 1940s [44], but scientists believed that 2DMs could not exist in nature due to their environmental instability. However, this opinion changed with the experimental discovery of graphene in 2004 [45], [46] by A. K. Geim and K. S. Novoselov, which led to the emergence of a new research field for 2D materials and attracted widespread research interest in the scientific community. 2DMs benefit from atomically thin thickness and dangling-bond-free surfaces [47], and consequently, some 2DMs can provide high carrier mobilities or near-ballistic transport properties that can be utilized for high-performance electron devices. However, the high contact resistance in devices with 2DM channels is one of the major problems and technology limiters.

Patterning into quasi-one-dimensional nanoribbons [30], [48], which could be used in GAA FETs [17], provides an additional way of tuning electronic, transport and device properties, such as bandgap, effective mass, injection velocity, etc. [49], [50], [51], [52]. Experimental work on NRs is limited to a few materials due to the high complexity of fabrication with the main challenge being the reliable control of crystal phase, edge structure, and dimensionality [53]. Nevertheless, the continuous progress in this field affirms fabrication potential and makes nanoribbons interesting structures for future nanodevices [54], [55], [56]. The search for potential 2DM candidates for future logic devices is a challenging task, as recently more than 1800 2DMs have been theoretically investigated using DFT [20] and of these materials about one hundred showed a bandgap suitable for future logic devices, i.e.  $E_g > 1$  eV. Given the large number of materials and the high experimental costs, it is necessary to evaluate which materials are worth considering as experimental candidates for future logic

devices. A recent theoretical study [5] compared all hundred 2D material candidates with appropriate bandgaps for future logic devices and found 13 best-performing FETs with 2DM channel that meet the International Roadmap for Devices and Systems (IRDS) [57] requirements for future technology nodes. Thirteen 2D materials whose FETs showed highest performance of all studied devices include monolayers of group-IV monoelemental materials ( $\alpha$  phase phosphorene or black phosphorus,  $\alpha$  and  $\beta$  arsenene, and  $\alpha$  phase antimonene), TMDs ( $\text{HfS}_2$  and  $\text{ZrS}_2$ ), monolayer Group-IV monochalcogenides ( $\text{GeS}$  and  $\text{GeSe}$ ), and other non-grouped 2DMs ( $\text{O}_6\text{Sb}_4$ ,  $\text{Si}_2\text{H}_2$ ,  $\text{Ti}_2\text{Br}_2\text{N}_2$ , and  $\text{Ti}_2\text{N}_2\text{Cl}_2$ ). In this work, the focus is on nanoribbons that are made by patterning 2DMs along one of the lattice directions, where the nanoribbons in each direction have a different structure and consequently different material properties. An example of patterning 2D materials into various structures is shown in Figure 2.1a for graphene, which can be patterned in the zigzag direction (as shown in Figure 2.1b) and armchair direction (as shown in Figure 2.1c), with the name of each nanoribbon based on the edge type. As result of patterning 2DMs into nanoribbons along various crystal directions, an even larger number of combinations are possible that need to be investigated and consequently finding the best candidates for future logic devices is a challenging task. Nevertheless, one can start by patterning 2DMs which showed potential such as the previously mentioned thirteen 2DMs whose FETs showed the highest performance of all 2DMs [5]. Most of these materials have not yet been patterned into nanoribbons and have not been studied theoretically or experimentally. These 13 materials include  $\text{GeS}$ ,  $\text{HfS}_2$  and  $\text{ZrS}_2$ ,

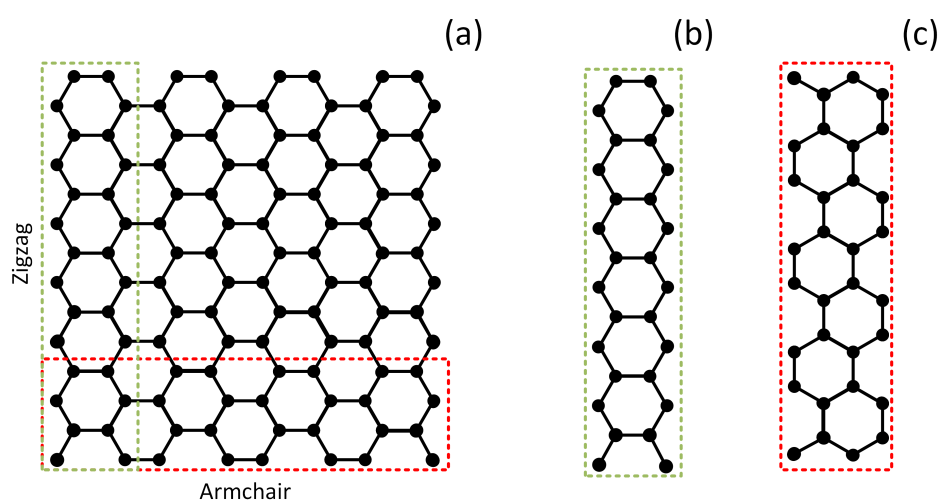


Figure 2.1 (a) Graphene monolayer cut into (b) armchair and (c) zigzag directions.

which are patterned into nanoribbons of various widths and edge types and analyzed in this thesis. In the following sections, we will examine the properties of the most promising 2DMs obtained from both theoretical and experimental studies.

## 2.2. Monoelemental 2D Materials

Research on monoelemental 2D materials (Xenes) is mostly focused on group-IV (graphene, silicene, and germanene) and group-V (phosphorene, arsenene, antimonene, and bismuthene) monolayer materials. Group-IV monolayer materials are represented with graphene which is the first synthesized and most studied 2D material, both theoretically and experimentally. Graphene has been studied in various configurations and integration levels from sample FET devices in [58], as shown in Figure 2.2 to wafer level integration compatible with complementary-metal-oxide-semiconductor (CMOS) technology in [59]. Graphene, silicene, and germanene have a hexagonal structure and zero bandgap due to the existence of Dirac-like dispersion at the  $K$ -point and as a direct consequence, effective mass tends to zero while group-IV mobility exceeds a few  $10,000\text{ s cm}^2\text{V}^{-1}\text{s}^{-1}$  [60]. Although group-IV materials exhibit high mobility, zero bandgap is a significant problem for usage as channel materials in digital logic devices as these devices would have poor switching capabilities, and consequently high-power consumption in the supposedly OFF-state [61]. Nevertheless, high-mobility materials are suitable for high-speed electronics where power consumption is not a problem. Finally,

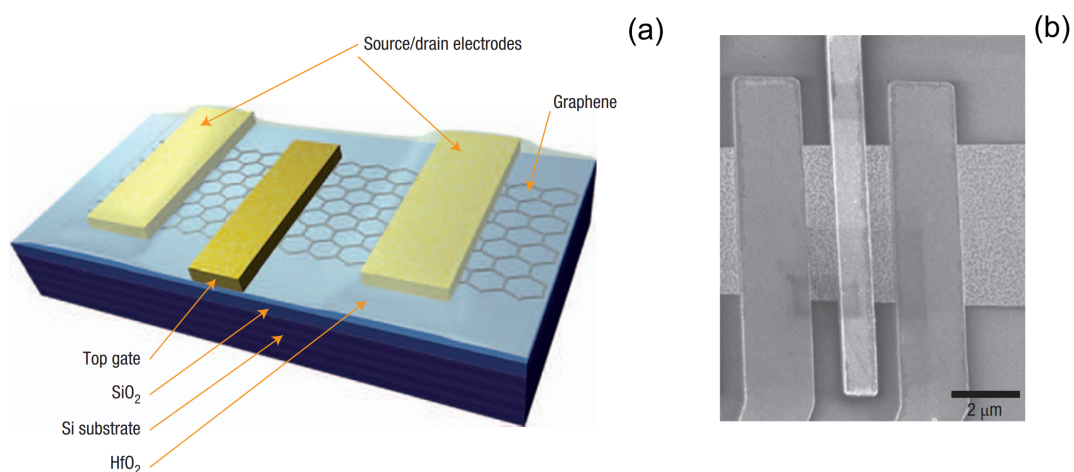


Figure 2.2 a) Schematic of top-gated graphene FET design and (b) SEM image of top-gated graphene FET. [58]

group-IV materials can be patterned into ultra-narrow nanoribbons with reported bandgap opening which potentially makes them suitable for logic devices [62].

Group-V monolayer semiconductors are fundamentally *p*-type semiconductors and found in two stable phases:  $\alpha$  phase group-V 2D materials form puckered monolayer formations which exhibit orthorhombic structure and  $\beta$  phase group-V 2D materials form wavy monolayer formations which exhibit rhombohedral structure. Group-V 2D materials have been studied theoretically [63] and experimentally [64], [65]. Theoretical DFT study [66] using HSE06 XC functional predicted electron and hole mobilities of black phosphorus to be  $\sim 1100 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  and  $\sim 700 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  along the armchair direction and zigzag direction  $\sim 80 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  and  $\sim 10,000 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$ . Arsenene is a semiconductor with a wide and direct bandgap of  $\sim 1.7 \text{ eV}$  for  $\alpha$ -phase and  $\sim 2.5 \text{ eV}$  for  $\beta$ -phase. Electron and hole mobilities of  $\beta$ -phase arsenene are  $\sim 635 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  and  $\sim 1700 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  [67]. Antimonene is an indirect semiconductor with a bandgap of  $\sim 1.2 \text{ eV}$  for  $\alpha$ -phase and  $\sim 2.3 \text{ eV}$  for  $\beta$ -phase. The  $\beta$ -phase antimonene electron and hole mobilities are  $\sim 630 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  and  $\sim 1737 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  [68]. Bismuthene is an indirect semiconductor with a bandgap of  $\sim 0.36 \text{ eV}$  for  $\alpha$ -phase and  $\sim 0.99 \text{ eV}$  for  $\beta$ -phase. The  $\beta$ -phase bismuthene exhibits electron mobility up to a few  $100 \text{ s cm}^2\text{V}^{-1}\text{s}^{-1}$  [69]. High electron mobility and suitable bandgaps in the  $1 \text{ eV}$  to  $2.5 \text{ eV}$  range of most group-V materials make them potential materials for future logic devices.

The  $\alpha$  phase phosphorene or black phosphorus,  $\alpha$  and  $\beta$  arsenene, and  $\beta$  phase antimonene are all one of the 13 best-performing 2D materials based on the ON-state current ( $I_{ON}$ ) benchmark from the recent theoretical study [5] where black phosphorus showed the highest performance of all 2D materials when both N- and P-FET  $I_{ON}$  performance is considered. On the topic of experimental work on group-IV FETs, single and few-layer *p*-type black phosphorus FET was reported in [64]. Black phosphorus was characterized only for the few-layer case, with  $I_{ON}/I_{OFF}$  ratio  $>10^4$ ,  $I_{ON} \sim 0.2 \text{ mA}/\mu\text{m}$  ( $\sim 20\times$  lower than the theorized ON-state current), and mobility up to  $286 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$ .

### 2.3. Transition Metal Dichalcogenides (MX<sub>2</sub>-enes)

TMDs are a family of 2D materials with a general formula being MX<sub>2</sub>, where M is a transition metal element (e.g., Mo, Hf, Zr, W, Ti, Sn) and X is a chalcogen element (e.g., S, Se, Te). Alongside monoelemental 2DMs represent one of the most studied materials. TMDs show promising electronic and transport properties such as low effective mass, high electron velocity,

and a wide range of bandgaps for future FETs. TMDs have a trigonal prismatic (2H) or octahedral (1T) structure [70], as shown in Figure 2.3, with mobility up to a few 100s  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  [21], [35]. Although the mobility is significantly lower compared to group-IV and group-V Xenes, the ON/OFF switching ratio of transistors based on TMDs exceeds  $10^6$  which is acceptable for next-generation FETs [5].

In this work, we focus on transition metal dichalcogenides  $\text{MX}_2$  ( $\text{M} = \{\text{Zr}, \text{Hf}\}$ ,  $\text{X} = \{\text{S}, \text{Se}\}$ ) as some of the most promising 2DMs [5], [71], [72]. Theoretical study on electronic properties of  $\text{MX}_2$ -enes in [72] reported bandgaps with HSE06 XC-functional as follows: 2.17 eV for  $\text{ZrS}_2$ , 1.07 eV for  $\text{ZrSe}_2$ , 2.4 eV for  $\text{HfS}_2$ , and 1.32 eV for  $\text{HfSe}_2$ , confirming all materials have appropriate bandgaps for logic devices. Furthermore, an *ab initio* study in [73] reported phonon limited mobility of mentioned  $\text{MX}_2$ -enes in range of a few thousand  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  with: 1247  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  for  $\text{ZrS}_2$ , 2316  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  for  $\text{ZrSe}_2$ , 1833  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  for  $\text{HfS}_2$ , and 3579  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  for  $\text{HfSe}_2$  which is 4-12 times higher compared to  $\text{MoS}_2$ , one of the most studied 2D materials, for which 340  $\text{cm}^2\text{V}^{-1}\text{s}^{-1}$  mobility was reported. The potential of 2D  $\text{MX}_2$  TMDs has been studied in depth [5], [73], [74] by advanced theoretical calculations and experimental work was reported in [75], [76]. Experimental work showed high compatibility of Hf and Zr-based TMDs to industry standard high- $k$  oxides ( $\text{HfO}_2$ ,  $\text{ZrO}_2$ )[77], [78], with FETs reported in [78] with schematic and scanning electron microscope (SEM) image shown in Figure 2.4. Although TMDs and TMD FETs are still experimental, research affirms production possibility. The  $\text{MX}_2$  nanoribbon ( $\text{MX}_2\text{NR}$ ) research is quite limited with electronic properties studied for  $\text{ZrS}_2\text{NRs}$  [79], and  $\text{HfSe}_2\text{NRs}$  [80]. As for  $\text{MX}_2\text{NR}$  FETs, only a single  $\text{ZrSe}_2\text{NR}$  FET was studied in [81] with the detailed study reported in our group and this thesis in [34], [82], which showed the potential of these devices for the future logic devices.

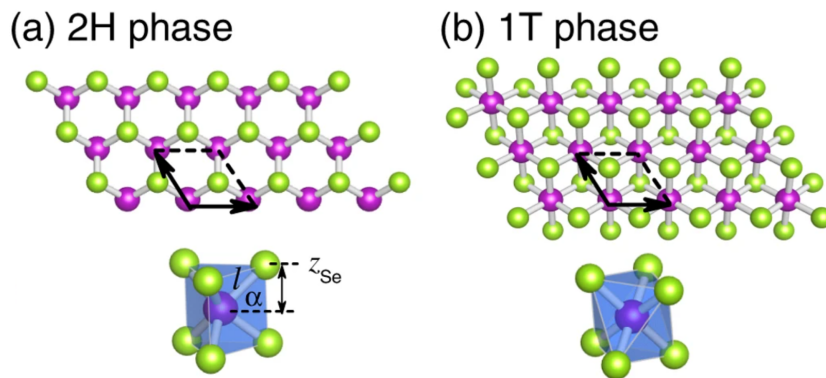


Figure 2.3. Illustration of the crystal structure of (a) 2H and (b) 1T phase of TMD 2D materials. [70]

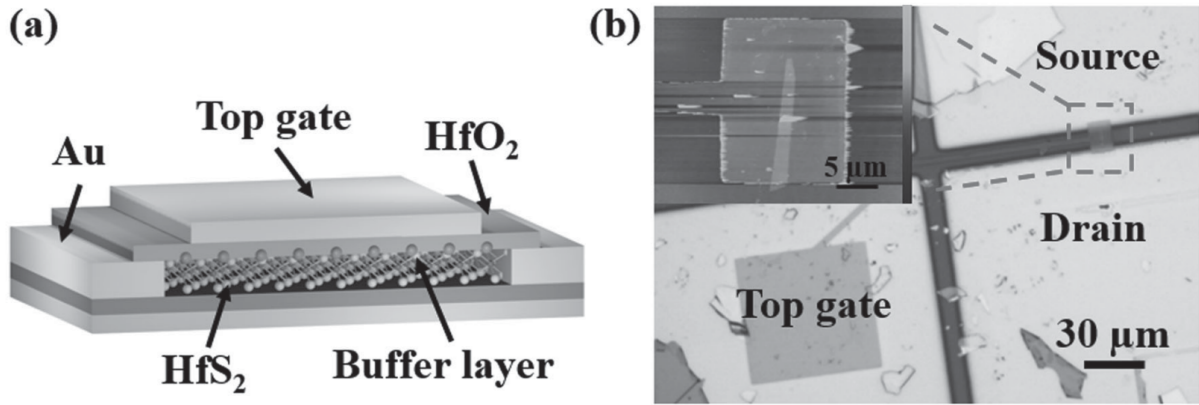


Figure 2.4. a) Schematic and (b) SEM image of top-gated HfS<sub>2</sub> FET. [78]

## 2.4. Monolayer Group-IV Monochalcogenides

Monolayer Group-IV monochalcogenides or MX-enes where ( $M \in \{\text{Ge, Si, Sn}\}$  and  $X \in \{\text{S, Se}\}$ ) are one of the most researched 2D materials. A recent theoretical study in [5] showed 2D GeS and GeSe as one of the best performing 2D materials based on ON-state current  $I_{ON}$  benchmark for logic devices with reported higher performance GeS compared to GeSe which served as initial motivation to study GeS.

The 2D germanium monosulfide (GeS) is a member of MX-enes with a phosphorene-like buckled orthorhombic lattice which indicates anisotropic transport. Theoretical study in [83] showed that 2D GeS exhibits an indirect bandgap of 2.34 eV, electron mobility higher than  $3000 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$  and a relatively low hole mobility of  $160 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$ . A recent quantum transport study of sub-10 nm monolayer GeS FETs [84] showed the great potential of GeS as a material for future short-channel transistors. Experimental work on GeS is limited to a few studies which affirm production potential [85], [86]. Before our group's study, reported in [87], [88], very little was known about quasi-1D GeS nanoribbon (GeSNR) devices, with the information being limited to electronic bandstructure [89]. Electronic properties of armchair and zigzag GeSNRs with bare and H-terminated edges were studied in [89]. This study demonstrated a high dependence of electronic properties on edge termination as ZZ GeSNRs with bare edges show metallic properties while all bare-edge AC-GeSNRs exhibit semiconducting behavior. On the other hand, termination by H atoms is presented as a good option to stabilize the AC- and ZZ-GeSNRs that exhibit semiconducting behavior.

## Chapter 3

# Computational Design of Nanotransistors using *Ab Initio* Quantum Transport Simulations

### 3.1. Overview of the Simulation Approach

Simulation of transistors and inclusion of all relevant physics is a demanding task, especially when working with materials that exhibit one or more dimensions at the nanometer scale such as 2D materials and nanoribbons where quantum confinement greatly affects the material properties. Employing the classical drift-diffusion (DD) model [90] of electron flow is insufficient to study these devices as it does not account for the quantum mechanical nature of materials and electron kinetics. There are semiclassical models based on the Boltzmann transport equation that incorporate some of the quantum mechanical effects that are good for micron-sized devices but do not fully capture the discrete nature of electron states and their wave functions. Therefore, the problem needs to be assessed at the quantum mechanical level, i.e. solving the Schrödinger equation of the studied system.

Solving the Schrödinger equation directly even for a simple system of  $N$  particles is a complex task as we have a  $3N$  dimensional problem that is impossible to solve even for a few particles. The problem is reduced from a many-particle problem to many single-particle problems, and each electron is treated as a point charge in the field of other electrons. Now we have a 3-dimensional problem that can be solved in real computational time. Schrödinger's equation describes a closed system and to include electron injection and extraction through the device one can employ non-equilibrium Green's function (NEGF) formalism to solve the Schrödinger equation for open-boundary conditions.

The main input of NEGF formalism is the Hamiltonian of the device. For macroscopic devices, an effective mass approximation can be used where the valence band (VB) and conduction band (CB) are approximated using the parabolic function. However, these models are not good enough to capture all physical effects at the nanoscale. At the time of writing of this thesis, two models are most popular to describe Hamiltonian of the system. The first model is based on *ab initio* density functional theory (DFT) which is a method that does not require outside parameters and is held as the theory with the highest accuracy to obtain the ground state of the nanostructure. DFT helps us to better understand the physics of such nanoscale devices and to predict device behavior. DFT is implemented in various programs such as Quantum Espresso [91], [92], VASP, SIESTA, ABINIT, QuantumATK, etc. However, depending on the parameters of the DFT, it has problems with evaluating the bandgap of the material which is one of the most important parameters when designing devices at the nanoscale. Furthermore, the computational burden is high and for more complex structures a supercomputer is needed. On the other hand, we have a tight-binding (TB) model which is an empirical model that is fitted on experimental results or *ab initio* DFT simulations results with the main advantage being much sparser matrices that enable simulation of a much higher number of atoms and consequently realistically sized devices even on desktop computers or workstations. To combine the accuracy of DFT and sparsity of the TB method, maximally localized Wannier functions can be used to transform DFT Hamiltonians into space-localized TB-like Hamiltonians. MLWF Hamiltonians are then used within NEGF formalism to describe the device at the atomic scale and obtain transport characteristics.

To simulate the transistor, the most advanced method is to solve NEGF in combination with the Poisson equation self-consistently. However, this method is computationally expensive and focusing on the ballistic performance of FET devices, the ballistic top-of-the-barrier model has proven to be good for assessing these devices. Although the TOB model only calculates thermionic current and tunneling current is neglected, studies have shown that for channels longer than 15 nm, it is good enough to study the performance. Under-the-barrier (UTB) model, an extension of the TOB model was developed to account for tunneling current. In this chapter simulation methods used to study nanoribbon-based FETs are explored where Hamiltonian is obtained using DFT and MLWF while the FET device is described and simulated using NEGF and TOB model.



## 3.2. Quantum Transport in Non-Equilibrium Green's Functions Formalism

Electrons, in quantum transport, are described fully quantum mechanically and injected into the simulation domain i.e. the studied nanostructure. After injection, some electrons are reflected while others are transmitted which causes current flow through the structure. Transport through the structure is only possible if the studied system is connected with the environment via electrical contacts, which is enabled by defining the open boundary conditions (OBCs). Therefore, non-equilibrium Green's functions (NEGF) formalism is employed to study the system by directly solving the Schrödinger equation with OBCs. The focus of this work is on coherent and ballistic transport in order to determine the upper intrinsic limits to device performance. Hence, it is assumed that the phase of the electron wavefunction is preserved through the device and all scattering processes that would cause decoherence, and momentum and energy relaxation, such as electron-phonon interactions, are neglected. The NEGF is implemented in QUDEN (from Quantum-Transport Device Engineering in Nanoelectronics), which is a legacy MATLAB code of the Computational Nanoelectronics Group at UNIZG-FER.

The NEGF is a known and widely used theory in physics that was based on the works of P. Martin and J. Schwinger in 1959 [93] and their PhD students L. P. Kadanoff and G. Baym in 1962 [94] and later formalized by L. P. Keldysh in 1965 [95]. More recently, the NEGF formalism has been adapted for applications in engineering fields by S. Datta [38], [40], Datta's simplified formulation yields the same results while being more accessible to electrical engineers [41] as there is no need to have previous knowledge in second quantization formalism and quantum statistical physics.

In order to introduce NEGF in a simplified manner, we focus on a nanosystem connected to external contacts or reservoirs which can be described as semi-infinite areas that are in local thermodynamic equilibrium with defined constant electrochemical potential or Fermi level. With details provided in [40], [41], the nanosystem with a single contact can be described using the non-homogenous differential equation

$$(E - H - \Sigma)\phi = S, \quad (1)$$

which resembles the Schrödinger equation with added terms that describe interaction with contacts. The  $\Sigma$  represents the contact self-energy which is a modification of the Hamiltonian to include interaction with connected contact. The  $S$  represents the source term or excitation of the nanosystem with electron waves from contact. This equation, unlike the Schrödinger

equation with closed boundary conditions, is not an eigenvalue problem and therefore one needs to solve the equation (1) using Green's functions. Green's function is a mathematical construct used to solve non-homogenous differential equations where for linear differential operator  $L(x)$  for which we can describe

$$L(x)\phi(x) = S(x). \quad (2)$$

Green's function  $G(x, x')$  is every solution of

$$L(x)G(x, x') = \delta(x - x'), \quad (3)$$

where  $\delta(x - x')$  is Dirac delta function. Solution of the eq. (2) using Green's function is then

$$\phi(x) = \int G(x, x')S(x')dx'. \quad (4)$$

Green function  $G(x, x')$  in equation (4) can be observed as a propagator that propagates the influence of excitation or perturbation  $S(x')$  from  $x'$  to  $x$  in which we evaluate the function  $\phi(x)$ . Also,  $G(x, x')$  can be treated as a correlation function because if  $x$  and  $x'$  exhibit high correlation then  $S(x')$  will have a strong impact on solution  $\phi(x)$  while the opposite is true for low correlation.

Applying Green's function to solve equation (1) of a nanosystem with a single contact we obtain two solutions. The first solution is the retarded Green's function

$$\mathbf{G}^R(E) = \left[ (E + i\eta)\mathbf{I} - \mathbf{H} - \mathbf{\Sigma} \right]^{-1}, \quad (5)$$

that represents the time-causal solution that ensures that response occurs after perturbation and therefore has a physical meaning. Obtaining a causal solution is assured by adding an infinitesimal positive imaginary constant  $i\eta$ , also called the convergence constant. Another solution is the advanced Green's function  $\mathbf{G}^A = (\mathbf{G}^R)^\dagger$  which is also useful in NEGF calculations.

In further text,  $\mathbf{G}^R$  and  $\mathbf{G}^A$  will be simplified and represented with  $\mathbf{G}$  and  $\mathbf{G}^\dagger$ , respectively. We start by defining two important parameters where the first is a spectral function

$$\mathbf{A}(E) = i \left[ \mathbf{G}(E) - \mathbf{G}^\dagger(E) \right], \quad (6)$$

which provides information about the available electronic states and their broadening due to interaction with contacts. Diagonal elements of spectral function represent the local density of states (LDOS) per spin

$$g_L(\mathbf{r}; E) = \frac{1}{2\pi} \text{Diag}[\mathbf{A}(E)], \quad (7)$$

while the trace of the density matrix

$$g(E) = \frac{1}{2\pi} \text{Trace}[\mathbf{A}(E)], \quad (8)$$

represents the density of states at the energy  $E$  per spin. The other important parameter is the broadening matrix

$$\Gamma(E) = i[\Sigma(E) - \Sigma(E)^\dagger] = -2\text{Im}[\Sigma(E)], \quad (9)$$

that can be derived from the imaginary part of the contact self-energy that introduces broadening due to the coupling of the studied nanosystem with a contact. Also, the broadening matrix can be interpreted as a generalized energy-dependent escape rate of particle from the structure to the contact. The connection between the spectral function and the broadening matrix is given by

$$\mathbf{A} = i(\mathbf{G} - \mathbf{G})^\dagger = \mathbf{G}\Gamma\mathbf{G}^\dagger = \mathbf{G}^\dagger\Gamma\mathbf{G}. \quad (10)$$

If we consider a system with two contacts, one can obtain the retarded Green's function of the system with two contacts as

$$\mathbf{G}(E) = [(E + i\eta)\mathbf{I} - \mathbf{H} - \Sigma_1 - \Sigma_2]^{-1}. \quad (11)$$

where  $\mathbf{H}$  is the device Hamiltonian while  $\Sigma_1$  and  $\Sigma_2$  are contact self-energy matrices. Electron density per energy and space can be marked as

$$\begin{aligned} \mathbf{G}^n(E) &= \mathbf{A}_1(E)f_1(E) + \mathbf{A}_2(E)f_2(E) \\ &= \mathbf{G}(E)[\Gamma_1(E)f_1(E) + \Gamma_2(E)f_2(E)]\mathbf{G}^\dagger(E), \end{aligned} \quad (12)$$

where  $f_1 = f_1(E) = f_0(E - E_{F1})$  and  $f_2 = f_2(E) = f_0(E - E_{F2})$ . Parameters  $E_{F1}$  and  $E_{F2}$  are Fermi levels of contacts 1 and 2 that are locally in thermodynamic equilibrium and act as reservoirs. Furthermore, the term in the middle of the equation can be marked as  $\Sigma^{in}$  and we can write

$$\mathbf{G}^n(E) = \mathbf{G}(E)\Sigma^{in}\mathbf{G}^\dagger(E). \quad (13)$$

This term is also called the electron correlation function or non-equilibrium Green's function from which the formalism got its name [38]. Non-equilibrium Green's function in Datta's formalism is similar to the original Keldysh quantum kinetic equation

$$\mathbf{G}^<(E) = \mathbf{G}(E)\mathbf{\Sigma}^<\mathbf{G}^\dagger(E), \quad (14)$$

where  $\mathbf{G}^<(E) = i\mathbf{G}^n(E)$  is the lesser Green's function, and  $\mathbf{\Sigma}^<(E) = i\mathbf{\Sigma}^{in}(E)$  is the lesser self-energy. Both the Keldysh quantum kinetic equation and retarded Green's function describe the system and its states while only the former incorporates information on the occupation of these states. The lesser Green's function  $\mathbf{G}^<$  gives information about the occupation of the state which refers to electrons while greater Green's function  $\mathbf{G}^>$  gives information about states that are not occupied and therefore refers to holes.

The current and its voltage dependence are determined by the electronic and transport properties of the simulated structure through the quantum transmission function calculated as

$$\bar{T}(E) = \text{Trace}[\Gamma_1 \mathbf{G} \Gamma_2 \mathbf{G}^\dagger], \quad (15)$$

where quantum transmission  $\bar{T}(E)$  depends on device Green's function and interaction with contacts through broadening matrices. This equation represents the connection between the Landauer-Büttiker and NEGF formalism and it is valid only for coherent quantum transport, i.e. ballistic transport without any scattering considered.

Finally, in order to improve and optimize the previous version of the legacy code QU DEN, the NEGF equations are solved using the recursive Green's function (RGF) method [96]. Within RGF, the simulation domain is broken down from a complex system into smaller and more manageable parts which are called "slices". One of the computationally most demanding tasks in NEGF is a calculation of retarded Green's function as it includes the inversion of a huge matrix. However, the RGF approach can be employed for the calculation of transmission and density of states where only the diagonal, and edge sub-matrices are needed of the full retarded Green's function matrix, as it provides a significant speedup of simulation for large systems. The RGF computation time is  $O(N^3/N_{SL}^2)$  while the direct method computation time is  $O(N^3)$ , where  $N$  is the size of the device matrix and  $N_{SL}$  is the number of slices. This implies that the maximum number of slices would drive the simulation time to a minimum,  $N_{SL}$  needs to be appropriate to include all relevant interaction information.

### 3.2.1. Surface Green's Function

Contacts, as previously defined, are semi-infinite leads of the same material as the channel and consequently, the Green's function of these contacts would be infinite in size. However, interaction with the full contacts can be reduced to surface-only interactions, and therefore we

employ the surface Green's function approach, which considers only the overlap between the surface or edge elements of contacts and the main structure. Surface Green's function is a submatrix of a full contact Green's function, and using this simplification the contact self-energies of the left and right contacts can be written as

$$\Sigma_L = \mathbf{T}_1 \mathbf{g}_L \mathbf{T}_1, \quad \Sigma_R = \mathbf{T}_2 \mathbf{g}_R \mathbf{T}_2^\dagger, \quad (16)$$

where  $\mathbf{g}_L$  and  $\mathbf{g}_R$  are the surface Green's functions of the left and right contact, respectively while  $\mathbf{T}$  matrices describe the orbital or site overlap Hamiltonians between the contact and the nanosystem.

For ideal contacts, i.e. reservoirs made of the same material as the channel, the surface Green's function can be calculated using numerically efficient recursive methods. In these methods, layer by layer of contact regions is added until the difference between two sequential calculated surface Green's functions is smaller than a predetermined tolerance, which means that calculated contact Green's function is indistinguishable from Green's function of an infinite contact. This iterative method is simple [38] but very slow with  $O(2^n)$  computational time where  $n$  is the number of layers. The most widely used method is the Sancho Rubio method [97] which has  $O(n)$  computing time because the approach is constructed in such a manner that the number of included layers doubles in each iteration. The Sancho Rubio algorithm for the left contact is as follows

1. Initialize  $\mathbf{A}_{old} = \mathbf{T}$ ,  $\mathbf{B}_{old} = \mathbf{T}^\dagger$ ,  $\mathbf{C}_{old} = \mathbf{D}_{old} = \mathbf{H}_0$ ,  $\delta(\text{tolerance})$ ,  $\epsilon > \delta$
2. Iterate until  $\epsilon > \delta$ 
  - a. Calculate  $\mathbf{X} = [(E+i\eta)\mathbf{I} - \mathbf{C}_{old}]^{-1}$
  - b. Calculate  $\mathbf{A}_{new} = \mathbf{A}_{old} \mathbf{X} \mathbf{A}_{old}$ ,  $\mathbf{A}_{new} = \mathbf{A}_{old} \mathbf{X} \mathbf{A}_{old}$   
 $\mathbf{C}_{new} = \mathbf{C}_{old} + \mathbf{A}_{old} \mathbf{X} \mathbf{B}_{old} + \mathbf{B}_{old} \mathbf{X} \mathbf{A}_{old}$   
 $\mathbf{D}_{new} = \mathbf{D}_{old} + \mathbf{B}_{old} \mathbf{X} \mathbf{A}_{old}$
  - c.  $\epsilon_1 = \max[\text{abs}(\mathbf{A}_{new} - \mathbf{A}_{old})]$ ,  $\epsilon_2 = \max[\text{abs}(\mathbf{B}_{new} - \mathbf{B}_{old})]$ ,  
 $\epsilon_3 = \max[\text{abs}(\mathbf{C}_{new} - \mathbf{C}_{old})]$ ,  $\epsilon_4 = \max[\text{abs}(\mathbf{D}_{new} - \mathbf{D}_{old})]$ ,  
 $\epsilon = \max(\epsilon_1, \epsilon_2, \epsilon_3, \epsilon_4)$
  - d.  $\mathbf{A}_{old} = \mathbf{A}_{new}$ ,  $\mathbf{B}_{old} = \mathbf{B}_{new}$ ,  $\mathbf{C}_{old} = \mathbf{C}_{new}$ ,  $\mathbf{D}_{old} = \mathbf{D}_{new}$ ,
3.  $\mathbf{g}_L = [(E+i\eta)\mathbf{I} - \mathbf{D}_{new}]^{-1}$
4.  $\Sigma_L = \mathbf{T}_1^\dagger \mathbf{g}_L \mathbf{T}_1$

while for the right contact, we need to make two small changes in 2.b)  $\mathbf{D}_{new} = \mathbf{D}_{old} + \mathbf{A}_{old}\mathbf{X}\mathbf{B}_{old}$  and in 4.  $\Sigma_R = \mathbf{T}\mathbf{g}_R\mathbf{T}^\dagger$ . In the Sancho Rubio algorithm,  $\mathbf{H}_0$  is the diagonal element of the total Hamiltonian block matrix while  $\mathbf{T}$  and  $\mathbf{T}^\dagger$  matrices describe the overlap to the right and left neighboring blocks, respectively. These matrices are illustrated later in the text in Section 3.5.1 and Figure 3.2 where  $\mathbf{T}$  and  $\mathbf{T}^\dagger$  matrices are denoted as  $\mathbf{H}_1$  and  $\mathbf{H}_{-1}$ , respectively. In the following sections, total Hamiltonian ( $\mathbf{H}$ ) of the device will be obtained using DFT and transformed into a localized basis using MLWFs to obtain Hamiltonians suitable for NEGF and consequently Sancho Rubio calculations.

### 3.3. Top-of-the-Barrier and Under-the-Barrier Models

To explore the ballistic device performance of FETs with nanoribbon channel we employ the top-of-the-barrier (TOB) model to account for thermionic current and its extension, the under-the-barrier (UTB) model to include the direct source-to-drain tunneling current [98]. Within the TOB model, FET is modeled with three points: the potential at the top-of-the-barrier ( $U_{SC}$ ), and source and drain Fermi levels. Furthermore, the transmission and DOS are obtained from NEGF and then used as inputs to the TOB module of QUDEN. The thermionic current flows only above the  $U_{SC}$ , as shown in Figure 3.1, and no tunneling is included at this point.

Mobile charge density at the top of the barrier is defined by local density at the top of the barrier, source and drain quasi-Fermi levels, and self-consistent TOB potential ( $U_{scf}$ ). In equilibrium, i.e. for  $V_G = V_D = V_S = 0$ , charge density at the top of the barrier is described with

$$N_0 = \int_{-\infty}^{\infty} D(E) [f(E - E_F)] dE, \quad (17)$$

where  $D(E)$  is the local density of states at the top of the barrier, while  $f(E - E_F)$  is the Fermi-Dirac function.

The consequences of applying a bias to the gate and drain, while the source is grounded ( $V_S = 0$  V), are: first,  $U_{scf}$  becomes self-consistent potential at the top of the barrier and, second, states at the top of the barrier are populated by two reservoirs with their respective Fermi levels. The positive velocity states in the channel are filled by the source with  $N_+$  states, while the negative velocity states are filled by the drain with  $N_-$ , as follows

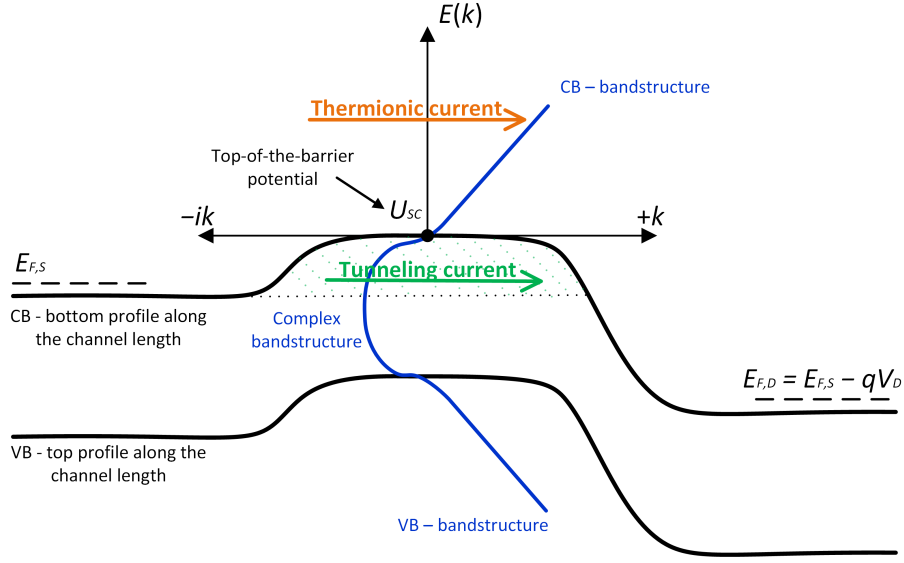


Figure 3.1. Profile of the conduction and valence bands along the channel length with quasi-Fermi levels in the source and drain. The  $E-k$  diagram is superimposed to illustrate the inclusion of real and complex parts of the bandstructure in FET simulations.[98]

$$\begin{aligned}
 N_+ &= \frac{1}{2} \int_{-\infty}^{\infty} D(E) f_1(E) dE, \\
 N_- &= \frac{1}{2} \int_{-\infty}^{\infty} D(E) f_2(E) dE,
 \end{aligned} \tag{18}$$

where

$$\begin{aligned}
 f_1(E) &\equiv f(E - E_{FS} - U_{scf}), \\
 f_2(E) &\equiv f(E - E_{FD} - U_{scf}),
 \end{aligned} \tag{19}$$

where the source Fermi level equals  $E_{FS} = E_F$  and the drain Fermi level is defined as  $E_{FD} = E_{FS} - qV_{DS}$ .

To obtain the electron density at the top of the barrier, i.e.  $N = N_+ + N_-$ , we need to know the self-consistent potential  $U_{scf}$ . To find the  $U_{scf}$ , the 2D Poisson equation needs to be solved for a system that is represented by the three capacitors with the bias-induced charge  $\Delta N = (N_+ + N_-) - N_0$  at the common terminal. The solution is obtained by superposition where first we ignore the mobile charge and calculate Laplace potential at the top-of-the-barrier as a result of terminal biases

$$U_L = -q(\alpha_G V_G + \alpha_D V_D + \alpha_S V_S). \tag{20}$$

In this equation,  $\alpha_G$ ,  $\alpha_D$ , and  $\alpha_S$  represent the influence of the gate, drain and source electrodes through capacitors  $C_G$ ,  $C_D$ , and  $C_S$  in Laplace solution, and are given as

$$\alpha_G = \frac{C_G}{C_\Sigma} \quad \alpha_D = \frac{C_D}{C_\Sigma} \quad \alpha_S = \frac{C_S}{C_\Sigma}. \quad (21)$$

where  $C_\Sigma$  is the parallel combination of the three capacitors. The second part of the solution is mobile charge  $\Delta N$  due to introduced biases. If we ground all three electrodes and calculate potential due to mobile charge at the top-of-the-barrier we get

$$U_P = \frac{q^2}{C_\Sigma} \Delta N. \quad (22)$$

Positive drain and gate voltages lower the top of the barrier potential energy, described with  $U_L$  but due to mobile charge it rises and the  $U_{scf}$  equation is given as follows

$$U_{scf} = U_P + U_L = -q(\alpha_G V_G + \alpha_D V_D + \alpha_S V_S) + \frac{q^2}{C_\Sigma} \Delta N. \quad (23)$$

To maintain charge neutrality in the highly doped source and drain regions under high bias conditions, a floating source potential is needed for ballistic transport. An increase in gate voltage decreases the number of electrons reflected from the barrier and consequently source potential needs to decrease to restore space-charge neutrality in the source. With the source potential decreasing the  $U_{scf}$  potential at the top of the barrier also decreases and this floating source effect results in an increased carrier density at the top of the barrier. In the analytical model, when the barrier height is high enough, i.e. when  $U_{scf} \gg E_{CS}$ , where  $E_{CS}$  is the conduction band minimum in the source, both positive and negative velocity states are filled according to the source Fermi level

$$N_{SD} = \int_{-\infty}^{\infty} D(E - E_{CS}) f(E - E_{FS}) dE, \quad (24)$$

where  $N_{SD}$  is source doping density. When high bias is applied at the gate and drain, three distinct groups of carriers are present:

- 1) carriers with energy lower than the barrier reflected by the barrier
- 2) carriers with energy higher than the barrier with positive velocity
- 3) carriers with energy higher than the barrier with negative velocity



Groups 1) and 2) are in equilibrium with  $E_{FS}$  while group 3) is in equilibrium with  $E_{FD}$ . The sum of these populations is lower than the equilibrium carrier density and to maintain charge neutrality ( $E_{FS} - E_{CS}$ ) needs to be increased. Although  $E_{FS}$  is fixed while  $E_{CS}$  floats down, in this model we keep  $E_{CS}$  fixed while  $E_{FS}$  floats up to  $E'_{FS}$ . From this, we can obtain charge neutrality condition in the source

$$N_{SD} = \int_{-\infty}^{U_{scf}} D(E - E_{CS}) f(E - E'_{FS}) dE + \int_{U_{scf}}^{\infty} D(E - E_{CS}) \left[ f(E - E'_{FS}) + f(E - E'_{FS} + qV_{DS}) \right] dE. \quad (25)$$

After the self-consistent  $U_{scf}$  is obtained, the thermionic current can be calculated. The difference between contact quasi-Fermi energies gives rise to the flow of current which can be calculated using Landauer's equation [38]

$$I_{th} = \frac{q}{h} \int_{-\infty}^{\infty} \bar{T}(E) [f_1(E) - f_2(E)] dE, \quad (26)$$

where  $I_{th}$  is calculated per spin.  $f_1$  and  $f_2$  represent source and drain Fermi functions defined in eq. (19) while  $T(E)$  is obtained from NEGF via eq. (15).

Finally, to account for tunneling effects, the under-the-barrier model [99] is used as an extension of the TOB model. Complex bandstructure inside the bandgap is obtained, belonging to the evanescent electron waves in contrast to travelling electron waves in the real part of the bandstructure. This dispersion characteristic is approximated by a parabolic function that represents an energy-dependent electron decay rate or tunneling attenuation ( $\kappa(E)$ ). The Wentzel-Kramers-Brillouin (WKB) approximation is used to obtain the transmission probability below the conduction band minimum (CBM) or above the valence band maximum (VBM) according to

$$T_{WKB}(E) = \sum_n \exp[-2l(E)\kappa(E)], \quad (27)$$

where  $n$  is a number of complex subbands of the channel material, i.e. respective nanoribbon, and  $l(E)$  is the energy-dependent tunneling barrier length. The tunneling current is calculated per spin using the Landauer formula

$$I_{tun} = \frac{q}{h} \int_{E_{F,S}}^{U_{sc}} T_{WKB}(E) [f(E - E_{F,S}) - f(E - E_{F,D})] dE, \quad (28)$$

where  $f(E - E_{F,S})$  and  $f(E - E_{F,D})$  are source and drain Fermi-Dirac functions, respectively, and  $E_{F,D} = E_{F,S} - qV_D$ . Tunneling occurs only between the source CBM/VBM and top-of-the-barrier potential ( $U_{SC}$ ), and mainly around  $E_{F,S}$ , as illustrated in Figure 3.1.

Finally, we can find the total current as

$$I_{tot} = I_{th} + I_{tun}, \quad (29)$$

which means a combination of TOB and UTB serves as an important tool to study FET devices with sub-15 nm gate lengths where the tunneling current cannot be ignored.

### 3.4. Density Functional Theory

To study nanoscale devices such as FETs with nanoribbons where strong quantum effects cannot be ignored, we need to use methods that are based on laws on physics and therefore do not use any fitting parameters from experimental data as for small and complex structures such as nanoribbons experimental data is limited to a few distinct materials and configurations due to complexity and price of fabrication. These methods are called first-principles or *ab initio* methods. Early *ab initio* methods that tried to solve the Schrödinger equation such as the Hartree method [100] in 1928 which introduced mean-field approximation and Hartree-Fock (HF) method [101] in 1930 that added Slater determinant for the wave function to the Hartree method relied on the  $3N$  dimensional wave equation of  $N$  electrons which made these models practical only for few dozens of atoms. The breakthrough in *ab initio* methods came when Hohenberg and Kohn in 1964 [102] presented two theorems:

1. The energy ground state is a unique electron density functional:  $E = E [(\rho(\mathbf{r}))]$
2. Electron density which minimizes total functional is the real ground state of electron density  $E [(\rho(\mathbf{r}))] > E_0 [(\rho_0(\mathbf{r}))]$ .

This was the ground for Kohn and Sham [103] in 1965 to develop a method called Density Functional Theory (DFT). DFT is an *ab initio* computational quantum mechanical method used to study the electronic structure of materials by solving the Schrödinger equation of the investigated system. The central quantity in DFT is electron density  $\rho(\mathbf{r})$  which is defined as the sum of a set of squares of noninteracting orbitals

$$\rho(\mathbf{r}) = \sum_i |\phi_i(\mathbf{r})|^2 = 2 \sum_i^{occ} |\phi_i(\mathbf{r})|^2 \quad (30)$$

where  $\phi_i$  are Kohn-Sham (KS) orbitals in a noninteracting reference system. Note that non-interacting KS orbitals replace interacting wavefunctions  $\psi$ . Electron density is introduced to reduce the problem from  $3N$  to 3 dimensions without losing information. Many-particle problem is reduced to many single-particle problems and each electron is treated as a point charge in the field of other electrons.

The introduction of the Kohn-Sham approach that utilizes electron density made it possible to study realistic-sized nano devices with hundreds or even thousands of atoms. In short, starting from the initial atomic structure, DFT iteratively optimizes structure geometry and electronic density until forces on atoms are low enough for it to be considered close enough to the true ground state. In the geometry part of the optimization process, atoms are moved to minimize forces on atoms. On the other hand, electronic density optimization relies on structure geometry and solving the Schrödinger equation.

### 3.4.1. The Kohn-Sham Approach

Firstly, the focus is on a stationary problem of  $n$  particles by neglecting the time-dependence of the Schrödinger equation whose full Hamiltonian of  $n$  particle system is

$$\hat{H} = -\frac{1}{2} \sum_{i=1}^n \nabla_i^2 - \sum_{I=1}^N \sum_{j=1}^n \frac{Z_I}{|\mathbf{R}_I - \mathbf{r}_j|} + \frac{1}{2} \sum_{i \neq j}^n \frac{1}{|\mathbf{r}_i - \mathbf{r}_j|} \quad (31)$$

where  $\mathbf{r}_i$  and  $\mathbf{r}_j$  are coordinates of electrons,  $\mathbf{R}_I$  are coordinates of nuclei while  $Z_I$  are charges of the nuclei. The equation consists of three terms where the first term represents kinetic energy, the second term external potential and the last term is Hartree potential. Hartree potential includes coupled interactions between all  $n$  particles that are difficult to formulate in this form and therefore Kohn and Sham derived a different approach.

Kohn and Sham assumed that each electron is noninteracting. They decomposed the energy of  $n$ -electron into energy of  $n$  one-electrons and mapped the  $n$ -electron interacting system to a noninteracting system of  $n$  one-electrons. Total energy  $E$  in DFT framework can be written as

$$E = E_{kin}^{non} + E_{ext} + E_H + E_{xc} \quad (32)$$

where  $E_{kin}^{non}$  is non-interacting kinetic energy,  $E_{ext}$  is external potential,  $E_H$  is Hartree energy while the last term is exchange-correlation (XC) energy  $E_{xc}$ . Energy functionals in terms of

electron density dependence can be written as follows. The kinetic energy  $E_{kin}^{non}$  in Kohn-Sham equations is defined as

$$E_{kin}^{non} = -\frac{1}{2} \sum_{i=1}^n \phi_i^*(\mathbf{r}) \nabla^2 \phi_i(\mathbf{r}) d\mathbf{r}. \quad (33)$$

where  $\phi_i$  are Kohn-Sham (KS) orbitals in a noninteracting system. Although orbitals are involved in this equation, it is directly correlated to electron density via eq. (30). External energy  $E_{ext}$  represents the interaction between electrons and other nuclei and can be written as

$$E_{ext} = \int \phi_i^*(\mathbf{r}) U_{ext} \phi_i(\mathbf{r}) d\mathbf{r} = \int U_{ext} \rho(\mathbf{r}) d\mathbf{r}, \quad (34)$$

where  $U_{ext}(\mathbf{r})$  is external potential. Hartree energy  $E_H$  accounts for Coulomb interaction between electrons with

$$E_H = \frac{1}{2} \iint \frac{\rho(\mathbf{r}) \rho(\mathbf{r}')}{|\mathbf{r} - \mathbf{r}'|} d\mathbf{r} d\mathbf{r}', \quad (35)$$

where  $\frac{1}{2}$  is for double counting. Furthermore, this term includes unphysical self-interactions of electrons which is corrected in the exchange energy term.

The final term is the exchange-correlation (XC) energy  $E_{xc}$  whose one-to-one relationship to the ground state was formalized by Hohenberg and Kohn [102]. It consists of all quantum effects and can be divided into exchange energy  $E_x$  and correlation energy  $E_c$  components where  $E_{xc} = E_x + E_c$ .  $E_x$  accounts for the exchange between electrons with the same spin while  $E_c$  is the correlation between electrons with a different spin. Exchange energy can be calculated as the sum of four-center integrals as a function of the single particle KS orbitals

$$E_x = -\frac{1}{2} \sum_{ij}^n \iint \frac{\phi_i^*(\mathbf{r}) \phi_j^*(\mathbf{r}) \phi_i(\mathbf{r}) \phi_j(\mathbf{r})}{|\mathbf{r} - \mathbf{r}'|} d\mathbf{r} d\mathbf{r}', \quad (36)$$

which leads to less overlapping between electron densities and consequently a reduction in repulsion energy between electrons. Although  $E_x$  can be calculated directly with equation (36) for small systems, due to bad scaling and high computational cost  $E_x$  is always approximated. On the other hand, we have an electronic correlation where electrons with different spins can occupy the same orbital but also repel each other as they exhibit the same negative charges. Like  $E_x$ , the  $E_c$  results in less overlapping of electron densities. This is the unknown  $n$ -electron effect that is subject to an approximation. Correlation energy is an important component,

especially for low electron densities where exchange energy becomes much lower due to lower interaction.

For small systems, XC-functional can be calculated but for bigger systems must be approximated. The simplest XC-functional approximations are local density approximation (LDA) and generalized gradient approximation (GGA). LDA depends only on the value of electronic density at each point in space. Electronic density is assumed to be the same everywhere and because of this assumption LDA often underestimates the bandgap of most semiconductors. The GGA improves upon LDA by taking into account the non-homogeneity of electron density. Perdew, Burke, and Ernzerhof (PBE) [104] parametrized GGA functional which significantly improved accuracy in the single electron orbital energies. Additionally, using hybrid functionals can reproduce band gaps even more accurately. The exchange part of the hybrid functional is calculated as a linear combination of GGA and Hartree-Fock exchange parts. The most widely used hybrid functional is HSE06, parametrized by Heyd, Scuseria, and Ernzerhof [105]. While highly precise, especially for band gap prediction, due to the high computational cost of using the Hartree-Fock method [106], the scalability of hybrid functional simulations is limited.

### 3.4.2. DFT for Crystalline Solids

The simulation path can be further narrowed because DFT is used to simulate crystalline solids. Crystal structures have a periodic arrangement of atoms and consequently periodic potential. Electrons in a periodic potential are Bloch waves which can be expanded into Fourier series and treated as a sum of plane waves with different kinetic energies. Ideally, an infinite range of plane waves with different energies should be considered but due to computational limits, a cutoff energy must be introduced. Cutoff energy must be high enough for total energy to converge within the given maximum error. The cutoff energy minimum for each atom type and used XC-functional is usually tested and attached to the materials pseudopotential (PP) file. Material properties are mainly characterized by valence electrons, so PPs are used to replace the core electrons and true potential with smoother and more effective potential. There are three common types of PPs: norm-conserving PPs, ultrasoft PPs and projector-augmented wave (PAW) PPs. Crystal structures are simulated by choosing a primitive unit cell that repeats infinitely in all directions. It is convenient to use reciprocal space because wavevectors  $\mathbf{k}$  are defined in reciprocal space. In reciprocal space, the primitive unit cell is called the 1st Brillouin

Zone (BZ). Numerical calculations must be evaluated only in the 1<sup>st</sup> BZ and an appropriate number of  $k$ -points have to be chosen to sample the 1st BZ.

### 3.5. Maximally Localized Wannier Functions

Plane waves are used by most DFT codes to expand the single-particle Kohn-Sham wavefunctions. Plane-wave basis set enables highly accurate calculation of electronic states, but they are localized in energy and represented with dense Hamiltonians. For atomistic quantum transport simulations space-localized basis set is desired. In the 1930s, Wannier [107] introduced a localized real-space representation of Bloch states. Building upon Wannier work, Marzari and Vanderbilt [39] developed a computational method with maximal localization criteria for the construction of Wannier functions (WFs) which are represented with maximally sparse block-tridiagonal matrix. The usage of sparse matrices enables the simulation of nanodevices with realistic physical sizes. Marzari and Vanderbilt method was implemented in the Wannier90 [108] program and is compatible with a variety of DFT programs. In the following sections, only the basic concepts of maximally localized Wannier functions (MLWFs) will be outlined, while extensive theory can be found in [109].

Electronic structure calculations are often performed with periodic boundary conditions to study perfect crystal structures, while it is also common to study non-periodic systems such as liquids, molecules, interfaces, and defects. Bloch orbitals ( $\psi_{nk}$ ) can be chosen as common eigenstates of Hamiltonian in periodic systems

$$\psi_{nk}(\mathbf{r}) = u_{nk}(\mathbf{r})e^{i\mathbf{k}\cdot\mathbf{r}}, \quad (37)$$

where  $u_{nk}(\mathbf{r})$  includes the periodicity of the Hamiltonian, while  $e^{i\mathbf{k}\cdot\mathbf{r}}$  can be interpreted as an envelope function where Bloch functions for different wave-vectors ( $\mathbf{k}$ ) exhibit different envelopes. Bloch functions are delocalized and spread over the entire space, but it is possible to construct a localized wave packet from Bloch functions by superimposing the contributions of different  $\mathbf{k}$  values. If we switch to bra-ket notation where  $\mathbf{R}n$  refers to the Wannier function  $w_{n\mathbf{R}}$  in cell  $\mathbf{R}$  and band  $n$ , we can construct WFs according to

$$|\mathbf{R}n\rangle = \frac{V}{(2\pi)^3} \int_{BZ} d\mathbf{k} e^{-i\mathbf{k}\cdot\mathbf{R}} \sum_{m=1}^J U_{mn}^{(\mathbf{k})} |\psi_{nk}\rangle, \quad (38)$$

where  $V$  is the volume of real-space primitive unit-cell,  $e^{-i\mathbf{k}\cdot\mathbf{R}}$  is phase factor while  $U_{mn}^{(\mathbf{k})}$  is unitary rotation matrix that can be interpreted as a gauge transformation used to deal with any discontinuity and ensure smoothness of  $\psi_{n\mathbf{k}}$  in  $\mathbf{k}$ -space. This equation has a form of Fourier transform, and we can obtain its inverse transform as

$$|\psi_{n\mathbf{k}}\rangle = \sum_{\mathbf{R}} e^{-i\mathbf{k}\cdot\mathbf{R}} |\mathbf{R}n\rangle. \quad (39)$$

With transformations in equations (38) and (39) there is a unitary transformation between Bloch and Wannier basis and consequently, both sets of states provide an equally valid descriptions of the band subspace, although WFs are not Hamiltonian eigenstates. Manifest of the equivalence can be seen by expressing the band projection operator ( $P$ ) in both Bloch and Wannier representations

$$P = \frac{V}{(2\pi)^3} \int_{BZ} |\psi_{n\mathbf{k}}\rangle \langle \psi_{n\mathbf{k}}| = \sum_{\mathbf{R}} |\mathbf{R}n\rangle \langle \mathbf{R}n|. \quad (40)$$

The WFs are not unique due to the gauge freedom in the definition of the Bloch functions and replacements

$$\begin{aligned} |\tilde{\psi}_{n\mathbf{k}}\rangle &= e^{i\varphi_n(\mathbf{k})} |\psi_{n\mathbf{k}}\rangle, \\ |\tilde{u}_{n\mathbf{k}}\rangle &= e^{i\varphi_n(\mathbf{k})} |u_{n\mathbf{k}}\rangle, \end{aligned} \quad (41)$$

in both Bloch and Wannier space can be made without changing the description of the system.  $\varphi_n(\mathbf{k})$  is any real function periodic in reciprocal space.

For NEGF simulations, maximum localization is desired as it results in maximally sparse matrices. Real-space Wannier functions localization is linked to the smoothness of Bloch functions in reciprocal space and one of the simplest and most effective ways to construct a smooth gauge can be found by starting from the already localized trial orbitals ( $g_n(\mathbf{r})$ ), usually atomic orbitals that represent a rough guess for home unit cell WFs, and projecting them on the Bloch manifold

$$|\phi_{n\mathbf{k}}\rangle = \sum_{m=1}^J |\psi_{m\mathbf{k}}\rangle \langle \psi_{m\mathbf{k}} | g_n \rangle, \quad (42)$$

where the inner product matrix can be written as  $(A_{\mathbf{k}})_{mn} = \langle \psi_{m\mathbf{k}} | g_n \rangle$  and used to compute the overlap matrix  $(S_{\mathbf{k}})_{mn} = \langle \phi_{m\mathbf{k}} | \phi_{n\mathbf{k}} \rangle_V = (A_{\mathbf{k}}^\dagger A_{\mathbf{k}})_{mn}$ . The result of projecting localized trial orbitals

are usually functions that are smooth in the  $\mathbf{k}$  space, but not orthonormal and applying the Löwdin orthonormalization technique [110] can fix this problem

$$|\tilde{\psi}_{n\mathbf{k}}\rangle = \sum_{m=1}^J |\phi_{m\mathbf{k}}\rangle (S_{\mathbf{k}}^{-1/2})_{mn}, \quad (43)$$

at the expense of the resulting states not giving exactly the same description of the original system. The WFs obtained by the trial orbital projection are not maximally localized and well-defined localization criteria are needed to find MLWFs. Marzari and Vanderbilt [39] introduced localization criteria within the unit cell which reduces the problem of finding a gauge transformation ( $U_{mn}^{(\mathbf{k})}$ ) that minimizes the localization functional

$$\Omega = \sum_n \left[ \langle \mathbf{0}n | r^2 | \mathbf{0}n \rangle - \langle \mathbf{0}n | \mathbf{r} | \mathbf{0}n \rangle^2 \right] = \sum_n \left[ \langle r^2 \rangle_n - \bar{\mathbf{r}}_n^2 \right], \quad (44)$$

described by the quadratic spread sum of the WFs in the home unit cell. Localization functional can be split into a sum of gauge invariant and gauge dependent parts where gauge-invariant part

$$\Omega_I = \sum_n \left[ \langle \mathbf{0}n | r^2 | \mathbf{0}n \rangle - \sum_{\mathbf{R}m} \left| \langle \mathbf{R}m | \mathbf{r} | \mathbf{0}n \rangle \right|^2 \right], \quad (45)$$

cannot be minimized, while the gauge-dependent part

$$\tilde{\Omega} = \sum_n \sum_{\mathbf{R}m \neq \mathbf{0}n} \left| \langle \mathbf{R}m | \mathbf{r} | \mathbf{0}n \rangle \right|^2, \quad (46)$$

is further minimized.

The energy window around the bandgap of each material must be defined in which the accompanying bands are kept in MLWF Hamiltonian. The MLWF Hamiltonian is diagonalized along the same  $k$ -point path as in the DFT calculation. The MLWFs are localized around atom centers and the MLWF Hamiltonian matrix elements decay quickly when the distance between the WFs increases. To exclude interactions between the WFs that may be considered redundant, cutoff distance can be set.



### 3.5.1. Nanoribbon Hamiltonian Construction

After obtaining the MLFW Hamiltonian it must be converted into a suitable form that enables it to be upscaled to create a device Hamiltonian. There are two main outputs of the MLFW procedure: The first is  $\mathbf{H}_{mn}(\mathbf{R})$  matrix where  $\mathbf{R}$  are lattice vectors  $(i,j,k) \in \mathbb{Z}$  which represents the interaction of the  $m$ -th WF in the home unit cell  $\mathbf{R}(0,0,0)$  to  $n$ -th WF in the unit cell with indices  $\mathbf{R}(i,j,k)$  as shown in Figure 3.2a. The second output are Wannier centers and their spreads within home unit cell. One can match the WFs to their centers in the home unit cell and construct various structures on an atom basis. This procedure is described in detail in [111] for various cases such as ideal scaling by repeating the unit cell  $N$  times where  $N$  is an integer, fractional scaling where one can determine the Hamiltonian of the device of desired length per atom basis and not per unit cell basis which is the case for ideal scaling. Nonetheless, in this work, the problem is simplified as we consider only the ideal upscaling procedure. Furthermore, the focus is on nanoribbons that are structures confined in a single direction and simulated in whole in DFT which means we can consider  $\mathbf{R}$  in only a single direction, and we can write  $\mathbf{H}_i \equiv \mathbf{H}_{mn}(\mathbf{R}(i,0,0))$  where  $(i) \in \mathbb{Z}$ .

With the inclusion of only the nearest-neighbor cell interactions and neglecting all other interactions between the WFs, we only need to consider  $\mathbf{H}_i$  with lattice vectors  $\mathbf{R}(i,0,0)$  where  $i = \{-1,0,1\}$ . The nanoribbon structure is shown in Figure 3.2b with depicted interactions within home unit cell  $\mathbf{H}_0$ , interactions of the home unit cell with first left unit cell with  $\mathbf{H}_{-1}$  and first right unit cell with  $\mathbf{H}_1$  where  $\mathbf{H}_{-1} = \mathbf{H}_1^T$ . Now that all needed interactions are described, we can use them to generate a super-cell Hamiltonian of a nanoribbon with the desired length in terms

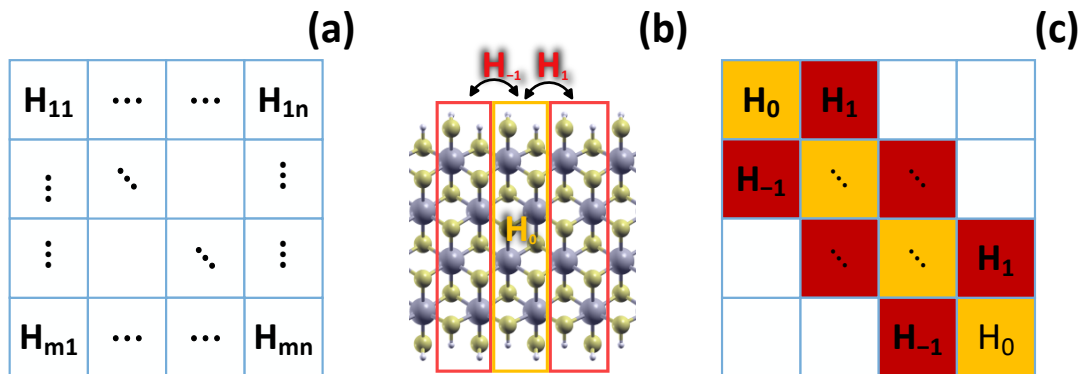


Figure 3.2. (a) Hamiltonian matrix  $\mathbf{H}_{mn}$ , (b) nanoribbon structure with depicted interactions, (c) device Hamiltonian

of a number of unit cells  $N_L$ . The total Hamiltonian  $\mathbf{H}$  of the nanoribbon is constructed as a block-tridiagonal matrix with  $\mathbf{H}_0$  on the main diagonal repeated by the number of cells along the nanoribbon length  $N_L$ ,  $\mathbf{H}_1$  on the first super-diagonal, and  $\mathbf{H}_{-1}^\dagger$  on the first sub-diagonal as shown in Figure 3.2c. If we designate the number of WFs in the unit-cell with  $N_{WANN}$ , the total Hamiltonian size is then  $(N_{WANN} \times N_L) \times (N_{WANN} \times N_L)$ . The obtained  $\mathbf{H}$  is then used as an input for NEGF equations, i.e. for the retarded Green's function of the device.

### 3.6. Summary of the Workflow

A summary of the workflow used for device simulations reported in this thesis is shown in Figure 3.3. The simulation process starts with a definition of the initial nanoribbon structure that is imported into the DFT to optimize the geometry and find the electronic structure of the material, i.e. DFT Hamiltonian. Energy-localized DFT Hamiltonian, represented with a dense matrix, is transformed into a localized basis using MLWFs to obtain sparse MLWF Hamiltonians appropriate for quantum transport simulations. MLWF Hamiltonians are upscaled to create a total channel Hamiltonian ( $\mathbf{H}$ ) which serves as the main input into the NEGF code. Within NEGF, the device is described using the total channel Hamiltonian and  $\Sigma$  matrices that represent the interaction of the device with two contacts. The NEGF is used to obtain the transport properties, including transmission and DOS in equilibrium, which serve as an input for the TOB module of the overall code. The TOB and its extension UTB are used to calculate the current-voltage characteristics of single-gate ballistic NR FETs and obtain all relevant device figures of merit.

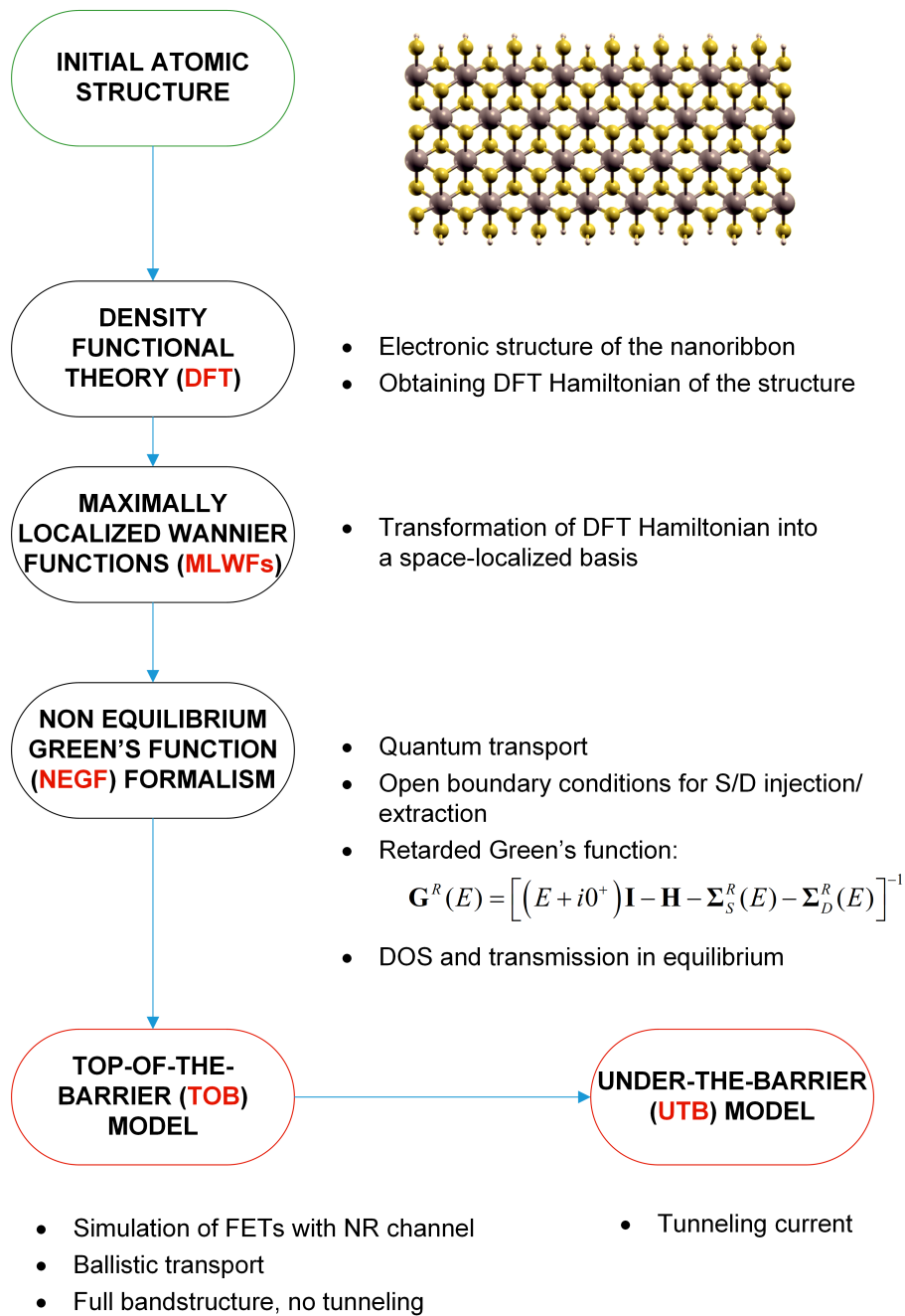


Figure 3.3 Summary of the simulation workflow used in this thesis to study nanoribbon FETs

# Chapter 4

## Main Scientific Contribution of the Thesis

The aim of this thesis is to develop a method based on the *ab initio* quantum transport calculations to analyze the electronic and transport properties of nanoribbons based on novel 2D materials, and to investigate the performance of respective 2D material NR FETs. The scientific contribution of this thesis can be divided into three main parts. The first part deals with the *ab initio* quantum transport method developed to study nanoribbon-based FETs from an atomistic material definition to fully quantum-mechanical quantum transport simulations. The second part deals with the application of the developed method to study the impact of quantum mechanical effects and dimensional scaling on the electronic and transport properties, as well as on the performance of NR FETs made of novel 2D materials. The last part provides optimum configurations of novel NR FETs and assesses their feasibility for future logic devices. The following subsections briefly discuss the main scientific contribution of the research for each of the three main parts.

### **1. Self-consistent method for simulations of quantum transport in nanoelectronic devices based on nanoribbons of novel 2D materials**

To properly study nanoscale electronic devices, the simulation process needs to incorporate all relevant physics. Therefore, a method is developed that utilizes multiple advanced theoretical and computational techniques which can be divided into two parts. The first part is the atomistic construction of the studied nanoribbons of novel 2D materials and obtaining the electronic structure and the Hamiltonian of the material. The second part represents the quantum transport simulation of transistors which uses as input the mentioned Hamiltonian. The first part starts with an initial structure where the unit cell of a 2D material is used to construct nanoribbons of various widths and edge configurations. Once edges are passivated, nanoribbon is constructed

and DFT is used to obtain electronic structure. Furthermore, the obtained DFT Hamiltonian is transformed into a space-localized basis using MLWFs which is one of the main inputs to quantum transport simulations. The quantum transport simulations utilize NEGF in combination with the TOB model for self-consistent calculation of the device current-voltage characteristics. Both NEGF and TOB modules of the total code are adapted and optimized for quasi-1D materials with DFT-MLWF Hamiltonian inputs. The NEGF is used in equilibrium to obtain transmission and density of states which serve as an input to TOB. TOB is used to model a single gate FET with three points, S/D Fermi level and TOB potential which represents barrier height between S/D. Although this model is simple, for devices with channels longer than 15 nm it showed similar results compared to the more advanced method that employs a full numerical solution of the Poisson equation, as reported in [Pub 5]. One of the biggest strengths of the developed and implemented DFT-MLWF-NEGF-TOB approach is the low computational time which is several orders of magnitude lower compared to full 3D Poisson simulation in commercial software. As a result, the implemented method can be used for fast screening of a variety of novel 2D materials patterned into nanoribbons with physical correctness and high accuracy.

## **2. Analysis of quantum-mechanical and scaling effects on the electronic and transport properties and on the performance of transistors based on nanoribbons of novel 2D materials using *ab initio* bandstructure calculations**

Due to their size, the studied nanoribbons experience strong quantum confinement effects that modify the material properties, which consequently affects the performance of transistors based on such nanostructures. The analysis of quantum-mechanical and scaling effects is carried out by exploring the relationship between the ON-state current ( $I_{ON}$ ) of NR FETs and the electronic, transport and device properties. Some of the physical variables and observables studied in this work include the bandstructure, bandstructure effective mass, bandgap, DOS, transmission, injection velocity, charge density, band decomposed charge density, effective transport mass, and current density. All these properties are extracted and analyzed separately for given nanoribbon material, width, and carrier type, while collectively they give a clear picture of the underlying physics behind the impact of quantum-mechanical and scaling effects.

Nanoribbons of novel 2D materials are studied in this thesis, specifically armchair and zigzag  $\text{MX}_2\text{NRs}$  where  $M = \{\text{Hf}, \text{Zr}\}$  and  $X = \{\text{S}, \text{Se}\}$  in [Pub 1], [Pub 2], [Pub 5] armchair and zigzag  $\text{GeSNRs}$  in [Pub 2], [Pub 3], and  $\text{MoS}_2\text{NRs}$  [Pub 6], [Pub 7], are atomically thin with

widths in range from  $\sim 0.8$  nm to  $\sim 7$  nm. Analysis of the ON-state current shows that  $I_{ON}$  for most devices deteriorates with downscaling to the value of 50% to 95% of the widest observed nanoribbon compared to the narrowest. However, FETs of some materials show an unexpected increase with downscaling with up to 70% increase for zigzag  $\text{MX}_2\text{NR}$  NFETs, up to 20% increase for armchair  $\text{MX}_2\text{NR}$  PFETs and up to  $6\times$  for zigzag GeSNR PFETs. Interestingly, the  $I_{ON}$  of all devices whose performance increases with downscaling reaches a maximum when nanoribbon width is downscaled to  $\sim 2$  nm.

### **3. Optimum configurations of transistors based on nanoribbons of novel 2D materials for future extremely scaled semiconductor electronic technologies**

Optimum configurations of transistors based on nanoribbons of novel 2D materials are found by comparison with IEEE IRDS requirements for future technological nodes. The main IRDS requirements for this thesis are the ballistic  $I_{ON}$  and injection velocity ( $v_{inj}$ ) which incorporate all the material and device physics. Material properties such as material composition, crystal phase, and edge configuration are predetermined by the material itself and therefore the optimization of NR FET performance can be achieved by tweaking nanoribbon width, S/D doping, gate oxide material, and gate oxide thickness. Nevertheless, all tunable properties in the simulation environment must stay within the physical limits of possible configurations in future devices.

Comparing the performance of studied NR FETs to IRDS  $I_{ON}$  requirement of  $\sim 2$  mA/ $\mu\text{m}$  for future technology nodes shows that most zigzag  $\text{MX}_2\text{NRs}$  satisfy the requirement for both NFET and PFET devices. Out of zigzag  $\text{MX}_2\text{NRs}$  reported in [Pub 1], ZZ-HfS<sub>2</sub>NRs and ZZ-HfSe<sub>2</sub>NRs fulfill the requirement for all NR widths while for Zr-based zigzag  $\text{MX}_2\text{NRs}$  the criteria is met only for ZZ-ZrS<sub>2</sub>NRs with  $W < 3$  nm and ZZ-ZrSe<sub>2</sub>NRs with  $W < 6$  nm. In contrast, only the performance of PFETs with armchair  $\text{MX}_2\text{NR}$  channel is high enough to meet the IRDS requirement. Furthermore, AC-GeSNRs with  $W \geq 1.86$  nm in [Pub 3] meet the  $I_{ON}$  criteria for both NFET and PFET devices while MoS<sub>2</sub>NRs do not meet the IRDS  $I_{ON}$  requirement for any configuration, as reported in [Pub 6]. Comparison with IRDS affirms the potential of some Zr- and Hf-based  $\text{MX}_2\text{NR}$  and GeSNR configurations for future FETs.

# Chapter 5

## Overview of Scientific Work of the Thesis

### 5.1. List of Scientific Qualification Articles

The main scientific publications, both journals and conferences, related to the dissertation and included in this thesis are listed here.

#### 5.1.1. Journal Publications

- [Pub 1]** M. Matić and M. Poljak, “Intrinsic performance limits of extremely scaled field-effect transistors based on  $\text{MX}_2$  ( $M = \{\text{Zr}, \text{Hf}\}$ ,  $X = \{\text{S}, \text{Se}\}$ ) nanoribbons,” *Journal of Applied Physics*, vol. 136, no. 8, p. 084307, Aug. 2024, doi: 10.1063/5.0224088.
- [Pub 2]** M. Matić and M. Poljak, “Ballistic Performance of Quasi-One-Dimensional Hafnium Disulfide Field-Effect Transistors,” *Electronics*, vol. 13, no. 6, p. 1048, 2024. doi: 10.3390/electronics13061048
- [Pub 3]** M. Matić and M. Poljak, “Electronic, transport and ballistic device properties of quasi-one-dimensional GeS,” *Journal of Computational Electronics*, vol. 22, no. 5, pp. 1350–1362, 2023. doi: 10.1007/s10825-023-02054-4
- [Pub 4]** M. Matić and M. Poljak, “Ab initio quantum transport simulations of monolayer GeS nanoribbons,” *Solid-State Electronics*, vol. 197, p. 108460, 2022. doi: 10.1016/j.sse.2022.108460

### 5.1.2. Conference Publications

- [Pub 5] M. Matic and M. Poljak, “Validity of the Ballistic Top-of-the-Barrier Model for FETs Based on 2D Material Nanoribbons,” in *2024 47th MIPRO ICT and Electronics Convention (MIPRO)*, 2024, pp. 1596–1601. doi: 10.1109/MIPRO60963.2024.10569245
- [Pub 6] M. Matic and M. Poljak, “Transport Properties and Device Performance of Quasi-One-Dimensional MoS<sub>2</sub> FETs,” in *2023 46th MIPRO ICT and Electronics Convention (MIPRO)*, 2023, pp. 168–172. doi: 10.23919/MIPRO57284.2023.10159951
- [Pub 7] I. Prevaric, M. Matic, and M. Poljak, “Tunneling Attenuation and Leakage Current in MoS<sub>2</sub> Nanoribbon MOSFETs,” in *2023 46th MIPRO ICT and Electronics Convention (MIPRO)*, 2023, pp. 163–167. doi: 10.23919/MIPRO57284.2023.10159745

## 5.2. Author’s Contribution to the Publications

The results presented in this thesis are based on the research conducted in the period from 2020 to 2024 at the University of Zagreb Faculty of Electrical Engineering and Computing, Department of Electronics, Microelectronics, Computer and Intelligent Systems (Unska 3, 10000 Zagreb, Croatia) under the supervision of Associate Professor Mirko Poljak, PhD. The work is the result of research within the project “Computational design of nanotransistors based on novel 2D materials” under the acronym CONAN2D, funded by the Croatian Science Foundation under grant number UIP-2019-04-3493.

The thesis includes four journal publications and three conference publications written in collaboration with coauthors of the published papers, while the author is listed as the first author on all journal papers and most conference papers. The author’s contribution to each paper consists of the manuscript conceptualization, methodology, software implementation, data curation, and formal analysis and interpretation of the results. The author’s contribution in the specific publication is detailed in the following list:



- [Pub 1]** In the journal paper “*Intrinsic Performance Limits of Extremely Scaled Field-Effect Transistors Based on  $MX_2$  ( $M = \{Zr, Hf\}$ ,  $X = \{S, Se\}$ ) Nanoribbons*” [34]: obtaining Hamiltonians of the armchair and zigzag  $MX_2$  ( $M = \{Zr, Hf\}$ ,  $X = \{S, Se\}$ ) nanoribbons of various widths using DFT and MLWF, analyzing the effects of nanoribbon edge configuration and width scaling on the bandstructure and bandgap, device performance analysis of  $MX_2NR$  FETs by evaluating the ON-state current scaling behavior using DOS, transmission, injection velocity, charge density, bandstructure effective mass and effective transport mass, assessment of  $MX_2NR$  FETs and potential of  $MX_2NR$ s as channel materials for future logic devices by comparison with IRDS  $I_{ON}$  requirement, data visualization and writing the paper.
- [Pub 2]** In the journal paper “*Ballistic Performance of Quasi-One-Dimensional Hafnium Disulfide Field-Effect Transistors*” [82]: obtaining Hamiltonians of zigzag  $HfS_2$  nanoribbons of various widths using DFT and MLWF, analysis of NR width scaling behavior of bandstructure, bandgap, and bandstructure effective mass, analysis of the nanoribbon width scaling on the ON-state current performance of ZZ- $HfS_2NR$  FETs via DOS, injection velocity, current density and band-decomposed charge density, assessment of the potential of ZZ- $HfS_2NR$  FETs for future logic devices by comparison with IRDS  $I_{ON}$  and injection velocity requirements, data visualization and writing the paper.
- [Pub 3]** In the journal paper: “*Electronic, transport and ballistic device properties of quasi-one-dimensional GeS*” [112]: upgrading the QUDEN quantum transport simulator to assess both N- and P-type FET devices, obtaining Hamiltonians of the armchair and zigzag GeS nanoribbons of various widths using DFT and MLWFs, analysis and interpretation of nanoribbon scaling impact on bandstructure evolution, bandgap, and bandstructure effective mass, analysis and interpretation of the ON-state current width dependence of AC and ZZ GeSNR FETs using DOS, transmission, charge density and injection velocity, optimization of GeSNR FETs via oxide thickness variation, data visualization and writing the paper.
- [Pub 4]** In the journal paper “*Ab initio quantum transport simulations of monolayer GeS nanoribbons*” [113]: creating the extension of the QUDEN quantum transport simulator to input DFT-MLWF Hamiltonians, obtaining DFT-MLWF Hamiltonians of armchair GeSNRs of various widths, analysis of bandstructure and electron effective mass evolution with scaling NR width, analysis of the ON-state

current of armchair GeSNR NFETs using DOS and transmission, data visualization and writing the paper.

- [Pub 5]** In the conference paper: “*Validity of the Ballistic Top-of-the-Barrier Model for FETs Based on 2D Material Nanoribbons*” [114]: assessment and validation of the QUDEN quantum transport simulator by comparison with commercial QuantumATK software that utilizes a combination of NEGF and 3D Poisson, comparison of ZrS<sub>2</sub>NR FET and graphene nanoribbon FET current performance by analysis of bandstructure, DOS and transmission, data visualization, writing the paper and oral presentation.
- [Pub 6]** In the conference paper “*Transport Properties and Device Performance of Quasi-One-Dimensional MoS<sub>2</sub> FETs*” [115]: obtaining Hamiltonians of MoS<sub>2</sub> nanoribbons of various widths using DFT and MLWF, analysis of bandstructure and bandgap, analysis of the ON-state current nanoribbon width scaling behavior, analysis and interpretation of DOS, transmission, charge density, injection velocity, and current density of MoS<sub>2</sub>NRs and MoS<sub>2</sub>NR FETs, data visualization, writing the paper and oral presentation.
- [Pub 7]** In the conference paper “*Tunneling Attenuation and Leakage Current in MoS<sub>2</sub> Nanoribbon MOSFETs*” [116]: conceptualization, methodology, obtaining DFT-MLWF Hamiltonians of MoS<sub>2</sub>NRs of various widths, analysis of complex bandstructure evolution with NR width scaling, analysis of the OFF-state tunneling current of single-gate FETs for various channel lengths, cowriting the paper.

# Chapter 6

## Conclusions and Future Work

The gate-all-around (GAA) field-effect transistors (FETs) with nanosheets and nanowires represent the future of logic device technology with industry leaders already including 2D materials in their roadmap as early as late 2020s. However, there is an ongoing search for best-performing materials and device architectures due to the high number of possible candidates. While some experimental studies are present in the literature, they are limited to only a few materials due to the high cost and complexity of fabrication, which renders a need to study and identify the potential materials using an advanced computational design methodology which is the focus of this thesis. The main goals of this research are achieved by developing an advanced *ab initio* quantum transport method and applying it to investigate the feasibility of using nanoribbons of novel 2D materials as channel materials alternative to silicon-based devices.

Firstly, an *ab initio* quantum transport method is implemented which employs density functional theory (DFT) and maximally localized Wannier functions (MLWFs) to obtain the electronic structure of nanoribbons, whereas quantum transport simulations based on the non-equilibrium Green's function (NEGF) formalism in combination with the top-of-the-barrier (TOB) model are used to simulate ballistic single-gate FETs with a nanoribbon channel. Quantum transport simulator is implemented in QUDEN (from Quantum-Transport Device Engineering in Nanoelectronics) which is a legacy MATLAB code of the Computational Nanoelectronics Group at UNIZG-FER. For this research, QUDEN was heavily upgraded and extended to study both N- and P-type FETs and use DFT-MLWF Hamiltonians as an input, while its performance is boosted by using a much more numerically efficient recursive Green's function method. The simulator is validated by comparison with a commercial simulator which employs more advanced calculations that include solving a full 2D or 3D Poisson equation for device electrostatics. The implemented simulator is used to evaluate the electronic and transport

properties of nanoribbons, and device properties of NR FETs, with the motivation of employing such nanoribbons as foreseeable replacements for “nanosheet structures” in MBC FETs and RibbonFETs that stand as industry-relevant GAA FET implementations.

The detailed study reported in this thesis has investigated the following nanoribbon candidates for future logic devices: (i) armchair (AC) and zigzag (ZZ)  $\text{MX}_2\text{NRs}$  where  $M = \{\text{Hf}, \text{Zr}\}$  and  $X = \{\text{S}, \text{Se}\}$ , (ii) AC and ZZ GeSNRs, and (iii)  $\text{MoS}_2\text{NRs}$ . Nanoribbon widths are designated based on the number of unit cells along the nanoribbon width (ranging from 2 to 10), which results in NR widths in the range from  $\sim 7$  nm down to only  $\sim 0.8$  nm. The studied materials exhibit a strong influence of atomistic and quantum-mechanical effects on the electronic and transport properties and, consequently, on the performance of ultra-scaled NR FET devices. Material properties are largely determined by material composition, crystal phase, and edge configuration and, for example, similar structures in terms of crystal phase and edge configuration with different material composition exhibit similar width scaling properties.

The bandstructure of the nanoribbon evolves with downscaling, and so do device properties and performance. Due to the mentioned quantum-mechanical effects whose effect on material properties increases as nanoribbon width decreases, the bandstructure of narrower NRs is significantly altered and exhibits a lower number of available subbands due to a lower number of orbitals. For most devices, the evolution of the bandstructure with downscaling leads to lower curvature of dominant subbands near the CBM/VBM, i.e. an increase of electron/hole bandstructure effective mass is observed. Consequently, electron or hole injection velocity is reduced in narrower nanoribbons and the respective NR FETs exhibit lower ON-state current ( $I_{ON}$ ). Interestingly, some materials show an unexpected  $I_{ON}$  increase with downscaling. Specifically, armchair  $\text{MX}_2\text{NR}$  PFETs, zigzag  $\text{MX}_2\text{NR}$  NFETs, and zigzag GeSNR PFETs display improved  $I_{ON}$  when nanoribbon width is downscaled to  $\sim 2$  nm. Although bandstructure evolution with nanoribbon width downscaling is different for each configuration, all devices that exhibit an increase in FET performance show an emergence of a subband with higher curvature (i.e. lower effective mass), which induces an increase in injection velocity and ON-state current. The maximum  $I_{ON}$  is reported for FETs with  $\sim 2$  nm-wide NR channels, while for narrower nanoribbons the strong quantum-confinement effects deteriorates the current-driving capabilities.

The potential of studied nanoribbon FETs for future technology nodes is assessed by comparing their performance with the IEEE International Roadmap for Devices and Systems (IRDS) requirements which specify the  $I_{ON}$  of  $\sim 2$  mA/ $\mu\text{m}$  for ‘3 nm’ node and beyond. The comparison shows that most zigzag  $\text{MX}_2\text{NRs}$  and AC-GeSNRs with  $W \geq 1.86$  nm meet criteria

for both NFET and PFET devices. As for the zigzag  $\text{MX}_2\text{NRs}$ , the requirement is met for all studied Hf-based  $\text{MX}_2\text{NRs}$  and some Zr-based zigzag  $\text{MX}_2\text{NRs}$ , i.e. sub-3 nm-wide ZZ-ZrS<sub>2</sub>NRs and sub-6 nm-wide ZZ-ZrSe<sub>2</sub>NRs. In contrast, only PFETs with an armchair  $\text{MX}_2\text{NR}$  channel fulfill the  $I_{ON}$  requirement. Finally, MoS<sub>2</sub>NRs, which are nanoribbons of one of the most researched 2D materials after graphene, do not meet the IRDS requirement in any configuration. Nonetheless, our results indicate that certain Zr- and Hf-based  $\text{MX}_2\text{NRs}$  and GeSNRs have the potential to be employed as channel materials for future high-density and high-performance logic FETs, especially in multiple nanowire/nanosheet architectures such as MBC FETs and RibbonFETs.

This work establishes the computational design framework needed for the assessment of the upper ballistic performance limits and provides an assessment of potential nanoribbon candidates for future nanoscale logic devices. To build upon this research and extend its impact on more realistic devices, future research should deal with fully self-consistent NEGF and Poisson simulations while including carrier scattering. This approach could provide a way to explore a variety of structures by providing physical insights into realistic devices with dissipative transport. Furthermore, the high contact resistance in FETs with 2D materials could be addressed by analyzing the impact of various metallic contacts and different configurations for a comprehensive evaluation of nanoribbon FET devices. This direction could possibly be used to find optimal configurations and metals to minimize contact resistance in future logic devices. Further research could also be directed at assessing hundreds of other 2D materials that have not yet been studied, neither theoretically nor experimentally, in FET configurations but can be, in principle, cut into quasi-1D nanostructures. Some of these nanostructured materials could provide unexpected but useful properties that are suitable for future electron devices.

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# Abbreviations

1D .....	One-Dimensional
2D .....	Two-Dimensional
2DM .....	Two-Dimensional Material
AC .....	Armchair
BTE .....	Boltzmann Transport Equation
BZ.....	Brillouin Zone
CBM.....	Conduction Band Minimum
CMOS.....	Complementary-Metal-Oxide-Semiconductor
DD .....	Drift-Diffusion
DFT .....	Density Functional Theory
DOS.....	Density of States
FET .....	Field-Effect Transistor
GAA .....	Gate-All-Around
GGA .....	Generalized Gradient Approximation
IRDS.....	International Roadmap for Devices and Systems
KS.....	Kohn-Sham
LDA.....	Local Density Approximation
LDOS .....	Local Density of States
MBC .....	Multi-Bridge-Channel
MLWF.....	Maximally Localized Wannier Functions
MX <sub>2</sub> .....	Transition Metal Dichalcogenide
MX <sub>2</sub> NR.....	Transition Metal Dichalcogenide Nanoribbon

NEGF ..... Non-Equilibrium Green's Function  
OBC..... Open Boundary Condition  
PBE..... Perdew-Burke-Ernzerhof  
PP ..... Pseudo-Potential  
QUDEN..... Quantum-transport Device Engineering in Nanoelectronics  
S/D..... Source and Drain  
TMD ..... Transition Metal Dichalcogenide  
TOB..... Top-Of-The-Barrier  
UTB..... Under-The-Barrier  
VBM..... Valence Band Maximum  
WF ..... Wannier Functions  
WKB..... Wentzel–Kramers–Brillouin  
XC ..... Exchange-Correlation  
ZZ ..... Zigzag

# Publications

## Publication 1

### **Intrinsic Performance Limits of Extremely Scaled Field-Effect Transistors Based on $\text{MX}_2$ ( $\text{M} = \{\text{Zr}, \text{Hf}\}$ , $\text{X} = \{\text{S}, \text{Se}\}$ ) Nanoribbons**

M. Matic and M. Poljak, “Intrinsic performance limits of extremely scaled field-effect transistors based on  $\text{MX}_2$  ( $\text{M} = \{\text{Zr}, \text{Hf}\}$ ,  $\text{X} = \{\text{S}, \text{Se}\}$ ) nanoribbons,” *Journal of Applied Physics*, vol. 136, no. 8, p. 084307, Aug. 2024.

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# Intrinsic performance limits of extremely scaled field-effect transistors based on $\text{MX}_2$ ( $\text{M} = \{\text{Zr}, \text{Hf}\}$ , $\text{X} = \{\text{S}, \text{Se}\}$ ) nanoribbons

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## ABSTRACT

We investigate the  $\text{MX}_2$  ( $\text{M} = \{\text{Hf}, \text{Zr}\}$ ,  $\text{X} = \{\text{S}, \text{Se}\}$ ) transition metal dichalcogenides patterned into armchair (AC) and zigzag (ZZ) nanoribbons (NRs) as potential channel materials in future logic field-effect devices. *Ab initio* quantum transport simulations are employed to assess the electronic, transport, and ballistic field-effect transistor (FET) properties of devices with such quasi-one-dimensional channels. We report a non-monotonic scaling behavior of  $\text{MX}_2\text{NR}$  properties due to strong quantum confinement effects, which is reflected in a strong dependence of the ON-state current ( $I_{\text{ON}}$ ) of  $\text{MX}_2\text{NR}$  FETs on the nanoribbon configuration. The  $\sim 2$  nm-wide HfSe<sub>2</sub> and ZrSe<sub>2</sub> AC-PFETs have the highest  $I_{\text{ON}}$  of up to 2.6 mA/ $\mu\text{m}$  at 10 nA/ $\mu\text{m}$  OFF-state current. Surprisingly,  $\text{MX}_2\text{NR}$  ZZ-NFETs exhibit a current increase of up to 70% when channel width is scaled down, with  $I_{\text{ON}}$  reaching 2.2 mA/ $\mu\text{m}$  in  $\sim 2$  nm-wide devices. The high ON-state performance is a direct consequence of high carrier injection velocity, which is explained by analyzing the band structure, transmission, and density of states. We demonstrate that nanostructured  $\text{MX}_2$  materials can be promising candidates for future logic transistors based on multi-nanowire architectures.

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## I. INTRODUCTION

Multi-bridge channel (MBC) FETs with bulk-silicon nanosheets or nanowires represent current state-of-the-art device technology.<sup>1–3</sup> However, silicon is reaching its limits and new materials are needed to extend Moore's law. 2D materials (2DMs) are one of the most promising candidates to replace silicon due to excellent electronic and transport properties,<sup>4,5</sup> despite the currently unresolved problem of high contact resistance, which greatly affects the device performance.<sup>6–8</sup> The 2DMs can be patterned into quasi-one-dimensional (quasi-1D) nanoribbons (NRs),<sup>9,10</sup> which could be used in MBC FETs<sup>11</sup> [see Fig. 1(a)] and enable high integration density with additional performance tuning by quantum confinement effects. Experimental work on NRs is limited to a few materials due to the high complexity of fabrication with the main challenge being the reliable control of crystal phase, edge structure, and dimensionality.<sup>12</sup> Nevertheless, continuous progress in this

field affirms fabrication potential and makes nanoribbons interesting structures for future nanodevices.<sup>13–15</sup> In this work, we focus on transition metal dichalcogenides (TMDs)  $\text{MX}_2$  ( $\text{M} = \{\text{Zr}, \text{Hf}\}$ ,  $\text{X} = \{\text{S}, \text{Se}\}$ ) as some of the most promising 2DMs,<sup>16–18</sup> with a reported high compatibility of Hf- and Zr-based TMDs to high- $k$  oxides (HfO<sub>2</sub>, ZrO<sub>2</sub>).<sup>19,20</sup> Potential of 2D  $\text{MX}_2$  TMDs has been studied in depth<sup>17,21,22</sup> by advanced theoretical calculations and experimental work was reported in Refs. 23 and 24. The  $\text{MX}_2$  nanoribbon ( $\text{MX}_2\text{NR}$ ) research is quite limited with electronic properties studied for ZrS<sub>2</sub>NRs,<sup>25</sup> HfSe<sub>2</sub>NRs.<sup>26</sup> As for  $\text{MX}_2\text{NR}$  FETs, only single ZrSe<sub>2</sub>NR FET was studied in Ref. 27 with our group's initial study on zigzag HfS<sub>2</sub>NR FETs reported in Ref. 28, which showed potential of these devices for future logic devices. Therefore, we expand our research to study all potential TMD materials similar to HfS<sub>2</sub>NRs that show semiconducting behavior. We report in detail the electronic, transport, and ballistic device characteristics, as intrinsic upper limits to device performance, for

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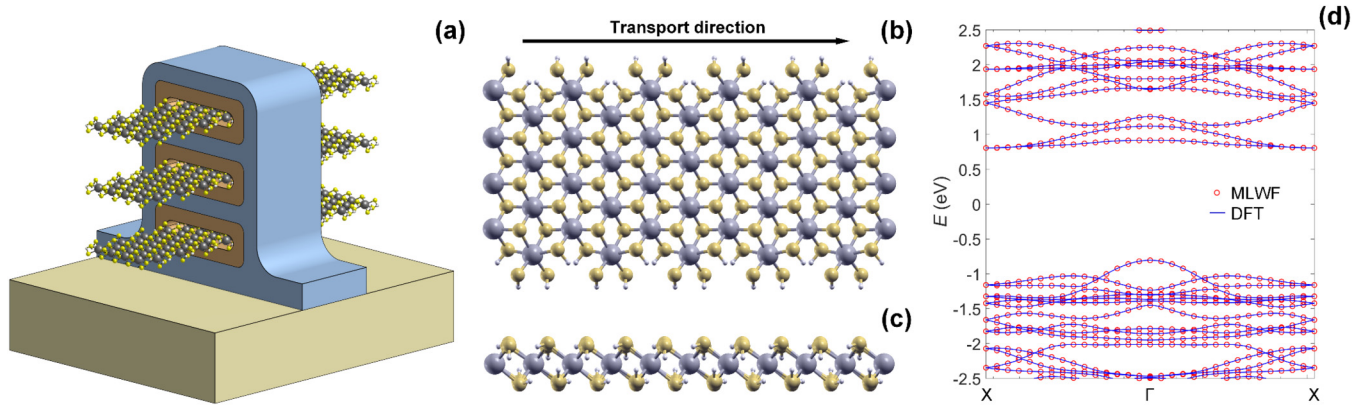


FIG. 1. (a) Model of a MBC FET with nanoribbon channel. (b) Top view and (c) side view of AC-MX<sub>2</sub>NR. (d) MLWF and DFT bandstructure of AC-ZrS<sub>2</sub>NR.

armchair (AC) and zigzag (ZZ) MX<sub>2</sub>NR FETs in eight different configurations defined by the NR material and edge type. We show AC-PFETs and ZZ-NFETs driving current increases with downscaling with maximum for ~2 nm-wide NRs while AC-NFET and ZZ-PFET show performance degradation with downscaling. To explore these findings, we investigate the density of states, transmission, and injection velocity of AC MX<sub>2</sub>NRs since ZZ-counterparts were explored previously in detail.<sup>28</sup> Furthermore, we explore interdependence of current to various properties such as charge density, injection velocity, band structure effective mass and effective transport mass where we show that the performance is mostly determined by injection velocity and transport effective mass. Finally, we compare AC- and ZZ- MX<sub>2</sub>NR NFETs and PFETs to the requirements of the International Roadmap of Devices and Systems (IRDS) and other 2DMs. We show that IRDS current requirement for both N- and PFET is met by ZZ-FETs with HfS<sub>2</sub>NR and HfSe<sub>2</sub>NR channel of all widths, ZZ-ZrS<sub>2</sub>NRs with  $W < 3$  nm and ZZ-ZrSe<sub>2</sub>NRs with  $W < 6$  nm while only PFET devices with AC nanoribbons meet IRDS  $I_{ON}$  requirements.

## II. METHODOLOGY

Supercells of AC-MX<sub>2</sub>NRs [Figs. 1(b) and 1(c)] and ZZ-MX<sub>2</sub>NRs are constructed based on the number of 2D MX<sub>2</sub> unit cells ( $NW$ , from 2 to 10) repeated along the nanoribbon width ( $W$ ). This results in  $W$  from 0.9 to 4 nm for AC-MX<sub>2</sub>NRs, and 1.3 to 6.7 nm for ZZ-MX<sub>2</sub>NRs. The Hamiltonians are found using the *ab initio* density functional theory (DFT) Quantum Espresso (QE) program<sup>29</sup> with plane-augmented wave (PAW) pseudopotentials and Perdew, Burke, and Ernzerhof (PBE)<sup>30</sup> exchange correlation (XC) functional. Interactions between the layers are excluded by adding a vacuum of 20 Å in confined directions. A  $1 \times 15 \times 1$  Monkhorst-Pack  $k$ -point grid<sup>31</sup> with 15 points in the transport direction is used to sample the Brillouin zone. The kinetic energy cutoff is set at 1360 eV, while the convergence threshold for the ionic forces is set to  $10^{-3}$  eV/Å and  $10^{-4}$  eV for the total energy. The DFT Hamiltonians are then transformed into a space-localized basis using maximally-localized Wannier functions (MLWFs)<sup>32</sup>

implemented in the Wannier90 tool.<sup>33</sup> Within Wannier90, trial orbitals are  $d$  orbitals for Zr/Hf atoms and  $p$  orbitals for S/Se atoms. The MLWF Hamiltonians are assessed by comparison of band structure calculated with DFT and MLWF, as reported in Fig. 1(d). The MLWF Hamiltonian matrices of MX<sub>2</sub>NR supercells are extended in the transport direction to construct the total Hamiltonian of ~15 nm-long nanoribbons that serve as the channel of MX<sub>2</sub>NR FETs.

The ballistic top-of-the-barrier (ToB) FET model<sup>34</sup> is used to simulate N- and P-type single gate FETs with MX<sub>2</sub>NR channels. The ToB model calculates the thermionic current while direct tunneling is negligible for a 15 nm-long device. Furthermore, as intrinsic limit is explored, there is no scattering and dissipation included in the simulation with contact resistance neglected as source and drain channels are considered ideal, i.e., of the same material as the channel. Although dissipative transport simulation is necessary for a complete assessment of device performance, previous studies show that carrier transport in sub-15 nm-long FETs is expected to be 75%–90% ballistic.<sup>35–37</sup> The transmission function and the density of states (DOS), which are the main inputs of the ToB FET model, are calculated using the non-equilibrium Green's function (NEGF) formalism<sup>38,39</sup> as implemented in our in-house code.<sup>40,41</sup> Main term in NEGF formalism is the retarded Green's function

$$G^R(E) = [(E + i0^+)I - H - \Sigma_S^R(E) - \Sigma_D^R(E)]^{-1}, \quad (1)$$

where  $H$  is the total channel Hamiltonian, while  $\Sigma_S^R$  and  $\Sigma_D^R$  are source/drain (S/D) contact self-energy matrices calculated using the Sancho–Rubio method.<sup>42,43</sup> Transmission is obtained using

$$T(E) = \text{tr}[\Gamma_S(E)G^R(E)\Gamma_D(E)G^A(E)], \quad (2)$$

where  $\Gamma_{S,D} = -2 \text{Im}(\Sigma^R)$  are S/D contact broadening matrices. On the other hand, density of states is calculated using

$$\text{DOS}(E) = \frac{1}{\pi} \text{tr}[-2\text{Im}(G^R(E))]. \quad (3)$$

The N- and PFETs with AC- and ZZ-MX<sub>2</sub>NR channels are simulated with an ideal electrostatic gate control assumed for these atomically-thin channels leading to an ideal subthreshold slope (60 mV/dec at 300 K), an equivalent oxide thickness (EOT) of 1 nm, an S/D doping of 0.01 areal molar fraction, and a supply voltage ( $V_{DD}$ ) of 0.7 V. The simulations of the MX<sub>2</sub>NR FETs are performed with a common OFF-state current ( $I_{OFF}$ ) of 10 nA/ $\mu$ m, as defined by the IEEE International Roadmap for Devices and Systems (IRDS) for high-performance logic devices.<sup>44</sup> The ON-state current ( $I_{ON}$ ) is extracted at  $V_{GS} = V_{DS} = V_{DD} = 0.7$  V. Finally, we set the EOT to 0.6 nm and compare the  $I_{ON}$  performance of MX<sub>2</sub>NR FETs to maximum IRDS  $I_{ON}$  requirement with  $I_{ON} = 1.979$  mA/ $\mu$ m, and other quasi-1D materials studied by either our or other groups.

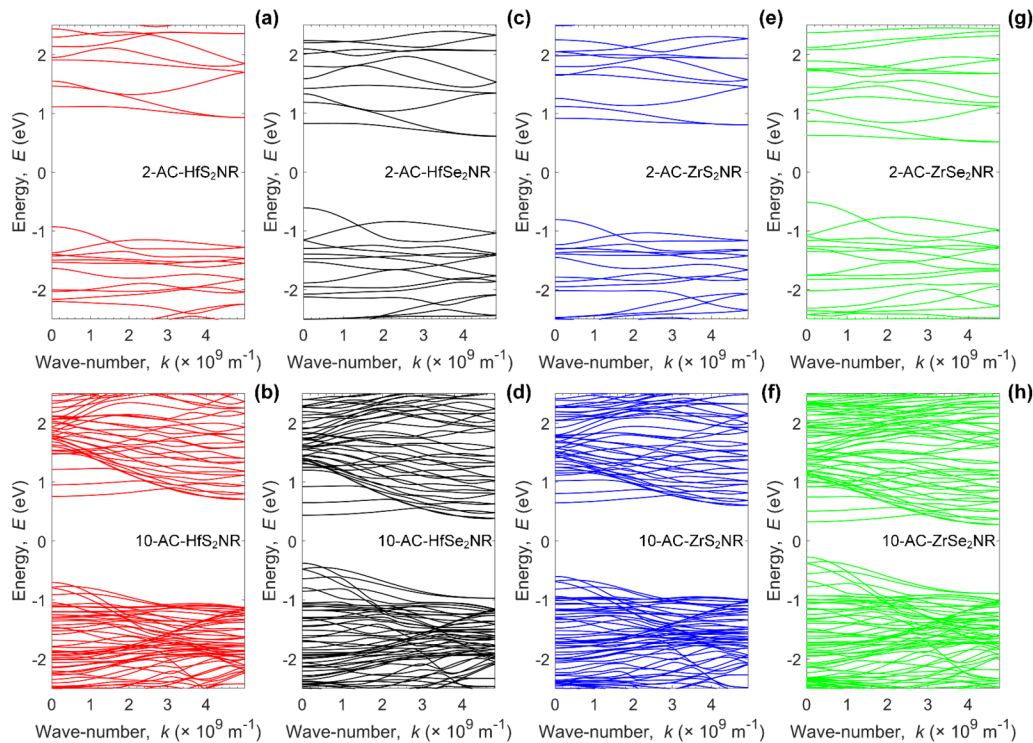
### III. RESULTS AND DISCUSSION

The band structure of the widest ( $NW = 10$ ) and narrowest ( $NW = 2$ ) MX<sub>2</sub>NRs with AC and ZZ nanoribbons are shown in Figs. 2 and 3, respectively. The AC-MX<sub>2</sub>NRs (Fig. 2) have an indirect bandgap and show qualitatively similar evolution of the band structure width and  $W$  downscaling which is accompanied by a decrease in the number of subbands near the conduction band minimum (CBM) and valence band maximum (VBM). On the other hand, ZZ-MX<sub>2</sub>NRs (Fig. 3) exhibit a direct bandgap with

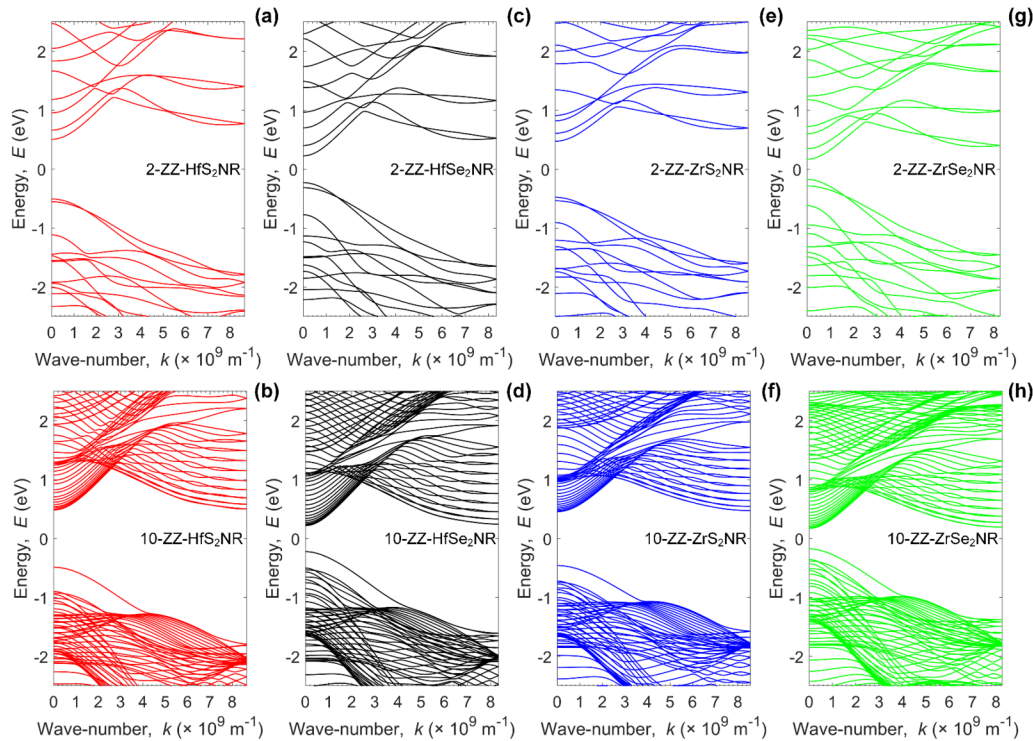
subband crowding in the conduction band at the CBM for wider NRs. Moreover, two degenerate subbands are formed in the valence band of the 10-ZZ-MX<sub>2</sub>NR due to edge effects,<sup>28</sup> and this degeneracy is generally broken in the narrowest ZZ-MX<sub>2</sub>NRs due to strong quantum confinement. Our DFT calculations show that all AC and ZZ MX<sub>2</sub>NRs are semiconductors which show qualitatively similar dispersions and band structure evolution features with  $W$  down-scaling for the two (AC and ZZ) categories.

The bandgap ( $E_g$ ) is extracted from the dispersions and its width-scaling dependence in AC and ZZ-MX<sub>2</sub>NRs is shown in Fig. 4.  $E_g$  of all AC-MX<sub>2</sub>NRs [Fig. 4(a)] increases by  $\sim 0.45$  eV when  $W$  is scaled from  $\sim 4$  to  $\sim 1$  nm. In terms of bandgap values, a  $\sim 0.7$  eV higher  $E_g$  is observed for S-based AC-MX<sub>2</sub>NRs compared to their Se-based counterparts with the highest  $E_g = 1.85$  eV observed for 1 nm-wide AC-HfS<sub>2</sub>NR and lowest  $E_g = 0.55$  eV for AC-ZrSe<sub>2</sub>NRs with  $W = 4$  nm. On the other hand, the bandgap of ZZ nanoribbons [Fig. 4(b)] is immune to width scaling, making it a good choice for robust NR FET design. Similarly to AC-MX<sub>2</sub>NRs, S-based ZZ-MX<sub>2</sub>NRs exhibit  $\sim 0.5$  eV higher  $E_g$  compared to Se-based ZZ-MX<sub>2</sub>NRs with maximum of 1 eV for ZZ-HfS<sub>2</sub>NRs and minimum of 0.35 eV for ZZ-ZrSe<sub>2</sub>NRs.

The S-based MX<sub>2</sub>NRs of both edge types exhibit bandgaps of at least 0.9 eV, which is enough to suppress band-to-band tunneling (BTBT) for  $V_{DD}$  under 0.7 V. On the other hand, Se-based MX<sub>2</sub>NRs with ZZ edges exhibit a rather constant  $E_g$  of about



**FIG. 2.** Bandstructure of the (a) 2- and (b) 10-unit-cell-wide armchair HfS<sub>2</sub>NR, (c) 2- and (d) 10-unit-cell-wide armchair HfSe<sub>2</sub>NR, (e) 2- and (f) 10-unit-cell-wide armchair ZrS<sub>2</sub>NR, and (g) 2- and (h) 10-unit-cell-wide armchair ZrSe<sub>2</sub>NR.



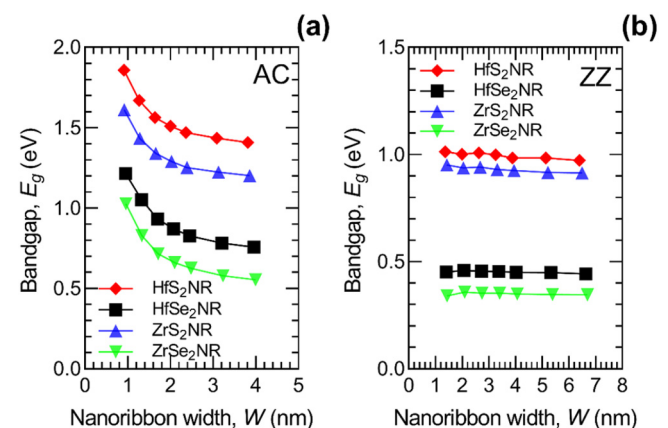
**FIG. 3.** Bandstructure of the (a) 2- and (b) 10-unit-cell-wide zigzag HfS<sub>2</sub>NR, (c) 2- and (d) 10-unit-cell-wide zigzag HfSe<sub>2</sub>NR, (e) 2- and (f) 10-unit-cell-wide zigzag ZrS<sub>2</sub>NR, and (g) 2- and (h) 10-unit-cell-wide zigzag ZrSe<sub>2</sub>NR.

0.4 eV, whereas for Se-based AC nanoribbons, one needs ultra-narrow widths to reach appropriate bandgaps. Nevertheless, we consider all these materials as potential candidates for future logic FETs in the following paragraphs because it is well established in the literature that PBE functionals underestimate the bandgap. A recent study<sup>18</sup> has shown that  $E_g$  obtained using the HSE06 functional is at least  $\sim 0.6$  eV higher for S- and Se-based MX<sub>2</sub>-enes than  $E_g$  calculated with the PBE functional.

The performance of N- and PFETs with AC- and ZZ-MX<sub>2</sub>NR channels is evaluated through the ON-state current, which is shown in Fig. 5 for AC-MX<sub>2</sub>NR FETs (AC-FETs) and ZZ-MX<sub>2</sub>NR FETs (ZZ-FETs). All AC-NFETs exhibit  $I_{ON}$  of  $\sim 1$  mA/ $\mu$ m for NRs with  $W > 2.4$  nm, while downscaling decreases the  $I_{ON}$  up to 50% due to strong quantum confinement effects [Fig. 5(a)] with an exception for the narrowest HfX<sub>2</sub>NRs which show surprising increase up to 30% due to quantum confinement effects. On the other hand, the  $I_{ON}$  of AC-PFETs [Fig. 5(b)] depends mostly on the chalcogenide, i.e., S and Se as their AC-PFET configurations show similar  $I_{ON}$  performance. We note that PFETs with AC HfSe<sub>2</sub> and ZrSe<sub>2</sub> nanoribbons as channels have  $\sim 30\%$  higher  $I_{ON}$  than the S-based AC-PFETs.  $I_{ON}$  is relatively constant for  $W > 3$  nm with  $\sim 2.4$  mA/ $\mu$ m for Se-based and  $\sim 1.9$  mA/ $\mu$ m for S-based devices. Scaling down the  $W$  shows surprising  $I_{ON}$  increase with the maximum for  $W$  of 2–2.5 nm, depending on the device with  $\sim 2.6$  mA/ $\mu$ m for HfSe<sub>2</sub> and ZrSe<sub>2</sub> nanoribbon devices with

$\sim 2.1$  mA/ $\mu$ m for HfS<sub>2</sub> and ZrS<sub>2</sub> nanoribbon devices. Further reduction in width decreases  $I_{ON}$  by  $\sim 30\%$  in all AC-PFETs.

$I_{ON}$  of ZZ-NFETs, reported in Fig. 5(c), shows that all devices exhibit surprising  $I_{ON}$  increase with downscaling.  $I_{ON}$  increases



**FIG. 4.** Bandgap dependence on nanoribbon width of the investigated (a) armchair and (b) zigzag MX<sub>2</sub>NRs.

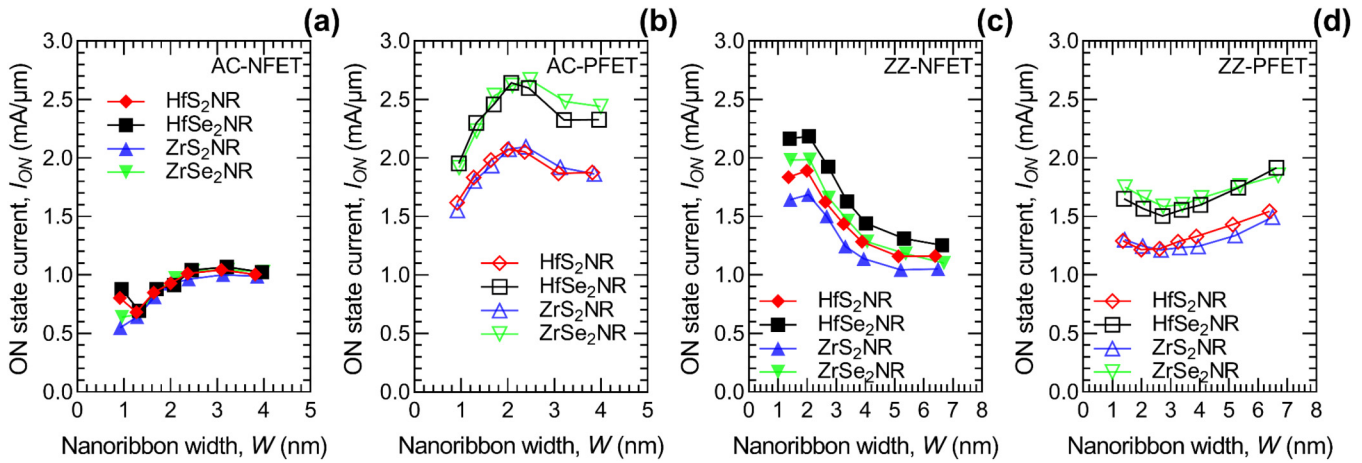


FIG. 5. ON-state current of armchair (a) NFETs and (b) PFETs, and zigzag (c) NFETs and (d) PFETs with various  $\text{MX}_2\text{NR}$  channels.

slightly for  $W > 4$  nm with  $I_{ON}$  in the 1–1.25 mA/ $\mu\text{m}$  range. Further NR width scaling from 4 to 2 nm shows significant increase of  $I_{ON}$  up to 70% while for the narrowest ZZ-NFETs with 1 nm-wide  $\text{MX}_2\text{NR}$  channel performance marginally degrades. ZZ-HfSe<sub>2</sub>NR NFETs exhibit the highest performance at given  $W$  and maximum  $I_{ON}$  of 2.2 mA/ $\mu\text{m}$  reported for  $\sim 1$ –2 nm-wide ZZ-HfSe<sub>2</sub>NR NFETs. ZZ-NFETs with HfS<sub>2</sub> and ZrSe<sub>2</sub> nanoribbon channels show similar  $I_{ON}$  performance, which is  $\sim 10\%$  lower compared to ZZ-NFETs with HfSe<sub>2</sub>NR channels. The ZZ-ZrS<sub>2</sub>NR NFETs exhibit the lowest  $I_{ON}$  with a maximum of 1.7 mA/ $\mu\text{m}$  for  $W = 2$  nm. In contrast, as reported in Fig. 5(d) the ZZ-PFETs have a weakly decreasing  $I_{ON}$  when  $W$  is downscaled up to  $W = 3$  nm and a slight increase of  $\sim 10\%$  when  $W$  is scaled from 3 to 1 nm. In the widest examined ZZ-NRs the drive current is 1.9 mA/ $\mu\text{m}$  for Se-based ZZ-PFETs and 1.5 mA/ $\mu\text{m}$  in S-based devices. The lowest performance is reported for  $W = 3$  nm where HfSe<sub>2</sub> and ZrSe<sub>2</sub> exhibit  $I_{ON} \sim 1.5$  mA/ $\mu\text{m}$  while their S-based counterparts  $I_{ON}$  is  $\sim 1.2$  mA/ $\mu\text{m}$ . Similar to AC-PFETs, Se-based ZZ-PFETs exhibit 25% higher  $I_{ON}$  compared to devices with HfS<sub>2</sub> and ZrS<sub>2</sub> nanoribbon channels. The results show that the  $I_{ON}$  scaling behavior is mainly determined by the edges, i.e., the AC and ZZ edges. Therefore, the performance  $\text{MX}_2\text{NR}$  FETs and the  $I_{ON}$  behavior within each group are governed by the same physical effects with the only real difference being the magnitude.

The same principles apply to ZZ-MX<sub>2</sub>NRs as to the previously studied ZZ-HfS<sub>2</sub>NRs in Ref. 28. In short, we have shown that for ZZ-NFETs current of the wider NRs is mainly determined by the higher energy subbands, while for the narrower ones it is determined by single subband nearest to the CBM due to lower number of subbands near the CBM. On the other hand, the PFET performance is mainly attributed to two degenerate subbands in the VB of wide nanoribbons, which are dominant due to edge effects. Furthermore, scaling down NR width breaks the degeneracy and lowers the ZZ-PFET performance. Therefore, we focus on AC-MX<sub>2</sub>NRs in this work.

We investigate the transport properties of AC-MX<sub>2</sub>NRs on an example of HfSe<sub>2</sub>NRs by studying the density of states,

transmission and injection velocity. The DOS and transmission in CB and VB of HfSe<sub>2</sub>NRs with various widths are shown in Fig. 6. The HfSe<sub>2</sub>NR NFETs exhibit dense DOS in CB, as shown in Fig. 6(a), and scaling down the NR width increases the overall DOS near CBM which is accompanied by decrease of the number of Van Hove singularities (VHS) due to the lower number of available bands. Although the DOS is higher in narrower NRs, it is not supported by higher transmission [see Fig. 6(b)]. This is a direct consequence of lower curvature of dominant subbands (i.e., higher effective mass) in narrower NRs which ultimately lowers the performance of NFETs with AC edges. Wide HfSe<sub>2</sub>NRs with  $W > 3$  nm show interesting transmission near the CBM where it is 2 at the CBM which sharply decreases to 1 and again increases back to two within CBM + 0.01 eV. The narrowest NR with  $W = 0.95$  nm has transmission 1 at the CBM which quickly rises to 2 at CBM + 0.01 eV. On the other hand, DOS curves in VB for AC-HfSe<sub>2</sub>NRs exhibit much lower number of bands near VBM compared to CB. Scaling down the nanoribbon width decreases VHS number while DOS [see Fig. 6(c)] near VBM increases. Transmission is unity for all NRs up to VBM + 0.07 eV. The NRs with  $W = 2.08$  nm and  $W = 2.46$  nm have the lowest overall DOS up to VBM + 0.1 eV which is the most relevant region for transport.

Although the density of states and transmission encompass all the physics that governs the performance of AC NFETs and PFETs, differences in device behavior are not necessarily easy to explain using barely these two features. Therefore, we extract and examine the figures-of-merit that incorporate the DOS and transmission such as injection velocity, charge density, band structure effective mass and effective transport mass. First, we explore on the dependence of the injection velocity ( $v_{inj}$ ) on the gate voltage ( $V_{GS}$ ) in the range between the threshold voltage ( $\sim 0.2$  V) and the supply voltage (0.7 V) for AC-NFETs and AC-PFETs with HfSe<sub>2</sub>NR channel in Figs. 7(a) and 7(b), respectively. The AC-NFETs show almost no modulation with  $V_{GS}$  with the magnitude being directly correlated with the  $I_{ON}$  performance. For NRs with  $W > 3$  nm,  $v_{inj}$  is  $\sim 0.75 \times 10^7$  cm/s while for the  $W = 1.33$  nm, which has the

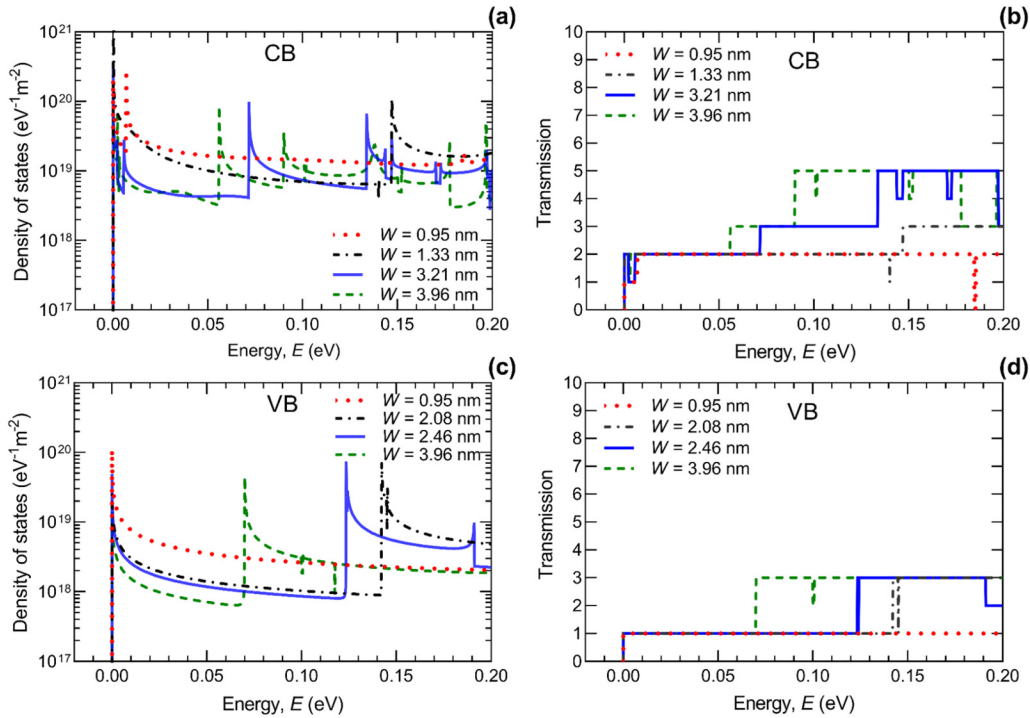


FIG. 6. DOS and transmission for (a), (b) CB and (c), (d) VB of AC-HfSe<sub>2</sub>NRs of various widths.

lowest  $I_{ON}$ ,  $v_{inj} = 0.5 \times 10^7$  cm/s. The AC-PFETs show much more interesting  $v_{inj}$ . At threshold voltage, NRs with  $W > 2$  nm show a similar  $v_{inj}$  of  $\sim 1.45 \times 10^7$  cm/s while  $v_{inj}$  modulation with  $V_{GS}$  increase results with highest  $v_{inj} \sim 2.05 \times 10^7$  cm/s at supply voltage for  $W = 2.08$  nm and  $W = 2.46$  nm. The narrowest NRs with  $W = 0.95$  nm show the lowest  $v_{inj}$  and the lowest modulation with  $V_{GS}$  where  $v_{inj}$  is  $\sim 1.5 \times 10^7$  cm/s at  $V_{GS} = 0.7$  V. Similarly to

AC-NFETs,  $I_{ON}$  directly corresponds to  $v_{inj}$  in the ON-state for AC-PFETs.

To affirm this, we plot the interdependence of the ON-state current, the ON-state charge density and the ON-state injection velocity in Fig. 8(a).  $I_{ON}$  is proportional to the ON-state injection velocity and inversely proportional to the ON-state charge density. PFETs generally exhibit higher  $v_{inj}$  and consequently higher  $I_{ON}$

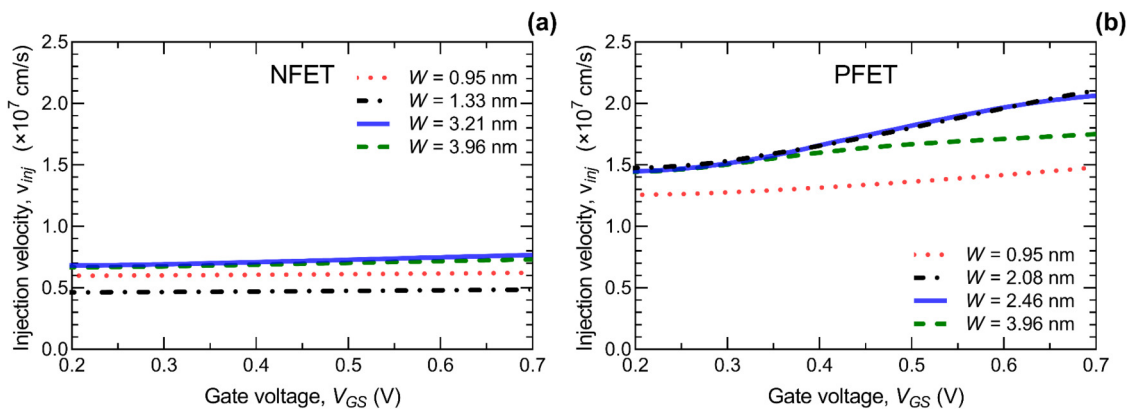
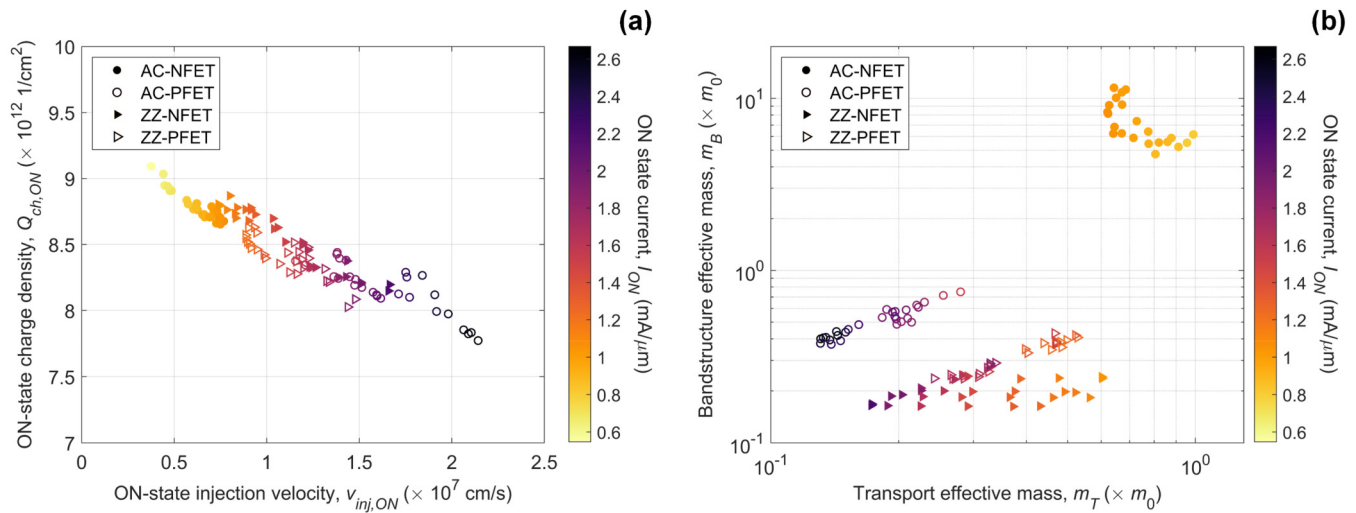


FIG. 7. Injection velocity gate voltage dependence of (a) n-type and (b) p-type armchair HfSe<sub>2</sub>NR FETs for various widths.

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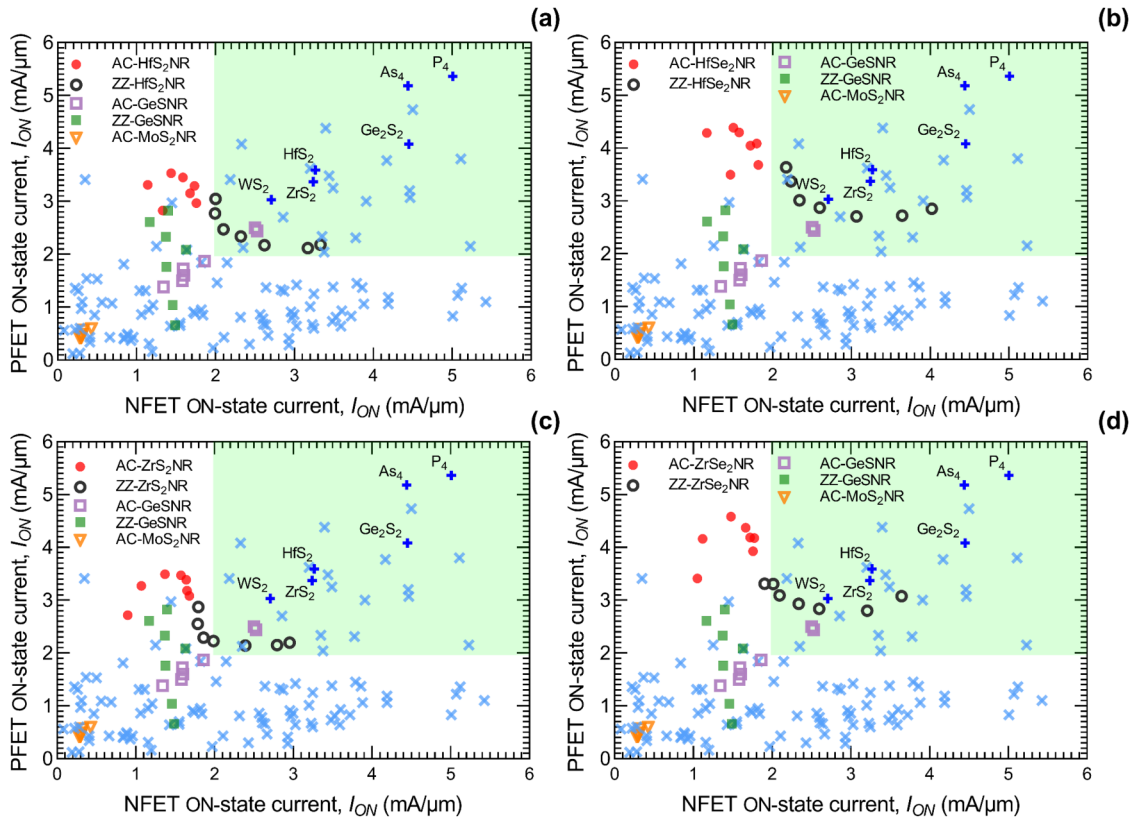
**FIG. 8.** (a) Interdependence of the ON-state current, charge density and injection velocity for all the examined MX<sub>2</sub>NR FETs. (b) Interdependence of the ON-state current, bandstructure, and effective transport mass for all the examined MX<sub>2</sub>NR FETs.

compared to NFETs with both AC and ZZ edges. Furthermore, in Fig. 8(b), we plot the interdependence of  $I_{ON}$ , band structure effective mass ( $m_B$ ), and the effective transport mass ( $m_T$ ).  $m_B$  of electrons and holes is extracted by a parabolic approximation of the subband closest to the CBM and VBM.  $m_T$  is calculated from the average thermal velocity that is extracted from the bias-dependence of the injection velocity in the quasi-1D channel,<sup>45</sup> as done in our previous work.<sup>46</sup> The low  $I_{ON}$  of AC-NFETs is directly caused by the highest  $m_T$  and  $m_B$  among all the studied devices, whereas the better performance of AC-PFETs is due to moderate  $m_B$  of 0.4–0.8 $m_0$  combined with low  $m_T < 0.3m_0$  and minimum of 0.14 $m_0$ . On the other hand, most N- and PFETs with the ZZ-MX<sub>2</sub>NR channels generally have lower  $m_B$  compared to their AC counterparts, and exhibit  $m_T$  in the 0.2–0.6 $m_0$  range. The narrowest ZZ-NFETs in which  $I_{ON}$  increases considerably [Fig. 4(c)] also exhibit the smallest  $m_T$  of only 0.18 $m_0$ . This discussion demonstrates that  $m_T$  and  $m_B$  of all MX<sub>2</sub>NR FETs, in combination with the 15-nm-long channel, should be large enough to suppress tunneling, which makes the ballistic  $I_{ON}$  a reliable figure-of-merit for these devices.

The comparison of our results with the IRDS  $I_{ON}$  requirement minimum of  $\sim 2$  mA/ $\mu$ m shows that most Se-based AC-PFETs with  $W > 1.2$  nm and sub-2 nm-wide Se-based ZZ-NFETs meet the IRDS requirement. These devices are studied with EOT set to 1 nm and using high- $\kappa$  dielectrics such as HfO<sub>2</sub> and ZrO<sub>2</sub> that exhibit  $\epsilon_r > 20$  should enable EOT up to 0.5. Furthermore, these dielectrics have shown high compatibility with studied MX<sub>2</sub>NRs which affirms the potential of these materials as logic device candidates. We compare  $I_{ON}$  of NFETs and PFETs with AC- and ZZ- MX<sub>2</sub>NR channels in Fig. 9 with one hundred 2D potential candidates for logic devices studied in Ref. 17, AC- and ZZ GeSNRs,<sup>40,41</sup> and AC-MoS<sub>2</sub>NRs<sup>47</sup> studied by our group. For a fair comparison, all

devices are single-gate FETs with an EOT value of 0.6 nm, i.e., the same value used in previous comparisons and referenced literature. We group the data according to the MX<sub>2</sub>NR channel material, as shown in Fig. 9.

None of the studied FETs with AC-MX<sub>2</sub>NR channel fulfill the IRDS  $I_{ON}$  requirements for both N- and PFET devices. Although AC-PFETs exhibit  $I_{ON} > 2.5$  mA/ $\mu$ m which is sufficient to meet the IRDS  $I_{ON}$  requirement, none of the AC-NFETs meet  $I_{ON}$  IRDS requirement. On the other hand, all NFETs and PFETs with Hf-based ZZ-MX<sub>2</sub>NR channel meet the IRDS requirement while only ZZ-ZrS<sub>2</sub>NRs with  $W < 3$  nm and ZZ-ZrSe<sub>2</sub>NRs with  $W < 6$  nm meet the requirement with limiting factor being low performance of wide ZZ-NFETs. Furthermore, we compare studied devices to our previous works. Compared to AC and ZZ GeSNRs, only AC-GeSNRs with  $W > 3$  nm show better NFET and PFET  $I_{ON}$  performance than most MX<sub>2</sub>NR devices with the only exception of Se-based ZZ-MX<sub>2</sub>NRs with  $W < 3$  nm. In addition, the  $I_{ON}$  performance of all AC or ZZ MX<sub>2</sub>NR FETs is superior to any AC-MoS<sub>2</sub>NR FET. Finally, compared to 2D materials, AC and ZZ MX<sub>2</sub>NR FETs perform better than  $\sim 90\%$  of the studied 2D materials. Compared to the 2D counterparts of the studied nanoribbons, e.g., HfS<sub>2</sub> and ZrS<sub>2</sub>, the  $I_{ON}$  performance of nanoribbon FETs cannot match the 2D FETs. However, this is to be expected due to the strong quantum confinement effects along the width in ultra-narrow NRs. The performance is especially poor when compared against other most promising 2D materials such WS<sub>2</sub>, GeS<sub>2</sub>, arsenene (As<sub>4</sub>) and phosphorene (P<sub>4</sub>). Nevertheless, MX<sub>2</sub>NR FETs show adequate performance that affirms the potential of MX<sub>2</sub>NRs as channel materials for future ultra-scaled FETs if the issues of high contact resistance in low-dimensional materials are solved.<sup>48,49</sup>



**FIG. 9.** nFET vs pFET ON-state current of devices with (a) AC and ZZ-HfS<sub>2</sub>NR, (b) AC and ZZ-HfSe<sub>2</sub>NR, (c) AC and ZZ-ZrS<sub>2</sub>NR, and (d) AC and ZZ-ZrSe<sub>2</sub>NR channel. Green area represents IRDS  $I_{ON}$  requirement with  $I_{ON} = 1.979 \text{ mA}/\mu\text{m}$ . The 100 2DMs reported in Ref. 12 are included in graphs with the most relevant materials directly named and marked with blue plus signs, while the unnamed 2DMs are shown with light blue crosses.

#### IV. CONCLUSIONS

Transition metal dichalcogenides (TMDs)  $\text{MX}_2$  ( $M = \{\text{Hf}, \text{Zr}\}$ ,  $X = \{\text{S}, \text{Se}\}$ ) are patterned into armchair and zigzag quasi-1D semiconductor nanoribbons and investigated using *ab initio* quantum transport simulations. The bandgap width-dependence characteristics can be divided into two groups, namely, in AC-MX<sub>2</sub>NRs  $E_g$  increases by  $\sim 0.45 \text{ eV}$  when  $W$  is scaled from  $\sim 4 \text{ nm}$  to  $\sim 1 \text{ nm}$ , while ZZ-MX<sub>2</sub>NRs exhibit bandgap immunity to nanoribbon width downscaling. By studying FETs with MX<sub>2</sub>NR channel and EOT of  $1 \text{ nm}$ , we show that AC-NFETs have the lowest performance with  $I_{ON} < 1 \text{ mA}/\mu\text{m}$ , while AC-PFETs are the best-performing devices with  $I_{ON}$  of up to  $2.6 \text{ mA}/\mu\text{m}$ . On the other hand, ZZ-PFETs are relatively immune to  $W$  downscaling as  $I_{ON}$  decreases only slightly, whereas ZZ-NFETs exhibit a surprising  $I_{ON}$  increase of up to 70% when the channel width decreases to  $\sim 2 \text{ nm}$ . We report that the ON-state performance of all devices is directly proportional to the ON-state injection velocity and effective transport mass, with  $v_{inj}$  reaching  $\sim 2.1 \times 10^7 \text{ cm/s}$  and  $m_T$  being as low as  $0.14m_0$ . Finally, we show that FETs with Hf-based MX<sub>2</sub> ZZ nanoribbons, ZZ-ZrS<sub>2</sub>NRs with  $W < 3 \text{ nm}$  and ZZ-ZrSe<sub>2</sub>NRs with  $W < 6 \text{ nm}$ , meet the IRDS requirements for both NFET and PFET devices. In

contrast, for AC-MX<sub>2</sub>NRs only the p-channel devices meet the  $I_{ON}$  provision as stated in the IRDS. Our work presents the upper ballistic limits to the potential device performance on the nanoscale, whereas further work is needed on addressing the contact resistance and carrier scattering for a detailed assessment of MX<sub>2</sub>NR FETs. Nevertheless, our results demonstrate that certain Zr- and Hf-based MX<sub>2</sub> nanoribbons could serve as high-performing channel materials in future high-density and high-performance logic FETs based on multiple-nanowire/nanosheet architectures such as MBC FETs.

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#### AUTHOR DECLARATIONS

##### Conflict of Interest

The authors have no conflicts to disclose.



## Author Contributions

**Mislav Matić:** Conceptualization (equal); Data curation (equal); Formal analysis (equal); Methodology (equal); Software (equal); Writing – original draft (equal). **Mirko Poljak:** Funding acquisition (equal); Methodology (equal); Supervision (equal); Writing – review & editing (equal).

## DATA AVAILABILITY

The data that support the findings of this study are available within the article and from the corresponding author upon reasonable request.

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## **Publication 2**

# **Ballistic Performance of Quasi-One-Dimensional Hafnium Disulfide Field-Effect Transistors**

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Article

# Ballistic Performance of Quasi-One-Dimensional Hafnium Disulfide Field-Effect Transistors

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**Abstract:** Hafnium disulfide ( $\text{HfS}_2$ ) monolayer is one of the most promising two-dimensional (2D) materials for future nanoscale electronic devices, and patterning it into quasi-one-dimensional  $\text{HfS}_2$  nanoribbons ( $\text{HfS}_2\text{NRs}$ ) enables multi-channel architectures for field-effect transistors (FETs). Electronic, transport and ballistic device characteristics are studied for sub-7 nm-wide and ~15 nm-long zigzag  $\text{HfS}_2\text{NR}$  FETs using non-equilibrium Green's functions (NEGF) formalism with density functional theory (DFT) and maximally localized Wannier functions (MLWFs). We provide an in-depth analysis of quantum confinement effects on ON-state performance. We show that bandgap and hole transport mass are immune to downscaling effects, while the ON-state performance is boosted by up to 53% but only in n-type devices. Finally, we demonstrate that  $\text{HfS}_2\text{NR}$  FETs can fulfill the industry requirements for future technology nodes, which makes them a promising solution for FET architectures based on multiple nanosheets or nanowires.

**Keywords:** density functional theory (DFT); hafnium disulfide ( $\text{HfS}_2$ ); nanoribbon; non-equilibrium Green's function (NEGF); quantum transport; quasi-one-dimensional



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## 1. Introduction

Atomically thin two-dimensional (2D) materials (2DMs) have arisen as potential candidates for future transistor channel materials [1–3] since the discovery of graphene in 2004 [4]. The 2DMs exhibit near-ballistic transport properties and show potential for future high-performance electronic devices due to atomic thickness and dangling-bond-free surfaces [5]. Despite their promising characteristics, the 2DM devices are severely limited by the high contact resistance that degrades the device performance [6–8]. After graphene, more than 1800 2DMs have been predicted to be stable [9], and many of them have shown promise as channel material with transition metal dichalcogenides (TMDs), such as  $\text{MoS}_2$ ,  $\text{MoTe}_2$ ,  $\text{WS}_2$ ,  $\text{WSe}_2$ ,  $\text{SnS}_2$ , etc. [10–12], being among the most promising for future FETs. One hundred 2DMs were studied recently in [13] for future logic devices where monolayer hafnium disulfide ( $\text{HfS}_2$ ) is reported to be one of the best-performing 2DMs for future ultra-scaled FETs due to a combination of electronic and transport properties such as low effective mass and high injection velocity that result in high ON-state current for both n- and p-FETs. The electronic, transport, and device properties of 2D  $\text{HfS}_2$  were studied in detail in [13–15] by advanced theoretical calculations, whereas experimental work on few-layer  $\text{HfS}_2$  FETs was reported in [16,17] where integration compatibility of monolayer  $\text{HfS}_2$  with  $\text{HfO}_2$  high- $k$  dielectric was emphasized as one of the biggest strengths of realization of devices with  $\text{HfS}_2$ .

With current state-of-the-art multi-bridge channel (MBC) FETs with silicon nanosheets or nanowires gaining momentum in the industry, 2DMs patterned into quasi-one-dimensional (quasi-1D) structures such as nanoribbons could replace silicon and extend Moore's law by offering higher integration density [18–20]. Additionally, quantum confinement effects provide avenues for tuning the material properties, which could benefit the performance of

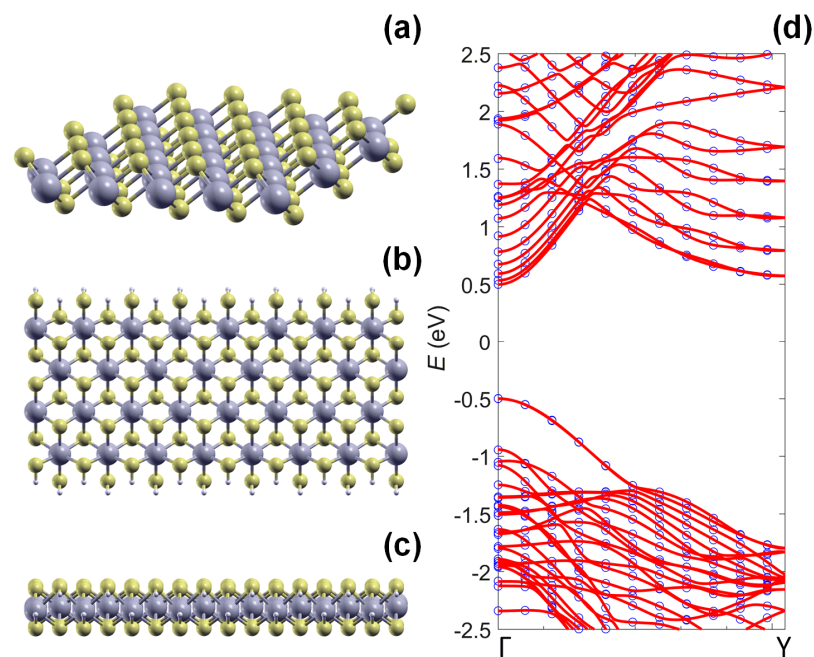
such electronic nanodevices. Recently, various nanoribbons with ultimately downscaled widths were experimentally reported, including graphene nanoribbons (GNRs) [21,22] and phosphorene nanoribbons (PNRs) [23,24], which affirms the possibility of constructing MBC FETs, at least in principle, with quasi-1D 2DM nanostructures. Therefore, given the promising performance of 2D HfS<sub>2</sub> FETs, it is imperative to systematically explore the electronic, transport, and device properties of quasi-1D nanoribbons of HfS<sub>2</sub> (HfS<sub>2</sub>NRs) about which nothing is currently known in the literature.

In this paper, we present an ab initio study on HfS<sub>2</sub>NRs using density functional theory (DFT) to obtain the electronic structure, and maximally localized Wannier functions (MLWFs) to transform DFT Hamiltonians into localized basis suitable for quantum transport simulation. The MLWF Hamiltonians are then coupled to our in-house non-equilibrium Green's function (NEGF)-based quantum transport [25,26] solver to obtain the relevant properties of HfS<sub>2</sub>NRs and HfS<sub>2</sub>NR FETs. Most importantly, we report the degradation of pFET performance while scaling down the nanoribbon width; however, the driving current in HfS<sub>2</sub>NR nFETs is surprisingly boosted in ~2 nm-wide transistors by the quantum confinement effects. These findings are further explained by investigating the bandgap, density of states and carriers, current density, and injection velocity. Finally, we compare HfS<sub>2</sub>NR n- and p-type FETs to other 2DMs and to the requirements set in the International Roadmap for Devices and Systems (IRDS). We show that both n- and p-type HfS<sub>2</sub>NR FETs with nanoribbon widths in the range from ≈2 nm to ≈5 nm can fulfil the goals set for future logic devices.

## 2. Methods

The unit cell of monolayer HfS<sub>2</sub> (Figure 1a) is obtained from the Materials Cloud [27] and scaled to construct the supercells of zigzag HfS<sub>2</sub> nanoribbons with hydrogen-passivated edges. The nanoribbon structure from the top and side views is shown in Figures 1b and 1c, respectively. The zigzag direction exhibits the highest curvature of the dominant subbands in the valence and conduction bands, which hints at excellent carrier transport in these devices. The HfS<sub>2</sub>NR supercells are constructed with respect to the number of HfS<sub>2</sub> unit cells repeated along the nanoribbon width ( $W$ ). This number ranges from 2 to 10 unit cells, which corresponds to  $W$  from 1.36 nm to 6.39 nm. After defining the initial structure, we employ an ab initio plane-wave DFT, implemented in the Quantum Espresso (QE) program package (v.6.8) [28], to relax the nanoribbon structure and obtain the Hamiltonians. A 20 Å vacuum is added in confined directions to exclude any interactions between layers. The DFT calculations use Perdew–Burke–Ernzerhof generalized gradient approximation (PBE-GGA) [29] as the exchange–correlation functional with plane augmented wave (PAW) pseudopotentials. The Brillouin zone is sampled with  $1 \times 15 \times 1$  Monkhorst–Pack  $k$ -point grid [30] where 15  $k$ -points are in transport direction, and the cutoff energy is set to 1360 eV. Convergence thresholds for ionic forces are fixed to  $10^{-3}$  eV/Å, while  $10^{-4}$  eV is used for total energy.

Energy-localized plane-wave Hamiltonians from QE are then converted into a space-localized basis using MLWFs [31] implemented in the Wannier90 (v.3.1.0) program package [32,33]. The main input into the Wannier90 tool are the trial orbitals that are used for Wannier transformation, and here we use  $d$  orbitals for Hf atoms and  $p$  orbitals for S atoms. The band structure calculated with MLWF and DFT Hamiltonians shows good agreement in the relevant energy region around the bandgap, as seen in Figure 1d that reports the dispersion of the 3.25 nm wide HfS<sub>2</sub>NR. Finally, the supercell MLWF Hamiltonian matrices are upscaled to construct the total HfS<sub>2</sub>NR Hamiltonian, where the ~15 nm-long nanoribbon represents the channel of the HfS<sub>2</sub>NR FET.



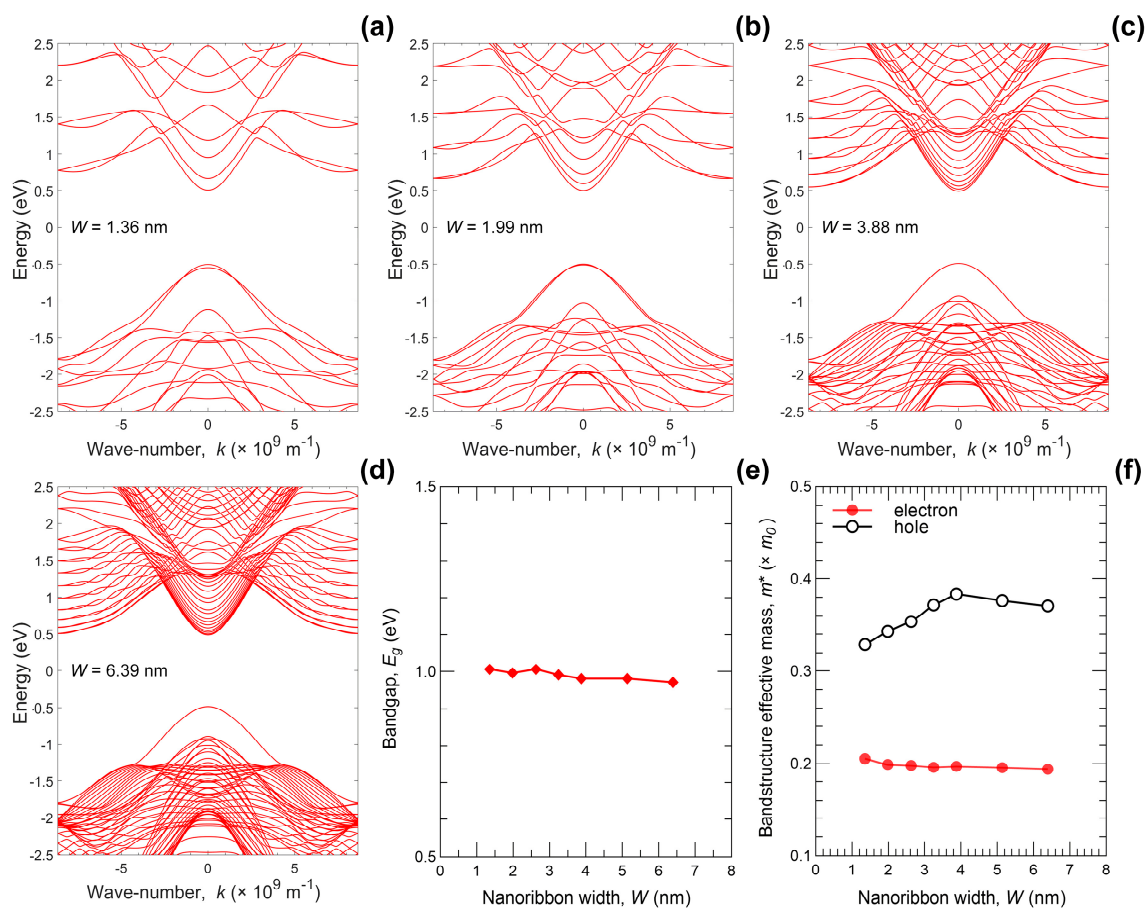
**Figure 1.** Illustration of (a) HfS<sub>2</sub> monolayer. (b) Top and (c) side view of the monolayer HfS<sub>2</sub> nanoribbon with zigzag edges. (d) Band structure obtained from DFT (blue dots) and MLWF (red lines).

Being primarily interested in the ON-state performance, we use the top-of-the-barrier (ToB) ballistic FET model [34] to simulate single gate n- and p-type FETs with HfS<sub>2</sub>NR channel. Within the ToB model, only the thermionic current is calculated, which is reasonable because the assumed 15 nm long channel is long enough for negligible tunnelling. The main inputs of the ToB FET model are transmission and density of states (DOS) calculated using the NEGF formalism implemented in our in-house code [35,36]. Within NEGF, the channel is described with the total HfS<sub>2</sub>NR Hamiltonian and source/drain (S/D) contacts are described with S/D self-energy matrices calculated using the numerically efficient Sancho–Rubio method [37,38]. The n- and p-type FETs with zigzag HfS<sub>2</sub>NR channels are simulated with ideal electrostatic control by the gate, resulting in a perfect subthreshold slope, equivalent oxide thickness (EOT) of 1 nm, S/D doping set at 0.01 areal molar fraction or  $\approx 2.7 \times 10^{13} \text{ cm}^{-2}$ , and supply voltage ( $V_{DD}$ ) set to 0.7 V. To provide a meaningful comparison between various HfS<sub>2</sub>NR devices, simulations are performed with a common OFF-state current ( $I_{OFF}$ ) set to 10 nA/ $\mu\text{m}$  as defined by IRDS for high performance (HP) devices [39]. The setting of  $I_{OFF}$  is performed by adjusting the gate work function for each device automatically within our code. The ballistic ON-state current ( $I_{ON}$ ) and the ON-state charge density at ToB are extracted when both gate and drain are biased at the supply voltage. Finally, we set EOT to 0.6 nm and compare  $I_{ON}$  and injection velocity to our previous work on GeS nanoribbon devices, in addition to one hundred 2DMs reported in [13].

### 3. Results and Discussion

Band structure of HfS<sub>2</sub>NRs with various widths is reported in Figure 2a–d. All HfS<sub>2</sub>NRs exhibit a direct bandgap at the  $\Gamma$  point and we observe an immunity of bandgap ( $E_g$ ) to width scaling. The bandgap keeps a constant value of  $\approx 1$  eV in all nanoribbons, as reported in Figure 2e, which is slightly smaller than the 1.3 eV reported in [13] for the HfS<sub>2</sub> monolayer. As  $W$  is scaled down, the conduction band (CB) exhibits fewer bands near the CB minimum (CBM), while the dominant subband qualitatively remains the same. On the other hand, two degenerate subbands are visible in the valence band (VB) of wide HfS<sub>2</sub>NRs with  $W > 4$  nm, and this degeneracy is broken in narrower nanoribbons

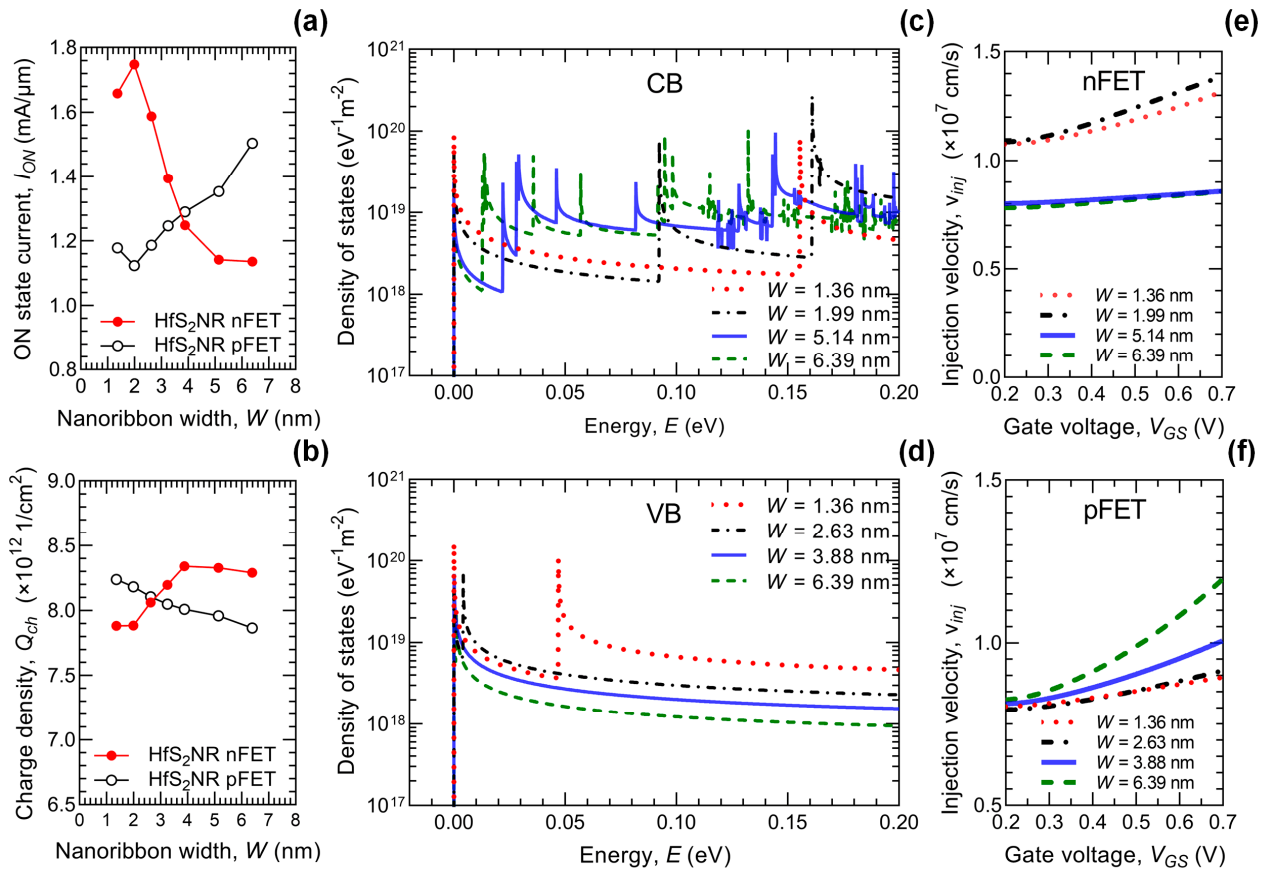
due to strong quantum confinement effect. Namely, two-hole subbands separate and this separation increases with  $W$  downscaling, which is followed by an increase in the curvature of the second subband near the VB maximum (VBM). To further investigate the quantum confinement effects on the band structure of all HfS<sub>2</sub>NR widths, we extract the electron and hole-band structure effective mass of the dominant subband, closest to the CBM or VBM, from the band structure by fitting its curvature with a parabolic approximation (Figure 2f). Electron effective mass ( $m_e^*$ ) is immune to scaling with  $m_e^* \approx 0.2m_0$  for all nanoribbon widths. In contrast, hole effective mass ( $m_h^*$ ) experiences a significant width-scaling effect. Namely,  $m_h^*$  is  $\approx 0.37m_0$  for HfS<sub>2</sub>NRs with  $W \geq 3.25$  nm; while scaling down the width linearly decreases  $m_h^*$  to  $0.33m_0$  when  $W = 1.36$  nm. Considering only the observed differences in CB and VB, where the  $m_h^*$  of the dominant (highest) subband is at least  $1.6 \times$  lower than the  $m_e^*$  for all observed HfS<sub>2</sub>NRs, we expect a considerable difference in the performance of n- and p-FETs with HfS<sub>2</sub>NR channels. However, this metric does not take into account degeneracy in VB or the higher number of subbands near CBM in wider nanoribbons.



**Figure 2.** Band structure of zigzag HfS<sub>2</sub>NRs with the widths of (a) 1.36 nm, (b) 1.99 nm, (c) 3.88 nm and (d) 6.39 nm. (e) Impact of nanoribbon width-scaling on the bandgap of zigzag HfS<sub>2</sub>NRs. (f) Electron and hole band structure effective mass dependence on nanoribbon width. Effective masses are extracted for the lowest (highest) subband in the CB (VB).

To assess the performance of n- and p-type HfS<sub>2</sub>NR FETs in Figure 3a, we plot the nanoribbon width dependence of the width-normalized ON-state current. The HfS<sub>2</sub>NR pFETs exhibit a monotonic  $I_{ON}$  decrease from 1.5 mA/ $\mu\text{m}$  to 1.12 mA/ $\mu\text{m}$  when the width is downscaled. The only exception is the narrowest pFET that shows a slight  $I_{ON}$  increase to 1.18 mA/ $\mu\text{m}$ . On the other hand, for HfS<sub>2</sub>NR nFETs, we surprisingly observe a generally monotonic increase of  $I_{ON}$  when HfS<sub>2</sub>NR width decreases. The ON-state performance is enhanced from 1.14 mA/ $\mu\text{m}$  to 1.74 mA/ $\mu\text{m}$  when the width is downscaled from 6.39 nm

to 1.99 nm, whereas the narrowest nanoribbon with  $W = 1.36$  nm exhibits a slight decrease of  $I_{ON}$  to 1.66 mA/ $\mu\text{m}$ . Therefore, quantum confinement effects induce a current boosting of 53% for nFETs with the  $\approx 2$  nm wide HfS<sub>2</sub>NR channel. Since the performance of HfS<sub>2</sub>NR FETs shows no correlation to the band structure effective mass, in the following paragraphs, we explore the features of charge density, density of states, and carrier injection velocity.



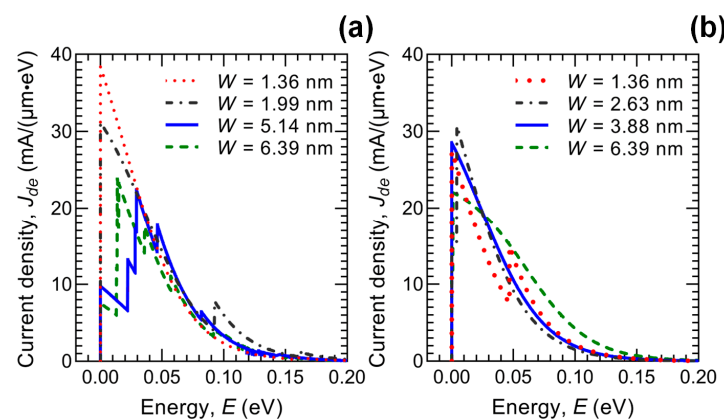
**Figure 3.** (a) ON-state current and (b) charge density at ToB width dependence in n- and p-type zigzag HfS<sub>2</sub>NR FETs.  $I_{ON}$  and  $Q_{ch}$  are extracted at  $V_{GS} = V_{DS} = V_{DD} = 0.7$  V with a common  $I_{OFF} = 10$  nA for all devices. Comparison of DOS in (c) conduction and (d) valence band of HfS<sub>2</sub>NR FETs. All DOS and transmission plots are shifted so that the CBM and VBM are positioned at 0 eV. Dependence of injection velocity on gate voltage in (e) n-type and (f) p-type zigzag HfS<sub>2</sub>NR FETs for various nanoribbon widths.

Charge density at the top-of-the-barrier extracted in the ON-state ( $Q_{CH}$ ) for various HfS<sub>2</sub>NR widths is plotted in Figure 3b. For HfS<sub>2</sub>NR nFETs, we report  $Q_{CH} \approx 8.3 \times 10^{12}$  cm<sup>-2</sup> for  $W \geq 3.88$  nm, while scaling down decreases  $Q_{CH}$  to  $7.88 \times 10^{12}$  cm<sup>-2</sup> in the 1.36 nm wide device. On the other hand, in pFETs, charge density increases monotonically from  $Q_{CH} = 7.87 \times 10^{12}$  cm<sup>-2</sup> for  $W = 6.39$  nm to  $Q_{CH} = 8.24 \times 10^{12}$  cm<sup>-2</sup> for  $W = 1.36$  nm. Charge density at the top-of-the-barrier depends on DOS near the CBM or VBM. Therefore, we plot DOS near the CBM (VBM) for various HfS<sub>2</sub>NR widths in Figure 3c,d. The HfS<sub>2</sub>NR nFETs exhibit a dense DOS with a high number of Van Hove singularities (VHS) near the CBM. Scaling down, HfS<sub>2</sub>NR width reduces the number of available bands in the CB, decreases the overall DOS in the 100 meV window, and, therefore, lowers the charge density in narrower HfS<sub>2</sub>NRs. However, VB DOS that is relevant for HfS<sub>2</sub>NR pFETs shows an increase from a single VHS to two VHSs near the VBM due to band separation of the two dominant subbands (see Figure 2a) which increases the DOS near the VBM and  $Q_{CH}$  when nanoribbon width is scaled down.



Since the trends in  $I_{ON}$  and  $Q_{CH}$  behavior, reported in Figure 3a,b, are qualitatively opposite, the only reasonable explanation for  $I_{ON}$  trends should be found in the carrier transport properties, i.e., injection velocity. Injection velocity ( $v_{inj}$ ) represents the average carrier velocity at the top-of-the-barrier under the ballistic limit and it is shown in Figure 3e,f for n- and p-type HfS<sub>2</sub>NR FETs, i.e., electrons and holes, respectively. The plots report a gate voltage ( $V_{GS}$ ) dependence of  $v_{inj}$  in the range from the threshold voltage ( $V_{GS} \approx 0.2$  V) to the supply voltage ( $V_{GS} = 0.7$  V). The nFETs with  $W \geq 5.14$  nm show almost no modulation by  $V_{GS}$  with electron  $v_{inj}$  being  $\approx 0.8 \times 10^7$  cm/s. In contrast,  $v_{inj}$  increases with increasing bias in the 1.36 nm and 1.99 nm wide HfS<sub>2</sub>NR nFETs. These two devices exhibit similar  $v_{inj}$  at the threshold voltage; however, HfS<sub>2</sub>NR nFETs with  $W = 1.99$  nm exhibit a stronger bias modulation and a higher maximum electron  $v_{inj}$  of  $1.39 \times 10^7$  cm/s. The best observed  $v_{inj}$  coincides with the best reported  $I_{ON}$  in nFETs for the 1.99 nm wide HfS<sub>2</sub>NR nFET. We attribute the optimum performance and highest electron  $v_{inj}$  for  $W \approx 2$  nm to the band structure evolution, especially to the second CB subband visible in Figure 2b. Namely, for this nanoribbon, the subband crowding is not as dense as for wider HfS<sub>2</sub>NRs, which means that higher subbands with heavier carriers do not contribute significantly to the current-carrying process. As for pFETs, hole  $v_{inj}$  at the threshold equals  $\approx 0.8 \times 10^7$  cm/s for all HfS<sub>2</sub>NR pFETs. Scaling down, HfS<sub>2</sub>NR width decreases the strength of  $V_{GS}$  modulation of the hole  $v_{inj}$ , and devices with  $W \leq 2.63$  nm show almost no bias modulation. The widest observed HfS<sub>2</sub>NR ( $W = 6.39$  nm) shows a 49% increase of hole  $v_{inj}$  to  $1.2 \times 10^7$  cm/s in the ON-state. As the width is downscaled, the hole  $v_{inj}$  decreases monotonically, which agrees with the  $I_{ON}$  behavior reported in Figure 3a.

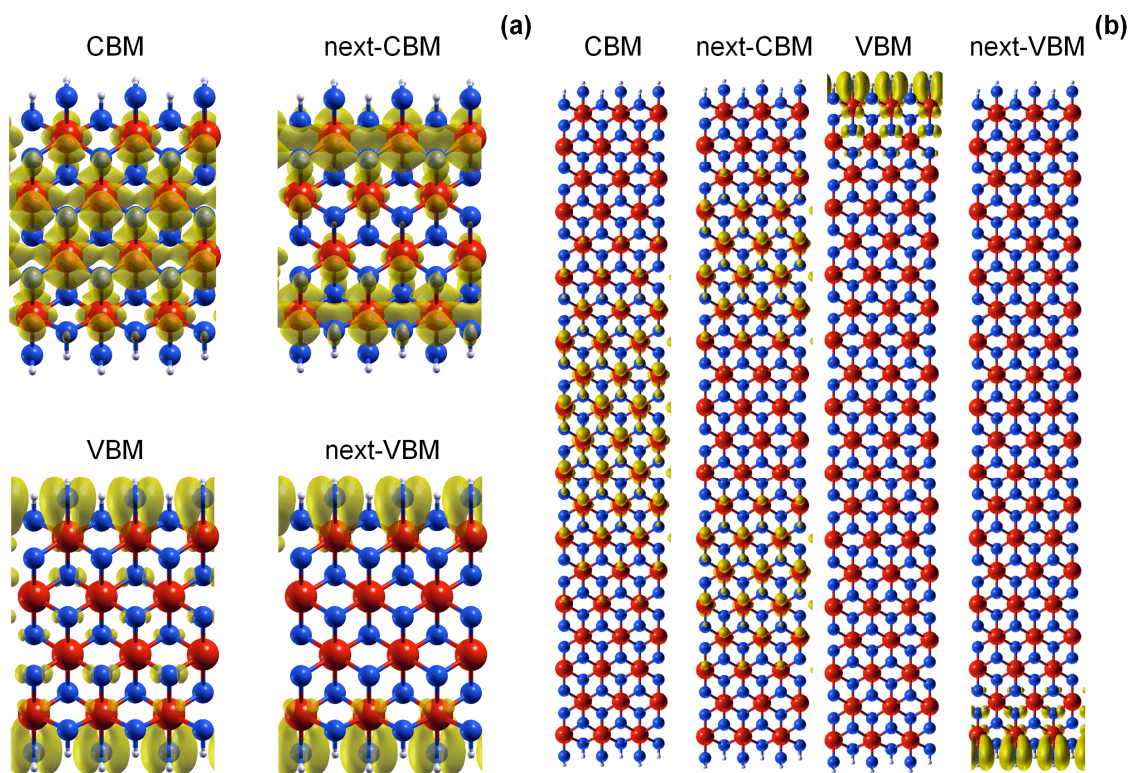
We further explore the current and transport properties in ultra-scaled HfS<sub>2</sub>NR nanodevices by analyzing the current energy density ( $J_{de}$ ) in the ON-state. The  $J_{de}$  results are shown for n- and pFETs in Figures 4a and 4b, respectively. In all devices, the current is mainly contained in the energy window up to  $\approx 100$  meV from the CBM/VBM. The nFETs exhibit  $J_{de}$  maximum at the CBM for the narrowest HfS<sub>2</sub>NR, but wider HfS<sub>2</sub>NRs exhibit a slight shift of the maximum by 20–30 meV, due to the higher number of occupied subbands. Namely, setting a common  $I_{OFF}$  for all devices results in different S/D Fermi levels ( $E_F$ ) depending on device width, with a greater  $E_F$  shift upward generally observed for wider HfS<sub>2</sub>NRs. Consequently, there are more current-carrying subbands, and the current density at the CBM is lower in wider HfS<sub>2</sub>NR nFETs. The 1.36 nm wide HfS<sub>2</sub>NR shows maximum current density near the CBM, with only a single dominant subband. In contrast, for  $W = 1.99$  nm, the second subband carries current as well, with the second-subband current density surpassing that of the first subband above CBM + 90 meV, which leads to the maximum  $I_{ON}$  for the 2 nm wide device among all the studied HfS<sub>2</sub>NR nFETs.



**Figure 4.** Current energy density at ToB in the ON-state for HfS<sub>2</sub>NR (a) n-type and (b) p-type FETs with different nanoribbon channel widths.

In addition to the current density, band decomposed charge density (BDCD) of nanoribbons with the widths of 1.36 nm and 6.39 nm is plotted in Figures 5a and 5b, respectively.

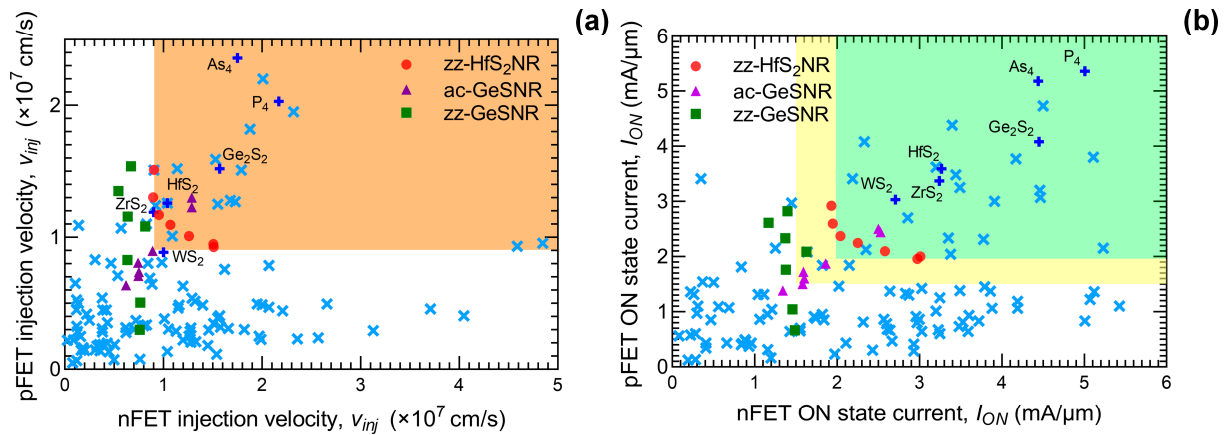
The BDCD is shown for subbands at the CBM/VBM, along with the nearest next subbands that are denoted as next-CBM/next-VBM. Figure 5a shows that the electron current in the narrowest nanoribbon, mainly determined by the first CB subband (see Figure 4a), is distributed almost through the whole nanoribbon width, except for edge S atoms. On the other hand, electron current in the widest HfS<sub>2</sub>NR is mostly determined by the next-CBM subband (see Figure 4a), so that the current flows away from the edges and somewhat through the middle, as shown in Figure 5b. As for HfS<sub>2</sub>NR pFETs with current density reported in Figure 4b,  $J_{de}$  is localized near the VBM due to the dominant first subband in the VB with a considerable contribution of the second subband in some devices. The lowest two VB subbands are slightly separated, i.e., degeneracy is broken, only in the narrowest HfS<sub>2</sub>NR (see Figure 2a), and this split results in lower transmission probability near the VBM and, therefore, lower  $J_{de}$  in pFETs with the narrowest 1.36 nm wide channel. As shown in the BDCD plots in Figure 5a,b, now addressing the situation for the VBM subband, we observe that the hole current is expected to flow exclusively along nanoribbon edges. Furthermore, for wide HfS<sub>2</sub>NRs where two degenerate subbands are dominant near the VBM, we observe that the current flows through separate edges in VBM and next-VBM, as seen in Figure 5b, due to zero overlap between the edges. Scaling down the nanoribbon width decreases the distance between the edges, which increases the overlap of the edge states and, therefore, causes the separation of degenerate subbands near the VBM, as seen in Figure 2. Increasing the current by increasing the width would be limited due to edge transport; hence, the narrowest HfS<sub>2</sub>NR pFETs exhibit a decreasing drive current (Figure 3a) due to higher DOS in S/D regions and related  $E_F$  downshift.



**Figure 5.** Band-decomposed charge density of CBM, next-CBM, VBM and next-VBM subbands of (a) 1.39 nm and (b) 6.39 nm wide HfS<sub>2</sub>NRs. Isovalue is set at 0.001 q/bohr<sup>3</sup>.

Finally, we compare the ON-state performance of HfS<sub>2</sub>NR FETs with one hundred 2DMs analyzed in [13], to the armchair and zigzag GeSNRs from our previous work [36,40], and to the IRDS requirements for future logic nodes [39]. For a proper comparison with the literature data, we set the EOT to 0.6 nm (HfO<sub>2</sub> with  $\epsilon_r = 20$ ,  $t_{ox} = 3$  nm) as in [13]. The injection velocity in the ON-state for nFET and pFETs is shown in Figure 6a. All HfS<sub>2</sub>NR

n- and pFETs exhibit  $v_{inj}$  close to, or higher, than the IRDS requirement ( $0.9 \times 10^7$  cm/s), while achieving comparable  $v_{inj}$  values to those in 2D HfS<sub>2</sub> along the zigzag direction. Furthermore, only a few other large-area 2D materials such as Ge<sub>2</sub>S<sub>2</sub>, As<sub>4</sub> and P<sub>4</sub> exhibit higher  $v_{inj}$  compared to HfS<sub>2</sub>NRs. This is noteworthy because HfS<sub>2</sub>NRs are quasi-1D nanostructures with additional quantum confinement in comparison to 2DMs that are infinite 2D sheets.



**Figure 6.** (a) nFET vs. pFET ON-state injection velocity with orange area denoting injection velocity higher than  $0.9 \times 10^7$  cm/s set by IRDS 2022 for future logic nodes. (b) nFET vs. pFET ON-state current with a green area representing IRDS 2021 maximum  $I_{ON}$  requirement with  $I_{ON} = 1.979$  mA/ $\mu$ m, and a yellow area representing the minimum  $I_{ON}$  requirement for future logic devices with  $I_{ON} = 1.504$  mA/ $\mu$ m. The 100 2DMs reported in [13] are included in graphs with the most relevant materials named directly and denoted with blue plus signs, while the unnamed 2DMs are presented with light blue crosses.

The ON-state current is compared in Figure 6b again for HfS<sub>2</sub>NR FETs from this work and one hundred 2DMs reported in [13]. We compare the data against IRDS 2021 [41] because the IRDS 2022 version, which we have used for all previous comparisons, does not provide  $I_{ON}$  requirements with zero series or contact resistance. We observe that HfS<sub>2</sub>NR FETs exhibit a relatively high  $I_{ON}$  and all devices meet the minimum IRDS  $I_{ON}$  for both nFET and pFET devices. On the other hand, the maximum IRDS  $I_{ON}$  specification is met only by HfS<sub>2</sub>NR FETs with  $W$  in the range from 1.99 nm to 5.14 nm. The remaining HfS<sub>2</sub>NR FETs are close but are nevertheless beyond the edges of the acceptable  $I_{ON}$  window. Compared to the armchair and zigzag GeSNRs, only armchair GeSNRs with  $W > 3$  nm show better  $I_{ON}$  performance than HfS<sub>2</sub>NR devices in both n- and p-FET configurations. Finally, in comparison to 2D HfS<sub>2</sub> and other 2D materials such as WS<sub>2</sub>, ZrS<sub>2</sub>, Ge<sub>2</sub>S<sub>2</sub>, arsenene and phosphorene, all HfS<sub>2</sub>NR FETs perform relatively poorly. Nevertheless, we stress that HfS<sub>2</sub>NRs are quasi-1D nanostructures with strong quantum confinement effects along the width, so a direct comparison to 2D monolayers is not completely fair.

The usage of zigzag HfS<sub>2</sub>NR for future FET architectures based on multiple parallel nanosheets or nanowires is plausible, given their fulfilment of the IRDS requirements for the ON-state current and injection velocity and, moreover, given the possibility of a matched performance of n- and p-channel devices. Although several mono-elemental 2D materials and TMDs outperform hafnium disulphide nanoribbon devices, the HfS<sub>2</sub>NR FETs still outperform most of the previously studied 2DMs when both n- and p-FET devices and their performance are considered. Meeting the IRDS requirements for the ON-state current is obtained here for the ideal single-gate FET structure, whereas the usage of multi-channel architectures such as MBC FETs could provide opportunities for further improvements in performance. Additionally, we note that this study deals with purely ballistic devices so only the upper ballistic performance limits are explored in this work, while taking into account realistic effects like carrier scattering in quasi-ballistic transport and contact

resistance would deteriorate the reported HfS<sub>2</sub>NR FET performance. While investigating the impact of these issues is important, it is also out of the scope of the current manuscript and will be addressed in future work. Nevertheless, the potential of using ultra-scaled HfS<sub>2</sub>NRs as a channel material in future logic devices is evident.

#### 4. Conclusions

We present a comprehensive study on the electronic, transport and ballistic device characteristics for HfS<sub>2</sub> nanoribbons with a length of 15 nm and widths under 7 nm. We show that HfS<sub>2</sub>NRs and HfS<sub>2</sub>NR FETs exhibit promising transport properties and ON-state performance combined with an immunity of bandgap to nanoribbon width downscaling. Moreover, an unexpected and significant  $I_{ON}$  increase of up to 53% is observed in n-type FETs with HfS<sub>2</sub>NR width of  $\approx 2$  nm. Concerning the industry goals for future technology nodes, we demonstrate that HfS<sub>2</sub>NR FETs with nanoribbon widths in the range from 1.99 nm to 5.14 nm meet all IRDS requirements when EOT is set to 0.6 nm. Therefore, just like 2D HfS<sub>2</sub>, quasi-1D nanostructures of monolayer HfS<sub>2</sub> present a promising candidate material system for ultra-scaled logic devices, especially for multi-channel nanosheet or nanowire nFETs, in which the  $\sim 2$  nm wide HfS<sub>2</sub>NRs could provide a significant performance boost due to the strong quantum confinement effect on the band structure.

**Author Contributions:** Conceptualization, M.M. and M.P.; methodology, M.M.; software, M.M.; validation, M.M. and M.P.; formal analysis, M.M. and M.P.; investigation, M.M.; resources, M.P.; data curation, M.M.; writing—original draft preparation, M.M.; writing—review and editing, M.P.; visualization, M.M.; supervision, M.P.; project administration, M.P.; funding acquisition, M.P. All authors have read and agreed to the published version of the manuscript.

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**Data Availability Statement:** The data that support the findings of this study are available from the corresponding author, M.P., upon reasonable request.

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## **Publication 3**

### **Electronic, transport and ballistic device properties of quasi-one-dimensional GeS**

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# Electronic, transport and ballistic device properties of quasi-one-dimensional GeS

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## Abstract

Monolayer germanium monosulfide (GeS) is among the most promising two-dimensional (2D) materials for applications in electron devices at the nanoscale. Quasi-one-dimensional GeS nanoribbons (GeSNRs) allow a high-density integration and provide an additional avenue for tuning the material and device properties. In this work we study electronic, transport and ballistic device characteristics of sub-5 nm-wide and ~ 15 nm-long armchair and zigzag GeSNRs using quantum transport simulations based on Green's functions, and atomically and orbitally resolved Hamiltonians obtained with density functional theory that are transformed using maximally localized Wannier functions. The evolution of bandstructure, effective mass, charge density, injection velocity, and ON-state drain current ( $I_{ON}$ ) of GeSNRs and GeSNR-based field-effect transistors (FETs) are studied with respect to GeSNR width downscaling. We show that GeSNRs and GeSNR FETs experience strikingly different consequences of scaling and confinement depending on carrier type and edge configuration, with e.g.  $I_{ON}$  behavior including monotonic decrease (n- and p-type FETs with armchair GeSNRs), nearly no change (nFETs with zigzag GeSNR), and appearance of local minima and maxima (pFETs with zigzag GeSNR channels). By comparing device performance to specifications set by a technology roadmap, we demonstrate that certain GeSNR FETs can fulfil the requirements and, moreover, we provide the ranges of acceptable nanoribbon widths and equivalent oxide thickness values depending on channel type and edge configuration.

**Keywords** Quantum transport · Non-equilibrium Green's function (NEGF) · Density functional theory (DFT) · Maximally-localized Wannier functions (MLWF) · Germanium monosulfide (GeS) · Nanoribbon · Quasi-one-dimensional

## 1 Introduction

The tremendous growth of the semiconductor industry over the past 60 years has been driven by the miniaturization and optimization of transistors. Due to the challenges to suppress short channel effects (SCEs) at gate lengths below 20 nm, new materials and device architectures are needed to enable further transistor scaling and enhance device performance. Since the discovery of graphene in 2004 [1], atomically-thin two-dimensional (2D) materials (2DMs) arose as potential candidates for future transistor channel materials [2–4]. With projected sub-15 nm channel lengths in future FETs in combination with atomic thickness and dangling-bond-free

surfaces [5], 2DMs can exhibit near-ballistic transport properties that can be utilized for high-performance electron devices. Nevertheless, high contact resistance is still an obstacle to their use in nanodevices [6–8]. Recently, hundreds of 2DMs were studied in detail in [9], and monolayer germanium monosulfide (GeS) was identified as one of the most promising 2DMs for ultra-scaled FETs. The 2D GeS is a member of monolayer group IV-VI monochalcogenides, MXs ( $M \in \{\text{Ge}, \text{Si}, \text{Sn}\}$  and  $X \in \{\text{S}, \text{Se}\}$ ) with phosphorene-like buckled orthorhombic lattice which indicates anisotropic transport [10]. As other 2DMs, the 2D GeS can in principle be patterned into quasi-one-dimensional (quasi-1D) nanoribbons, which enables an additional way of tuning of electronic, transport and device properties that include e.g. bandgap, effective mass, injection velocity, etc. [11–14].

A recent quantum transport study of sub-10 nm monolayer GeS FETs [15] showed great potential of GeS as a material for future short-channel transistors. However, very little is known about quasi-1D GeS nanoribbon (GeSNR)

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devices, with the information being limited to electronic bandstructure [16] and some transport and n-channel transistor (nFET) properties for GeSNRs with armchair edges (ac-GeSNR) from our previous work [17]. Electronic properties of armchair and zigzag GeSNRs with bare and H-terminated edges were studied in [16]. This study demonstrated a high dependence of electronic properties on edge termination as zigzag GeSNRs (zz-GeSNR) with bare edges show metallic properties while all bare-edge ac-GeSNRs exhibit semiconducting behavior. On the other hand, termination by H atoms is presented as a good option to stabilize the ac- and zz-GeSNRs that exhibit semiconducting behavior. In the literature, there is currently no information about the scaling effects on the performance of ac-GeSNR p-channel transistors (pFETs) and zz-GeSNR-based FETs for both carrier types, i.e. zz-GeSNR nFET and pFET. Therefore, in this work we study in detail the electronic and transport properties, and ballistic device performance of ultra-scaled GeS nanodevices down to the 1D structure limit.

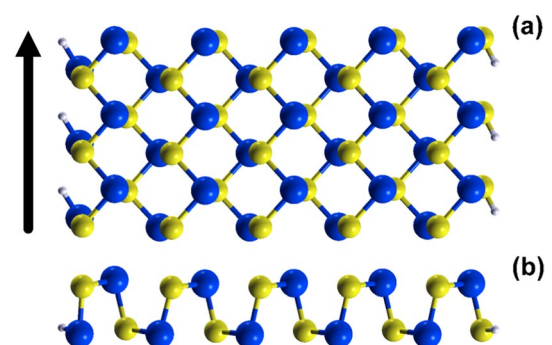
In order to properly account for the atomistic resolution and strong quantum effects in nanodevices, advanced modeling is necessary for the simulation of materials and FETs at the nanoscale [18, 19]. Ab initio density functional theory (DFT) is used in this study to calculate the electronic structure, and maximally-localized Wannier functions (MLWFs) are used to convert DFT Hamiltonians into a localized basis, preserving the precision of the bandstructure and enabling transport calculations for realistically-sized devices. Afterward, ballistic quantum transport simulations are then performed using the non-equilibrium Green's function (NEGF) formalism, which includes the MLWF Hamiltonians. The GeSNR FETs are analyzed using our in-house DFT-MLWF-NEGF solver that is described in [20]. We demonstrate strong bandstructure effects that occur in GeSNRs when their width is downscaled from  $\sim 4.2$ – $0.7$  nm, with considerable impact on bandgap, electron and hole effective masses, transmission, charge densities and carrier injection velocities. Finally, we show that scaling down the equivalent oxide thickness (EOT) enables various ac- and zz-GeSNR FETs to meet the requirements of the International Roadmap for Devices and Systems (IRDS) for logic technology beyond the "3 nm" node [21].

## 2 Methodology

We start by obtaining the Hamiltonian of the GeSNR using ab initio plane-wave DFT and transforming the DFT Hamiltonian into a localized basis using the MLWFs [9, 22]. The GeSNR FET structure is then simulated using several results obtained by NEGF simulations that are fed into the top-of-the-barrier (ToB) model to obtain ballistic performance of n- and p-type GeSNR FETs with armchair and zigzag edges.

The GeS nanoribbon super-cell is constructed from the 2D GeS unit cell (obtained from Materials Cloud [23]) that is repeated along the nanoribbon width 2–10 times, which translates to nanoribbon widths ( $W$ ) from 0.76 to 3.70 nm for ac-GeSNRs and from 0.67 to 4.18 nm for zz-GeSNRs. Hydrogen atoms are used to passivate the edges of the nanoribbons. After constructing the super-cell, Quantum Espresso (QE) program package [24] is used to perform DFT calculations that include relaxation and electronic structure calculations. Since DFT assumes a periodic structure in all three directions, a vacuum layer of 20 Å is added to exclude any interactions in confined directions. Generalized gradient approximation parameterized by Perdew-Burke-Ernzerhof (PBE-GGA) [25] is used as the exchange–correlation functional in the simulations due to good evaluation of bandstructure, with a downside of underestimating the bandgap. In DFT simulations the cut-off energy is set to at least  $1.5 \times$  the suggested minimum cut-off provided in pseudopotential file for each element, i.e. 1360 eV in this study. Convergence threshold is set to  $10^{-3}$  eV/Å for the ionic forces, and to  $10^{-4}$  eV for the total energy. A 15-point equally-spaced Monkhorst–Pack grid [26] is used to sample the  $k$ -space in the transport direction with single point in the confined directions. Figure 1 shows a zz-GeSNR structure relaxed using DFT, with a top view in Fig. 1a and a side view in Fig. 1b, and we observe a slight shift of the edge atoms for both Ge and S atoms.

Due to the plane-wave basis of DFT in QE, output DFT Hamiltonians are localized in energy, but for NEGF calculations a spatially-localized basis is desired. Transformation of DFT Hamiltonians into spatially-localized basis is done using maximally-localized Wannier functions (MLWFs) [27], which results in much sparser tight-binding like matrices. The process of obtaining MLWF based Hamiltonians is implemented in Wannier90 program package [28–30]. The main component for the wannierization process are trial orbitals that are projected onto the Bloch manifold where localization in real space is linked to smoothness

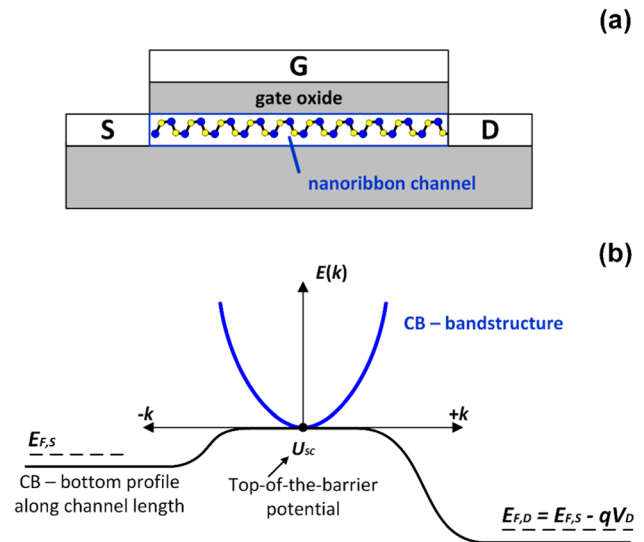


**Fig. 1** **a** Top and **b** side view of the monolayer GeS nanoribbon with zigzag edges. Transport direction is designated with an arrow

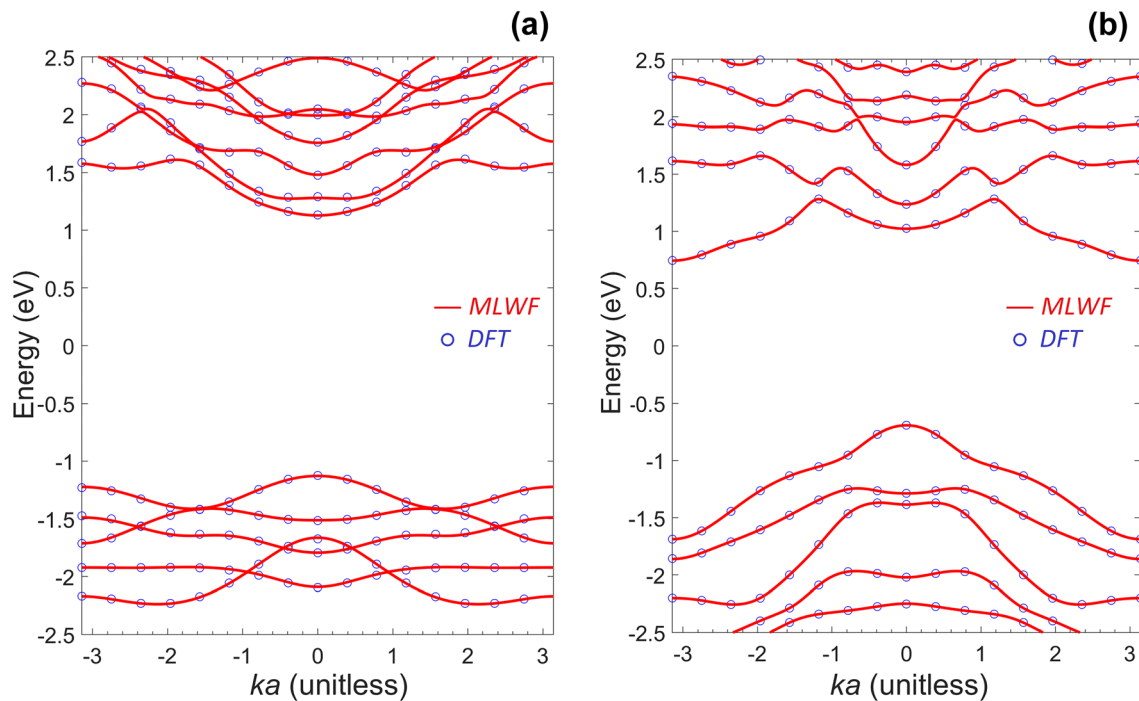
in reciprocal Bloch space. Atomic orbitals are smooth in reciprocal space and are used as trial orbitals in this work. For ac-GeSNRs we choose  $s$  and  $p$  atomic orbitals as trial orbitals for both Ge and S atoms. On the other hand,  $s$ ,  $p$  and  $d$  orbitals are chosen for Ge atoms and  $s$  and  $p$  orbitals for S atoms in the case of zz-GeSNRs. In Fig. 2 we compare the bandstructure plots obtained using DFT and MLWF and we observe a good agreement for energies around the Fermi level for both nanoribbon types, i.e. for ac-GeSNR in Fig. 2a and zz-GeSNR in Fig. 2b. After transformation to a localized basis, MLWF Hamiltonian matrices are used to construct the total GeSNR Hamiltonians of  $\sim 15$  nm-long ac- and zz-GeSNRs with various widths which represent the channel of the device.

In our in-house code [14, 20] we employ the NEGF formalism to obtain electronic and transport properties of the device attached to two contacts, e.g. source and drain (S/D). Within NEGF, the device is described with the total GeSNR Hamiltonian representing the channel of the device and S/D self-energy matrices that account for contacts, i.e. open boundary conditions at S/D. While metallic S/D contacts can be included into NEGF [8, 31], here we assume ideal contacts, i.e. semi-infinite regions of the same material as the channel and calculated using the numerically efficient Sancho-Rubio method [19, 32]. Therefore, the resulting density of states (DOS) will exhibit van Hove singularities, whereas S/D transmission will be a step-like curve.

The top-of-the-barrier (ToB) model, as described in [33], is used to study ballistic device characteristics. Within the ToB model a FET is defined by three potential/energy points, i.e. S/D quasi Fermi levels and the self-consistently calculated barrier height between S/D, denoted as the ToB potential (Fig. 3a). The main inputs to ToB are DOS and



**Fig. 3** **a** Illustration of a FET with a GeSNR channel. **b** Conduction band profile along the channel length with S/D quasi-Fermi levels and an illustration of the channel material bandstructure



**Fig. 2** Bandstructure obtained from DFT and MLWF for **a** ac-GeSNR, **b** zz-GeSNR

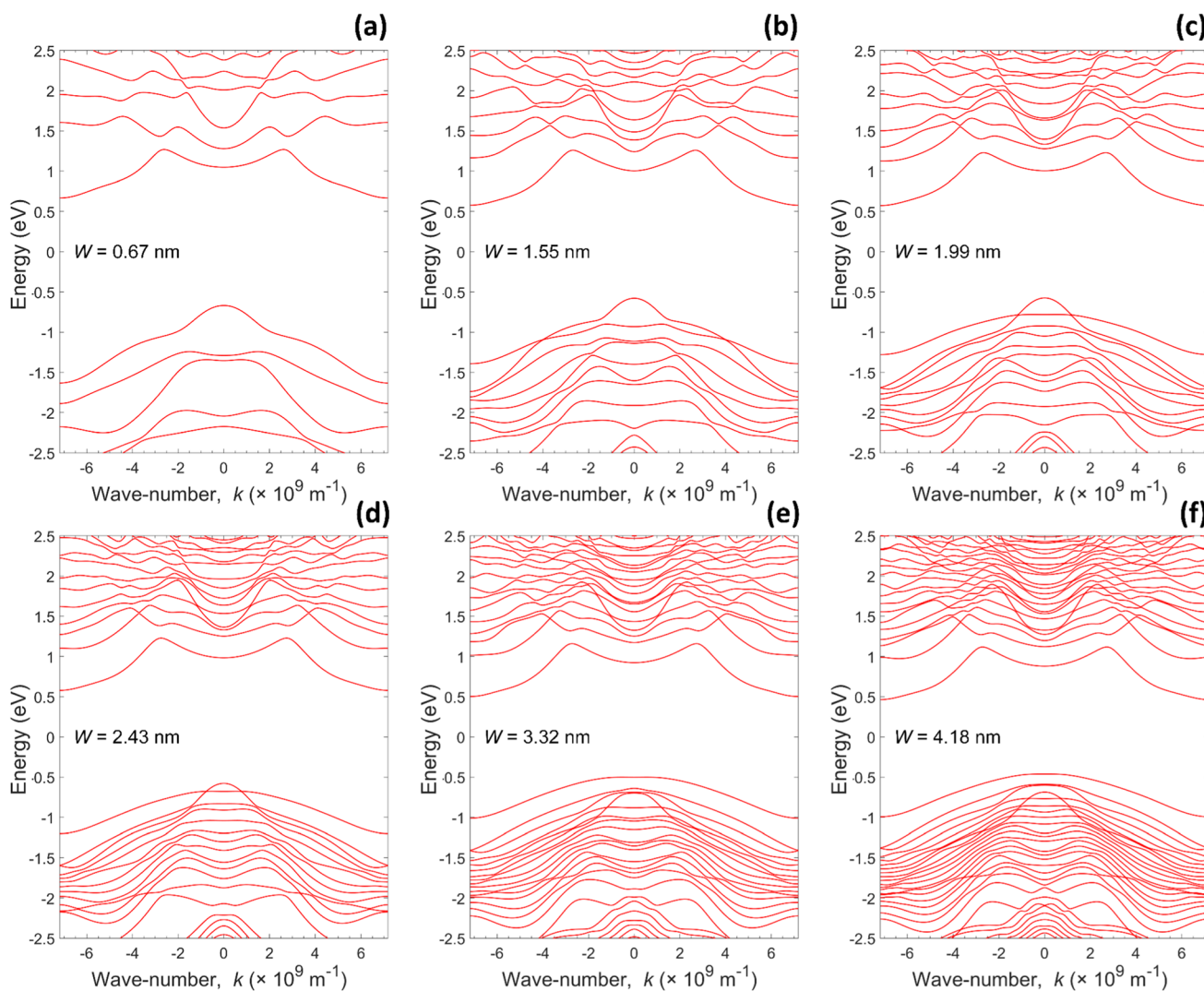
transmission calculated in equilibrium using NEGF, gate oxide material and thickness, and S/D Fermi levels due to doping. To illustrate the ToB model and the inclusion of orbitally-resolved bandstructure, conduction band profile along channel length is plotted in Fig. 3b. The ToB model finds only the thermionic current above the S/D barrier. Nevertheless, this approach is a dependable method for FETs where direct S/D tunneling and band to band tunneling (BTBT) are negligible, i.e. for channel lengths larger than  $\sim 15$  nm, and materials with a bandgap wider than  $\sim 0.5$  eV, respectively.

In this study, we simulate n- and p-type FETs with armchair and zigzag GeSNR channels. Simulation parameters are set to comply with IRDS for generations beyond the “3 nm” logic node [21]. In ToB FET model, channel control by the gate is assumed to be ideal, S/D doping is set at 0.01 molar fraction of the GeS areal density, and an initial

EOT is set to 1 nm. Supply voltage is  $V_{DD}=0.7$  V, which is slightly higher than 0.65 V that is predicted by IRDS for “2.1 nm” and “1.5 nm” logic nodes. The ballistic ON-state current ( $I_{ON}$ ) and ON-state charge density at ToB ( $Q_{CH}$ ) are extracted when both gate and drain are biased at the supply voltage. Simulations are done with a common OFF-state current ( $I_{OFF}$ ) for all devices to provide a fair and meaningful comparison between various GeS quasi-1D nanodevices. The  $I_{OFF}$  is set to 10 nA/ $\mu\text{m}$  so the study deals with high performance (HP) devices as defined by IRDS.

### 3 Results and discussion

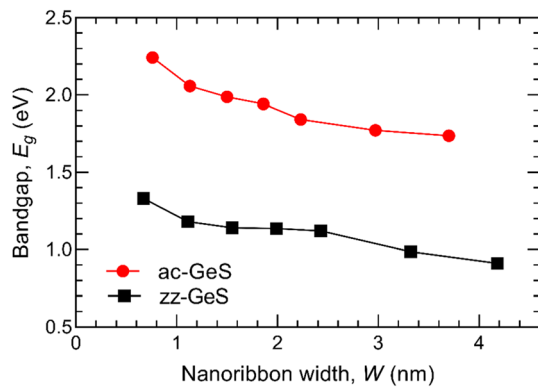
Bandstructure of various zz-GeSNRs is shown in Fig. 4, and generally we observe that zz-GeSNRs exhibit an indirect bandgap for all nanoribbon widths. Conduction band (CB)



**Fig. 4** Bandstructure of zigzag GeSNRs with the widths of **a** 0.67 nm, **b** 1.55 nm, **c** 1.99 nm, **d** 2.43 nm, **e** 3.32 nm, and **f** 4.18 nm

near the bandgap shows almost no change while scaling down nanoribbon width, i.e. the lowest CB subband is not affected by width scaling. On the other hand, in valence band (VB) a subband with a higher curvature, i.e. lower effective mass, emerges for nanoribbon widths below 3.32 nm. In order to provide a full picture, here we refer to our previous work where the bandstructure of various ac-GeSNRs was studied [17]. Notably, ac-GeSNRs with the widths below 1.86 nm transition from an indirect to a direct semiconductor. Additionally, for  $W=1.86$  nm the subband with lower effective mass for both conduction and valence bands becomes dominant in ac-GeSNRs.

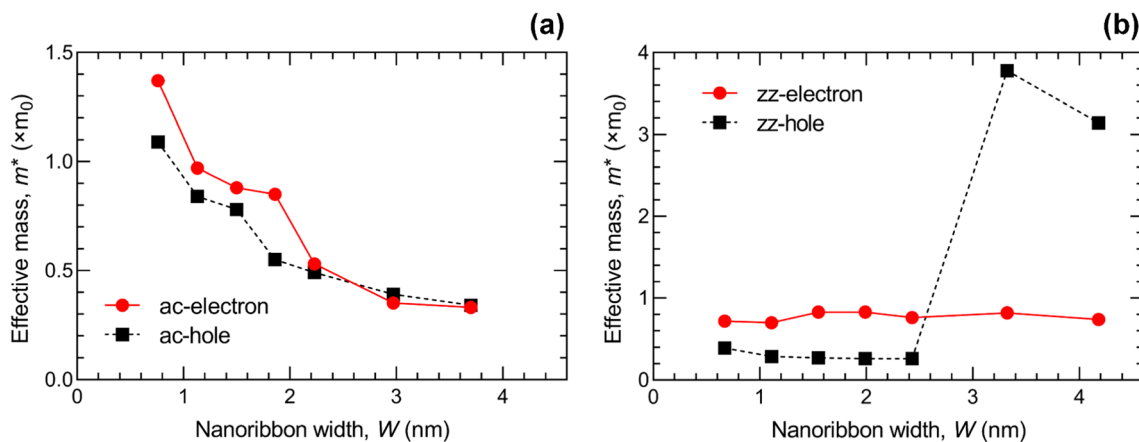
From the bandstructure we extract the bandgap ( $E_g$ ) and plot it in Fig. 5 for the examined ac- and zz-GeSNRs with the widths ranging from  $\sim 4.2$  to  $\sim 0.6$  nm. Scaling down the width of ac-GeSNRs changes the bandgap from indirect to direct, as it increases from 1.73 eV for  $W=3.70$  nm to 1.94 eV for  $W=1.86$  nm. The direct bandgap in sub-1.86 nm-wide ac-GeSNRs shows a similar scaling effect



**Fig. 5** Impact of nanoribbon width-scaling on the bandgap of armchair and zigzag GeSNRs

with the maximum direct  $E_g$  of 2.24 eV obtained for the 0.76 nm-wide ac-GeSNR. On the other hand, all zz-GeSNRs have an indirect bandgap but the  $E_g$  scaling law is different in two width regions, depending on the behavior of the highest subband in VB. In wider GeSNRs with zigzag edges the bandgap change is limited, i.e.  $E_g$  increases from 0.91 eV for  $W=4.18$  nm to 0.99 eV for the 3.32 nm-wide zz-GeSNR. Scaling the width below 3.32 nm changes the bandstructure so that the highest subband in VB is the one with a lower curvature (see Fig. 4d and e). Hence, bandgap increase to 1.12 eV for the 2.43 nm-wide zz-GeSNR, and reaches the maximum of 1.33 eV in the 0.67 nm-wide zz-GeSNR due to the strong quantum confinement in this nearly 1D nanostructure. For the large-area 2D GeS we obtain  $E_g=1.69$  eV, which is similar to the value of 1.65 eV reported in [15]. The bandgap of the 2D material is lower than in ac-GeSNRs due to quantum confinement, but higher than in zz-GeSNRs. The latter is unsurprising due to the existence of a subband in CB that belongs to edge states.

Effective mass ( $m^*$ ) is a good indicator of device properties and can be obtained near bandstructure minima/maxima by a parabolic approximation. The effective mass of the lowest conduction subband, i.e. electron effective mass  $m_e^*$ , and highest valence subband, i.e. hole effective mass  $m_h^*$ , for ac- and zz-GeSNRs are reported in Fig. 6. The effective mass in ac-GeSNRs (Fig. 4a) for both electrons and holes increase while scaling down nanoribbon width. The  $m_e^*$  increases from  $0.33 m_0$  for  $W=3.70$  nm to  $1.37 m_0$  for  $W=0.76$  nm, whereas  $m_h^*$  increases from  $0.34 m_0$  for  $W=3.70$  nm to  $1.09 m_0$  for  $W=0.76$  nm. The effective masses for both holes and electrons in ac-GeSNRs are higher than in 2D GeS in the armchair direction. The difference is larger than  $\sim 1.4\times$  because in [34] the authors obtained  $m_e^*=0.23 m_0$  and  $m_h^*=0.25 m_0$ . Therefore, transport properties of ac-GeSNRs relevant for device applications are



**Fig. 6** Dependence of electron and hole effective masses on nanoribbon width for **a** armchair and **b** zigzag GeSNRs. Effective masses are extracted for the lowest (highest) subband in the conduction (valence) band

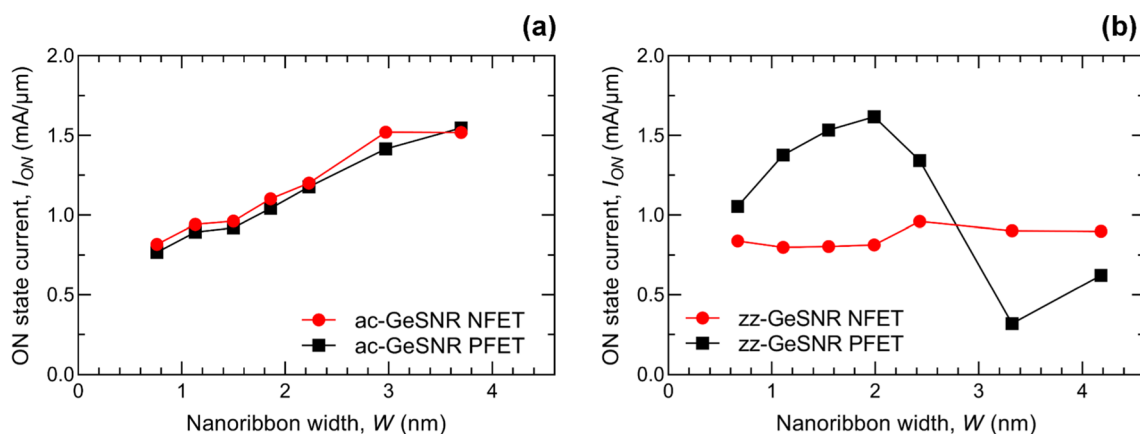
expected to suffer significantly from downscaling and confinement effects. On the other hand, in zz-GeSNRs (Fig. 4b) the effective mass of electrons is almost constant for all GeSNR widths, varying slightly from  $m_e^* = 0.70 m_0$  for  $W = 1.11$  nm to  $m_e^* = 0.83 m_0$  for  $W = 1.99$  nm. In contrast to  $m_e^*$ , hole effective mass is  $> 3 m_0$  for  $W \geq 3.32$  nm. We note that the extraction of  $m_h^*$  is much less accurate due to the existence of a subband with two barely noticeable peaks near the  $\Gamma$  point with high effective mass. Scaling down zz-GeSNR width below  $W = 3.32$  nm gives rise to subband with much lower effective mass with minimum obtained for  $W = 1.99$  nm where  $m_h^* = 0.26 m_0$ . As for the 2D GeS in zigzag direction, as reported in [34], electron effective mass of  $0.55 m_0$  in 2D GeS is  $\sim 1.3 \times$  smaller than the minimum value obtained for  $m_e^*$  in zz-GeSNRs. On the other hand, holes are lighter in zz-GeSNRs than in the 2D counterpart, i.e.  $m_h^* = 0.67 m_0$  is reported for 2D GeS in the zigzag direction, which is  $\sim 2.6 \times$  larger than the minimum hole effective mass obtained for zz-GeSNRs with  $W \leq 2.43$  nm.

Effective mass in the transport direction can help roughly predict device performance so, for example, the results provided in Fig. 5 indicate promising zz-GeSNR FETs if nanoribbon width is kept under 2.43 nm. However, the rough prediction can be improved by simulating the ON-state current to assess device performance in more detail. The  $I_{ON}$  is plotted for n- and p-channel GeSNR FETs for GeSNRs with armchair (Fig. 7a) and zigzag (Fig. 7b) edges. The ON-state current of the ac-GeSNR nFETs decreases monotonically while scaling down the channel width, from 1.52 mA/ $\mu\text{m}$  for  $W = 3.70$  nm to  $I_{ON} = 0.82$  mA/ $\mu\text{m}$  for  $W = 0.76$  nm. Similarly, the  $I_{ON}$  of pFETs with armchair GeSNRs also decreases monotonically while scaling down the channel width, from 1.55 mA/ $\mu\text{m}$  for  $W = 3.70$  nm to 0.77 mA/ $\mu\text{m}$  in the 0.76 nm-wide nanoribbon. On the other hand, the ON-state current exhibits qualitatively different behavior in FETs with zz-GeSNRs. Namely, in zz-GeSNR nFETs

the  $I_{ON}$  is relatively constant with respect to width scaling, and ranges between 0.96 and 0.80 mA/ $\mu\text{m}$ . However, in zz-GeSNR pFETs the driving current exhibits a local maximum for the 1.99 nm-wide device with  $I_{ON} = 1.62$  mA/ $\mu\text{m}$ , and a local minimum of 0.32 mA/ $\mu\text{m}$  for  $W = 3.32$  nm. Digital switching capabilities of GeSNR FETs for logic applications can be assessed by the  $I_{ON}/I_{OFF}$  ratio. Both ac- and zz-GeSNR FETs show good switching capabilities with ac-GeSNR FETs showing  $I_{ON}/I_{OFF}$  higher than  $7.7 \times 10^4$  while zz-GeSNR FETs show  $I_{ON}/I_{OFF}$  higher than  $3.2 \times 10^4$ . Maximum  $I_{ON}/I_{OFF}$  value of  $1.62 \times 10^5$  is obtained for zz-GeSNR FETs with  $W = 1.99$  nm.

The ON-state performance for both zigzag and armchair GeSNR FETs is directly correlated to the bandstructure along the transport direction. Namely, the current depends on the amount of charge in the channel and its transport properties, i.e. carrier charge density at ToB depends on DOS and transport probability for each conducting mode is represented by the transmission characteristics. The ON-state current is mainly determined by the subbands that are the nearest to the conduction band minimum (CBM) for nFETs, and valence band maximum (VBM) for pFETs. Higher effective mass correlates directly to lower  $I_{ON}$  which can be seen by comparing e.g. the effective mass in Fig. 6a and current in Fig. 7a for GeSNRs with armchair edges. Here we can see that the downscaling of ac-GeSNR width increases the effective mass and decreases the  $I_{ON}$ , both monotonically. Additionally, a considerable drop in hole effective mass in zz-GeSNRs when going from the 3.3 nm to 2.4 nm-wide nanoribbons (Fig. 6b) translates into a significant  $I_{ON}$  increase for zz-GeSNRs pFETs in the same width range (Fig. 7b).

To further analyze the ON-state performance of FETs with quasi-1D GeS channels we investigate the features of DOS, transmission, charge density and injection velocity. Transmission and DOS of ac-GeSNRs are discussed

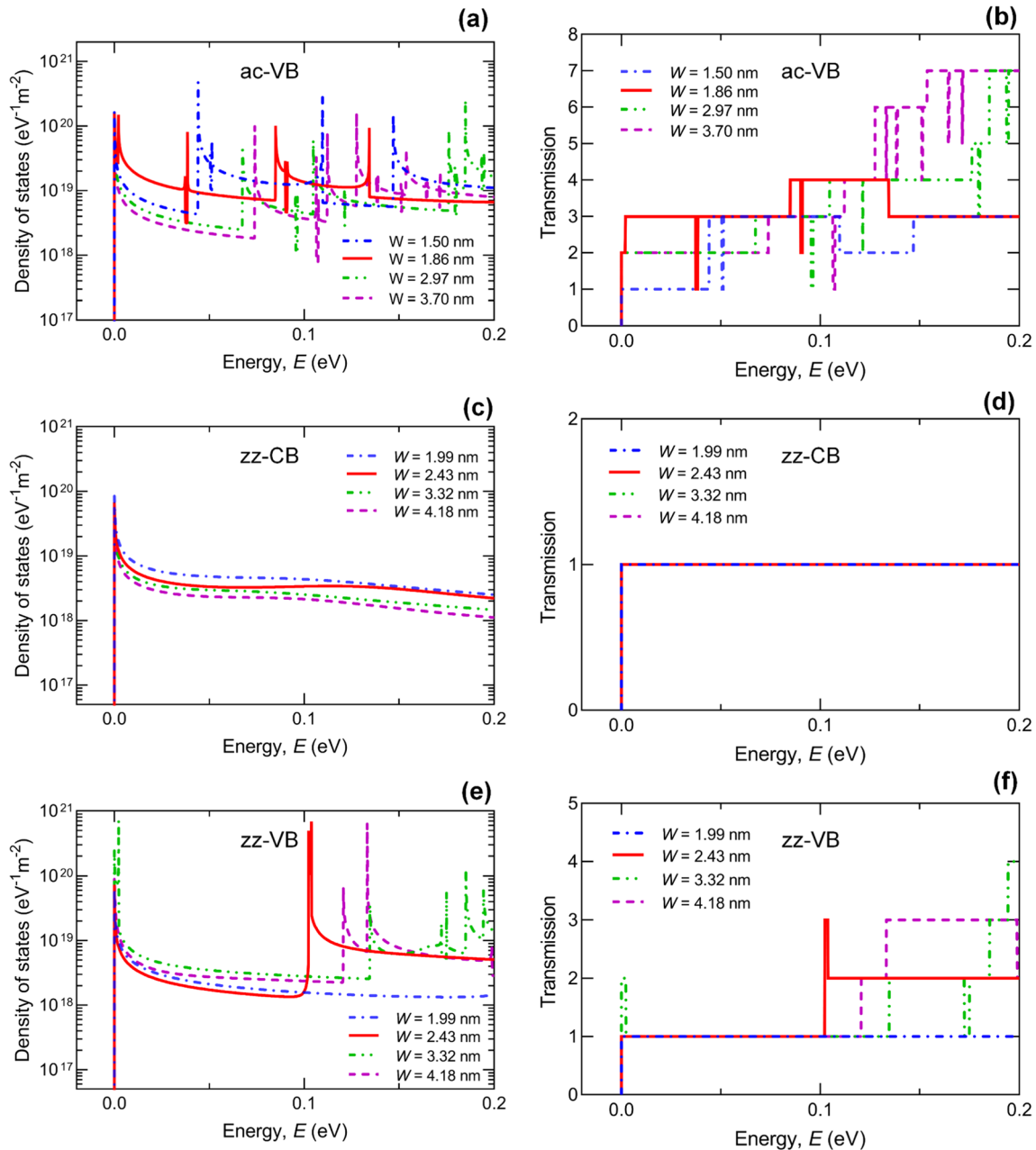


**Fig. 7** Width-dependence of the ON-state current in n- and p-type **a** armchair and **b** zigzag GeSNR FETs.  $I_{ON}$  is extracted at  $V_{GS} = V_{DS} = V_{DD} = 0.7$  V with a common  $I_{OFF} = 10$  nA for all devices

previously in [17], but only for electrons in the CB. In short, we showed that scaling down the width increases DOS near the CBM (due to emergence of subbands with lower curvature, i.e. higher effective mass), and decreases the number of Van Hove singularities (VHS) due to a lower number of conducting modes in narrower nanoribbons. Moreover, transmission equals unity near the CBM for all ac-GeSNR widths and rises for wider ac-GeSNRs due to higher number of subbands near CBM. Figure 8 reports the DOS and transmission near the CBM, VBM, or both for ac- or zz-GeSNRs

of various widths. Since the characteristics of CB are already known, for ac-GeSNRs we plot only the DOS and transmission in the VB in Fig. 8(a,b). For zz-GeSNRs, the properties in the CB and VB are plotted in Fig. 8(c,d) and (e,f), respectively.

The DOS in ac-GeSNRs near the VBM is rather high with a high number of densely spaced Van Hove singularities. Scaling down nanoribbon width decreases the transmission near the VBM from 2 for  $W=3.70$  nm to 1 for  $W<1.86$  nm, which is where ac-GeSNRs transition from indirect to direct



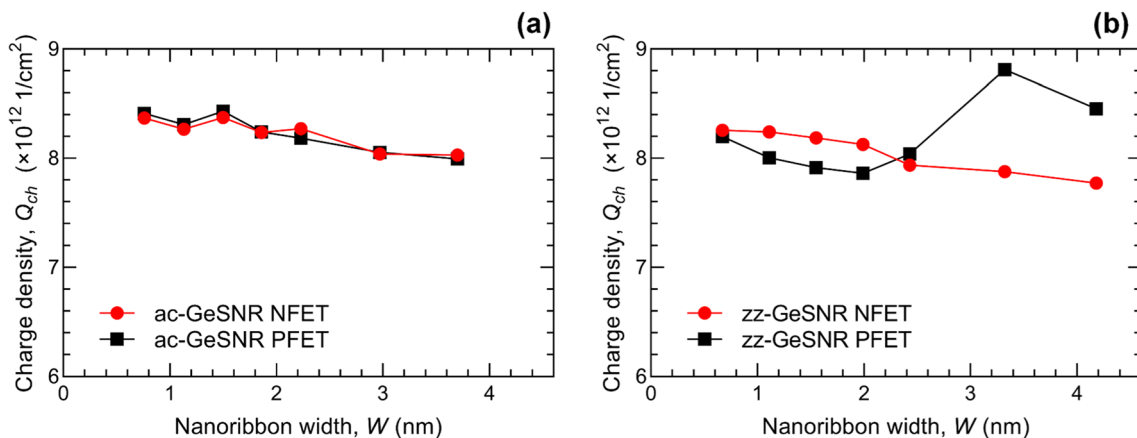
**Fig. 8** Comparison of DOS and transmission in **a, b** valence band of ac-GeSNRs, **c, d** conduction band of zz-GeSNRs and **e, f** valence band of zz-GeSNRs for various nanoribbon widths. All DOS and transmission plots are shifted so that the CBM and VBM are positioned at 0 eV

semiconductor. For 1.86 nm-wide ac-GeSNR, transmission quickly rises to 3 at  $V_{BM} - 0.002$  eV because a subband emerges at the  $\Gamma$  point. The DOS curves in CB for zz-GeSNRs have a similar magnitude with a single dominant band. This is also visible in the transmission plot where CB transmission is unity near the CBM for all zz-GeSNR widths. The immunity of electron bands in zz-GeSNRs to width-scaling confinement effects observed for transmission in Fig. 8d is in qualitative agreement with  $I_{ON}$  behavior of zz-GeSNR nFETs reported in Fig. 7b. On the other hand, transmission and DOS in VB of zz-GeSNR exhibit a bit more interesting characteristics than in the CB. The widest zz-GeSNRs with  $W = 3.32$  nm and  $W = 4.18$  nm have higher DOS near the VBM due to the low-curvature and high- $m^*$  in the highest VB subband (see Fig. 4e and f). The 3.32 nm-wide zz-GeSNR also shows a secondary VHS at an energy 0.002 eV away from the VBM because of the shape of the top subband that has two barely noticeable peaks near  $\Gamma$  point. This effect is also seen in the transmission plot in Fig. 8f where the transmission equals 2 in the narrow energy range near the VBM and decreases to unity at higher energies. The similar transmission values in VB of zz-GeSNRs (Fig. 8f) stand in contrast with a strongly nonmonotonic  $I_{ON}$  behavior in zz-GeSNR pFETs reported in Fig. 7b. Therefore, in this case key information is contained in effective masses along the transport direction which, in turn, are visible in the properties of channel charge density and carrier injection velocity.

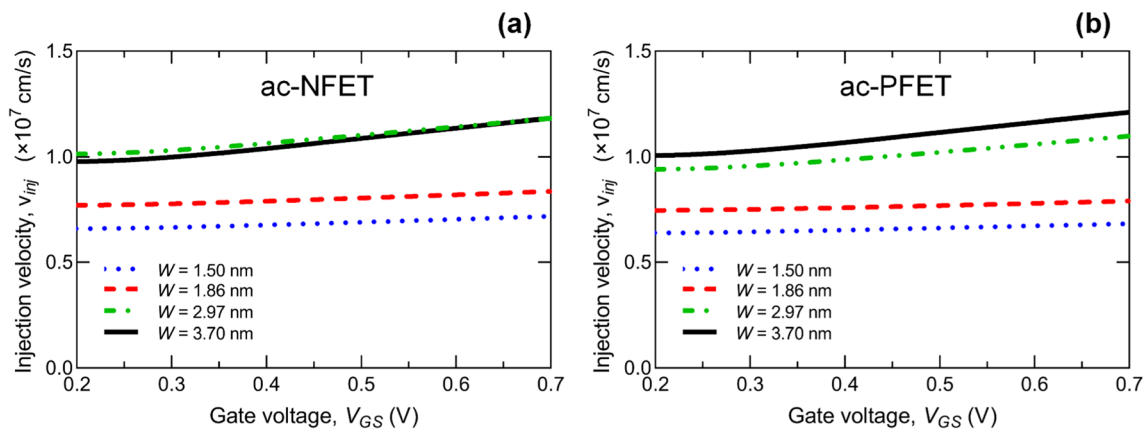
The stark differences in DOS reported in Fig. 8 should translate into considerable variations of  $Q_{CH}$  in various GeSNR devices. The ON-state charge density is plotted for n- and p- type FETs for various widths of ac-GeSNRs and zz-GeSNRs in Fig. 9a and b, respectively. Scaling down ac-GeSNR width shows similar scaling properties for both n- and p-type FETs. The nFET charge density slightly increases

from  $8.03 \times 10^{12}$   $\text{cm}^{-2}$  for the GeSNR width of 3.70 nm to  $8.37 \times 10^{12}$   $\text{cm}^{-2}$  for the 0.76 nm-wide ac-GeSNR. Similarly, in pFETs with armchair GeSNRs charge density increases from  $7.99 \times 10^{12}$   $\text{cm}^{-2}$  for  $W = 3.70$  nm to  $8.43 \times 10^{12}$   $\text{cm}^{-2}$  for  $W = 1.50$  nm. To accommodate for the increase of bandgap in the narrowest nanoribbons and setting a proper  $I_{OFF}$ , charge density is the highest in the narrowest nanoribbons where the ON-state current is the lowest. On the other hand, scaling down zz-GeSNR width (Fig. 9b) increase the ToB charge density in nFETs from  $7.77 \times 10^{12}$   $\text{cm}^{-2}$  in the 4.18 nm-wide zz-GeSNR up to  $8.26 \times 10^{12}$   $\text{cm}^{-2}$  for  $W = 0.67$  nm. While the ON-state current has similar values for all nFETs with zz-GeSNR channel, charge density is the highest for the narrowest nanoribbons due to the increase of bandgap and setting of a common  $I_{OFF}$ . In the case of pFETs with zz-GeSNR channels we can split the devices into three groups. The first group includes zz-GeSNRs with  $W > 2.43$  nm where charge density is the highest among all simulated GeSNRs with the maximum value obtained for  $W = 4.18$  nm where  $Q_{CH} = 8.81 \times 10^{12}$   $\text{cm}^{-2}$ . This occurs due to the subband with high DOS near the VBM, as seen in Fig. 4e and f and Fig. 8e, which in turn gives rise to more mobile charge at the ToB for the same applied voltage. A local minimum in hole density of  $Q_{CH} = 7.86 \times 10^{12}$   $\text{cm}^{-2}$  is reached for  $W = 1.99$  nm after which the hole density increases to  $8.19 \times 10^{12}$   $\text{cm}^{-2}$  in the 0.67 nm-wide zz-GeSNR. Charge density is of the same magnitude for all ac- and zz-GeSNR FETs, agreeing with the obtained magnitude of the ON-state current, and with a scaling behavior qualitatively comparable to effective mass scaling shown in Fig. 6.

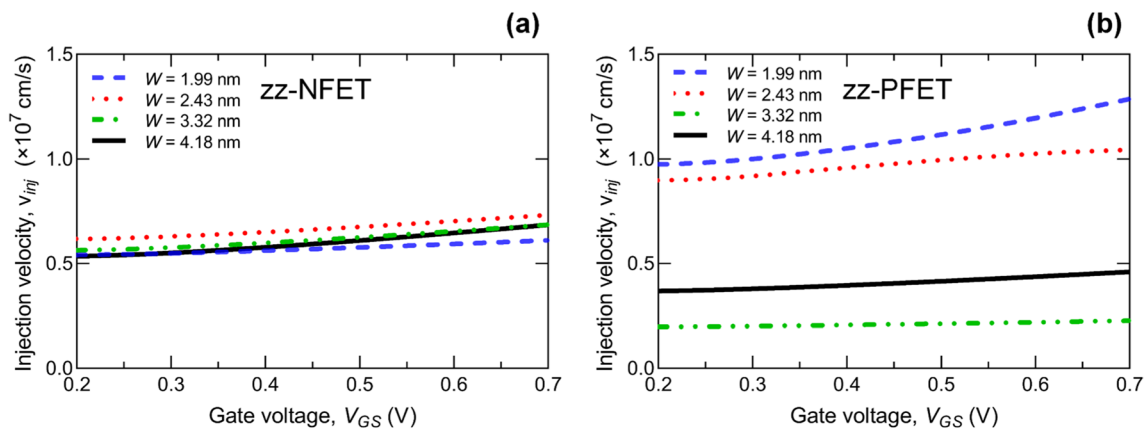
Injection velocity ( $v_{inj}$ ) dependence on  $V_{GS}$  in the range from the threshold voltage to the supply voltage ( $\sim 0.2$  V to 0.7 V) for n- and p-type GeSNR FETs with armchair (Fig. 10) and zigzag edges (Fig. 11). Nanoribbon widths are the same as in Fig. 8. For each device, a relative  $v_{inj}$  increase



**Fig. 9** Width-dependence of charge density at ToB in n- and p-type **a** armchair and **b** zigzag GeSNR FETs. Charge density is extracted in the ON-state, i.e. for  $V_{GS} = V_{DS} = V_{DD} = 0.7$  V



**Fig. 10** Dependence of injection velocity on gate voltage in **a** n-type and **b** p-type armchair GeSNR FETs for various nanoribbon widths



**Fig. 11** Injection velocity vs. gate voltage for **a** n-type and **b** p-type zigzag GeSNR FETs with different nanoribbon widths

is defined as an increase of injection velocity extracted at 0.7 V compared to the value at 0.2 V. As shown in Fig. 10a, scaling down the width of ac-GeSNR nFETs decreases the electron  $v_{inj}$  from  $1.18 \times 10^7$  cm/s for  $W = 3.70$  nm to  $0.72 \times 10^7$  cm/s for  $W = 1.50$  nm. Injection velocity noticeably rises with increasing  $V_{GS}$  only in wider nanoribbons because wider GeSNRs exhibit a denser bandstructure near the CBM, and therefore higher modulation of  $v_{inj}$  with the applied bias. The relative  $v_{inj}$  increase equals 20% for  $W = 3.70$  nm, while the smallest relative increase is 9% and is obtained for  $W = 1.50$  nm. The hole injection velocity in ac-GeSNR pFETs (Fig. 10b) shows comparable values and nearly identical scaling properties as electron  $v_{inj}$  in nFETs with ac-GeSNR channels. On the other hand, electron injection velocity in zz-GeSNR nFETs changes very little for different nanoribbon widths and various gate bias. The  $v_{inj}$  ranges from  $0.61 \times 10^7$  cm/s to  $0.73 \times 10^7$  cm/s, with the highest value obtained for the 2.43 nm-wide zz-GeSNR due to the existence of a single dominant subband in CB

that is resistant to scaling. Unlike nFETs, the hole injection velocity in zz-GeSNR pFETs varies considerably with the width downscaling and exhibits bias-dependence, especially for the  $\sim 2$  nm-wide device. The maximum hole  $v_{inj}$  equals  $1.29 \times 10^7$  cm/s that is obtained in the 1.99 nm-wide zz-GeSNR, whereas the minimum  $v_{inj}$  is only  $0.23 \times 10^7$  cm/s for  $W = 3.32$  nm. This  $\sim 5.6 \times$  difference is caused by the emergence of a subband in VB of zz-GeSNRs with a higher curvature, as seen in Fig. 3 and discussed in related text. Contrary to other ac- and zz-GeSNR FETs in which the widest nanoribbons exhibit the highest relative  $v_{inj}$  increase, the largest improvement of hole injection velocity in zz-GeSNRs is 32% and occurs in the 1.99 nm-wide device. The findings related to the injection velocity are in line with the reported bandstructure, effective mass and current modulation with width scaling. For example, lower effective mass leads to a higher  $v_{inj}$  and this relationship can be clearly seen when comparing effective mass in Fig. 6a and  $v_{inj}$  in Fig. 10, i.e. monotonic increase of  $m^*$  leads to  $v_{inj}$  decrease when the



width is scaled down in ac-GeSNRs. The ON-state current is proportional to  $v_{inj}$  and  $Q_{CH}$ , and while  $v_{inj}$  shows similar scaling laws compared to  $I_{ON}$ ,  $Q_{CH}$  exhibits an inverse scaling behavior as discussed earlier. Therefore, the injection velocity is a dominant factor that determines the values and trends of drain current in GeSNR FETs.

In order to benchmark GeSNR devices against relevant digital logic technology goals, we compare our results to the ON-state current requirements of IRDS for HP devices for two future nodes, i.e. “2.1 nm” node with  $I_{ON}=1.79$  mA/ $\mu$ m and “1.5 nm” node with  $I_{ON}=1.98$  mA/ $\mu$ m. Initially in the simulations the EOT is set to 1 nm that results in  $I_{ON}$  values reported in Fig. 7, and none of these GeSNR FETs meets the IRDS requirements for either node. Nevertheless, using high- $\kappa$  dielectrics such as  $HfO_2$  with a relative dielectric constant of  $\sim 20$  enables further oxide thickness scaling down to  $\sim 0.5$  nm. Hence, we simulate the ON-state for n- and p-channel, ac- and zz-GeSNR FETs again for various nanoribbon widths and different EOT values ranging from 0.5 to 1 nm. The  $I_{OFF}$  is common for all devices and is again set to 10 nA/ $\mu$ m in order to assess GeSNR FETs as potential HP transistors. The results are plotted in Fig. 12 and Fig. 13 for GeSNR FETs with armchair and zigzag edges, respectively. In the plots, light blue squares indicate that a specific combination of width and EOT meets the “2.1 nm” node goal, while darker blue squares indicate the same for both the “2.1 nm” and “1.5 nm” technology node.

The results for armchair n-type (Fig. 12a) and p-type (Fig. 12b) GeSNR FETs show that width-scaling decreases the EOT needed to meet the requirements for “2.1 nm” and “1.5 nm” nodes. The ac-GeSNR nFETs with the widths of

3.70 nm and 2.97 nm fulfil the “2.1 nm” node requirements for  $EOT < 0.85$  nm, while  $EOT < 0.77$  nm is needed for the “1.5 nm” node. The narrowest ac-GeSNR nFETs that meet IRDS requirements are those with  $W=1.13$  nm and  $W=1.50$  nm, but a small  $EOT \sim 0.5$  nm is needed in these devices. Similarly, for pFETs wider ac-GeSNRs also allow a thicker oxide, which benefits the fabrication process complexity. For example, the 3.70 nm-wide ac-GeSNR pFET exhibits the largest allowed EOT of 0.86 nm and 0.78 nm, depending on the desired node. The narrowest ac-GeSNRs that meet IRDS requirements as p-channel devices are those with  $EOT \sim 0.5$  nm, with the width of 1.13 nm for “2.1 nm” node, and  $W=1.86$  nm for “1.5 nm” node. The 0.76 nm-wide ac-GeSNR n- and p-type FETs do not meet IRDS specification for either node even with a downscaled oxide thickness, which is expected given the bandstructure and confinement effects explained earlier in the text.

Devices with zigzag edges, i.e. zz-GeSNR n-type FETs shown in Fig. 13a and p-type FETs reported in Fig. 13b, experience remarkably different scaling effects compared to their armchair-edge counterparts. The nFETs with  $W \geq 2.43$  nm and with EOT up to  $\sim 0.55$  nm meet IRDS goals for the “2.1 nm” node, whereas only the 2.43 nm-wide and 4.18 nm-wide devices with  $EOT \sim 0.5$  nm meet the requirements for “1.5 nm” node. The zz-GeSNR nFETs with sub-1.99 nm widths do not meet IRDS specifications for either node. These results indicate that 2D GeS nFETs in the zz-direction should meet IRDS requirements because the large-area GeS does not have the subband that is dominant near the CBM. However, the influence of this subband seems to be a bottleneck for nFETs with a zz-GeSNR channel. In

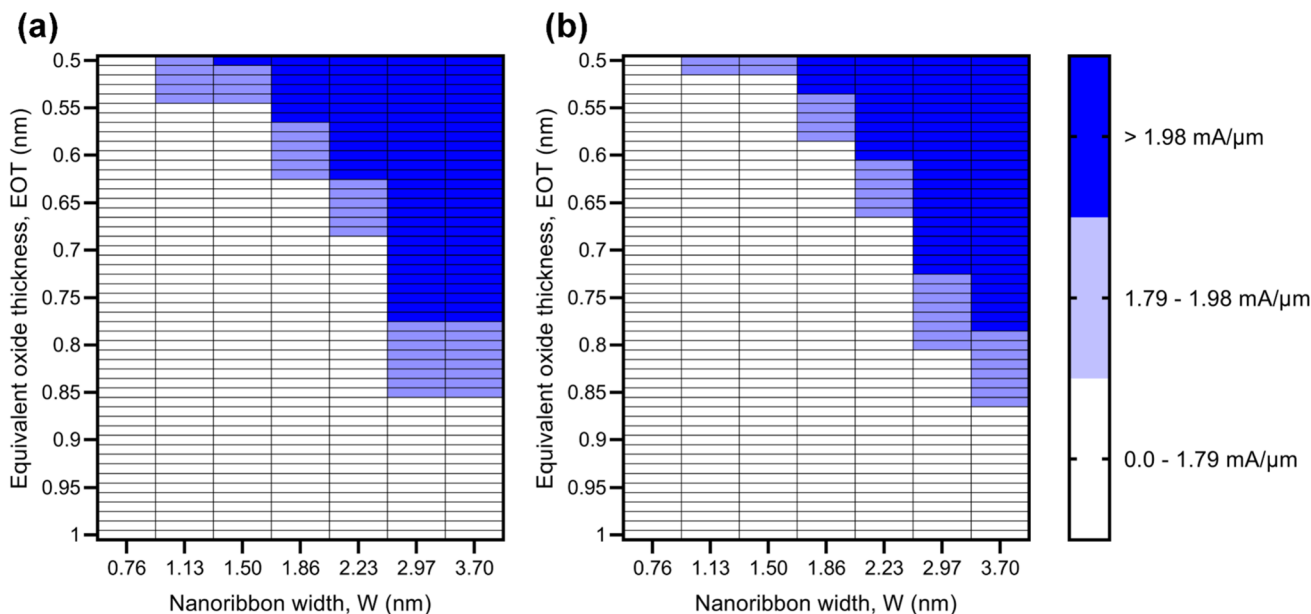
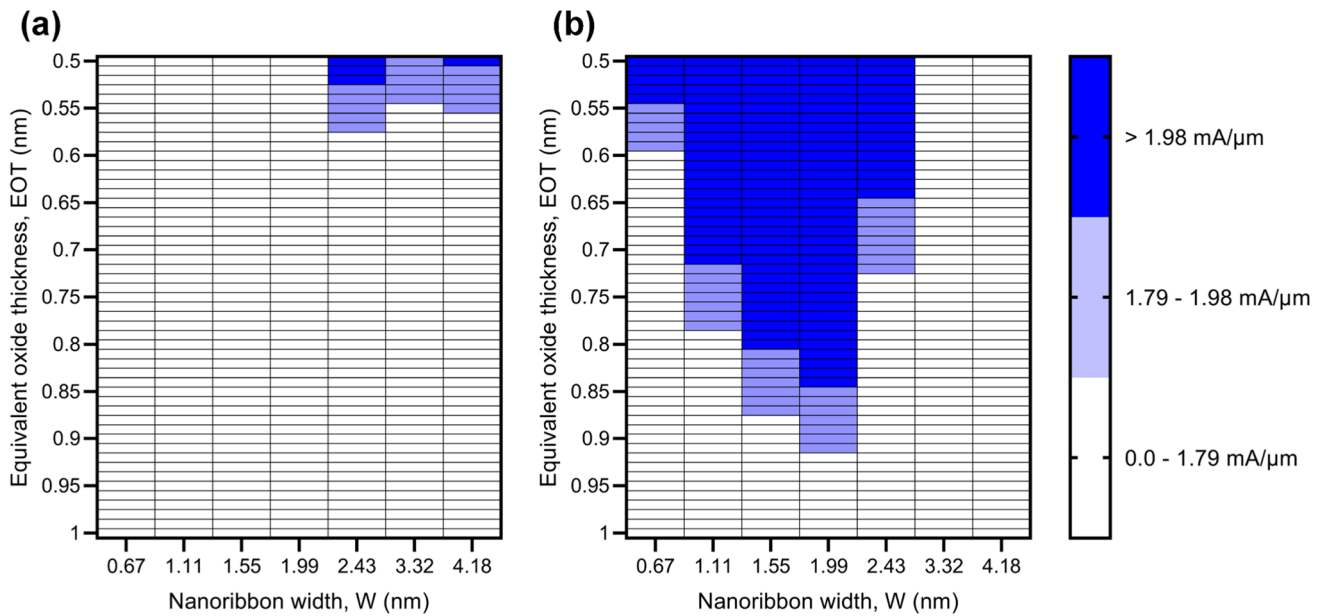


Fig. 12 ON-state current dependence on equivalent oxide thickness and nanoribbon width in a n-type and b p-type armchair GeSNR FETs



**Fig. 13** ON-state current dependence on equivalent oxide thickness and nanoribbon width in **a** n-type and **b** p-type zigzag GeSNR FETs

contrast, the situation looks more optimistic for zz-GeSNR pFETs. Namely, some of these devices with  $W \leq 2.43$  nm meet IRDS requirements for both nodes. These results correspond to those in Fig. 7b where maximum  $I_{ON}$  is reported for  $\sim 2$  nm-wide zigzag GeSNR pFETs, and is caused by the emergence of sub-band with lower effective mass. In turn, this effect creates a region of high  $I_{ON}$  that is centered around  $W \sim 1.55$  nm and  $EOT \sim 0.65$  nm in the EOT- $W$  plane visible in Fig. 13b. For example, within this region the 1.99 nm-wide zz-GeSNR pFET meets the IRDS requirements for both nodes when  $EOT < 0.85$  nm. Beyond this region, i.e. for  $W \geq 3.32$  nm, IRDS specifications are not fulfilled for either node. We expect the same to be true for 2D GeS pFETs in the zigzag direction, irrespective of node and EOT employed in the device.

The results obtained for armchair and zigzag GeS nanoribbon FETs are promising when compared to the IRDS requirements, however, we note that the upper ballistic limits are explored in this work. Clearly, taking realistic metal contacts and carrier scattering would deteriorate the reported GeSNR FET performance. For example, due to polar nature of GeS the mobility decreases by  $\sim 4 \times$  when polarization effects on carrier transport are taken into account as shown in [34]. Another potential problem for realistic GeSNR devices is edge roughness, which greatly depends on advancements in manufacturing of such devices at the nanoscale. While some of these issues such as elastic defect scattering, inelastic phonon scattering, and the impact of metal contacts and contact resistance will be addressed in future work, we nevertheless stress the potential of GeSNRs for future multi-channel FETs as reported in our study.

## 4 Conclusions

We presented an in-depth study on the electronic, transport and ballistic device characteristics of quasi-1D GeS nanostructures. We investigated sub-5 nm-wide and  $\sim 15$  nm-long armchair and zigzag GeSNRs and GeSNR n- and p-type FETs by combining DFT, MLWF, NEGF and ToB modeling and numerical simulations. Starting from the bandstructure, and analyzing DOS, transmission, carrier effective mass and injection velocity, we show that some ac- and zz-GeSNR FETs show promising ON-state performance when benchmarked against IRDS requirements. Moreover, IRDS specifications are fulfilled for “2.1 nm” and “1.5 nm” nodes with realistic and technologically relevant EOT values. In both n- and p-type FETs with ac-GeSNR channels the  $I_{ON}$  monotonically decreases while scaling down nanoribbon width due to increase of  $m^*$  and, consequently, reduction of electron and hole injection velocity. Although ac-GeSNR FETs exhibit a deteriorating performance with the width-downscaling, for  $W > 1.13$  nm and by extension for 2D GeS in armchair direction a device that meets IRDS specifications is possible for both n- and p-type FETs. In contrast, all zz-GeSNR have a relatively high electron  $m^*$ , which results in low electron  $v_{inj}$  and poor ON-state performance of zz-GeSNR nFETs. The IRDS goals are met only for the widest analyzed nanoribbons and with an EOT close to 0.5 nm, which disqualifies zz-GeSNR as a plausible solution for ultra-scaled nFETs. The most interesting characteristics are provided by zz-GeSNR pFETs that exhibit nonmonotonic behavior of hole density, effective mass, injection velocity, and ON-state current. Namely, for  $W \leq 2.43$  nm a subband with low effective

mass appears in zz-GeSNRs at the top of VB that results in high hole  $v_{inj}$  and good ON-state performance of zz-GeSNR pFETs. For these devices, a region of acceptable EOT and  $W$  values exists where IRDS specifications are fulfilled. The zz-GeSNR pFETs with  $W > 2.43$  nm, and by extension 2D GeS pFETs with channel oriented along the zigzag direction, do not meet IRDS requirements. Finally, the  $I_{ON}/I_{OFF}$  ratio of at least  $\sim 7.7 \times 10^4$  and  $\sim 3.2 \times 10^4$  is reported for GeSNR FETs with armchair and zigzag nanoribbons, respectively, which indicates good digital switching performance for logic devices. Therefore, our work demonstrates that quasi-1D GeS nanostructures offer interesting and promising electronic and ballistic transport properties with potential applications in future extremely-scaled transistors.

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**Author contribution** All authors contributed to the study conception and design. Material preparation, data collection and analysis were performed by MM and MP. The first draft of the manuscript was written by MM and all authors commented on previous versions of the manuscript. All authors read and approved the final manuscript. The datasets generated during and/or analyzed during the current study are available from the corresponding author on reasonable request.

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**Data availability** Enquiries about data availability should be directed to the authors.

**Competing interests** The authors have not disclosed any competing interests.

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## **Publication 4**

### ***Ab initio* quantum transport simulations of monolayer GeS nanoribbons**

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# *Ab initio* quantum transport simulations of monolayer GeS nanoribbons

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## ABSTRACT

Monolayer germanium monosulfide (GeS) was recently identified as one of the most promising 2D materials for ultra-scaled FETs. While sub-10 nm monolayer GeS FETs were studied by quantum transport, very little is known about GeS nanoribbons (GeSNRs) or GeSNR FET performance. In this work, we employ quantum transport and Hamiltonians with an orbital resolution to study the electronic, transport, and ballistic device properties of sub-4 nm-wide and  $\sim 15$  nm-long GeSNRs. While ultra-scaled GeSNR FETs exhibit  $I_{ON}/I_{OFF}$  of at least  $\sim 7 \times 10^5$ , indicating good switching performance, they also offer modest ballistic  $I_{ON}$  values of up to  $\sim 1.2$  mA/ $\mu\text{m}$ .

## 1. Introduction

Miniaturization and optimization of transistors have driven the tremendous development of the semiconductor industry in the last 60 years. Short channel effects (SCEs) suppression at gate lengths under  $\sim 20$  nm is difficult and, on that account, new materials and device architectures are needed to enable further transistor scaling and improve device performance. Potential candidates for future transistor channel materials are atomically thin 2D materials (2DMs). Due to their atomic thickness and dangling-bond-free surfaces, 2DMs have high immunity to SCEs, and the near-ballistic transport properties are promising for high-performance devices [1], but the high contact resistance still remains a limiting factor for 2DMs application in nanodevices [2,3]. Patterning 2DMs into quasi-1D nanoribbons enables tuning of the electronic, transport, and device properties [4,5] such as bandgap, effective mass, injection velocity, etc., which makes these nanostructures of interest for nanoelectronic devices.

Monolayer germanium monosulfide (GeS) is a group-IV monochalcogenide 2D material with a buckled orthorhombic lattice. Monolayer GeS was recently examined along with hundreds of 2D materials as one of the most promising 2D materials for ultra-scaled FETs in [1], while a quantum transport study of sub-10 nm monolayer GeS FETs was reported in [6]. On the other hand, very little is known about GeS nanoribbons (GeSNRs) or GeSNR device performance, with the knowledge on the former being limited to electronic properties only, as reported in [7]. Concerning their electronic properties, armchair and

zigzag GeSNRs were studied with armchair 2D GeS showing more promise for device applications due to lower electron and hole effective masses. Hence, in this work, we analyze GeSNRs with armchair edges.

Advanced modeling is needed for the simulation of transistors at the nanoscale due to the atomistic resolution of the material and strong quantum effects. Here we use *ab initio* density functional theory (DFT) to perform electronic structure calculations and maximally localized Wannier functions (MLWFs) are employed to transform DFT Hamiltonians into a localized basis, which preserves bandstructure accuracy and reduces the computational load for transport calculations. Next, non-equilibrium Green's function (NEGF) formalism, including the MLWF Hamiltonians, is used for ballistic quantum transport simulations [8–10]. In this work, our in-house DFT-MLWF-NEGF solver is employed to analyze the electronic, transport, and ballistic device properties of ultra-scaled armchair GeSNRs and GeSNR FETs that exhibit a direct bandgap for narrowest nanoribbons.

### 1.1. Methodology

The unit cell of the 2D GeS is obtained from the 2D materials database provided by Materials Cloud [11], which is then used to construct an armchair GeSNR super-cell along the nanoribbon width ( $W$ ). Edges of the GeSNRs are passivated with H atoms and a vacuum of  $20 \text{ \AA}$  is added in the confined directions to exclude any interactions (existing due to DFT that assumes periodicity in all three directions). We construct and perform DFT simulations for GeSNR super-cells for nanoribbon widths

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from  $W = 0.76$  nm to  $W = 3.70$  nm. The DFT calculations are used to relax H-passivated GeSNRs structures and obtain the band structure with high accuracy. Plane-wave based Quantum Espresso program package [12] is used for DFT calculations, with Perdew-Burke-Ernzerhof generalized gradient approximation (PBE-GGA) [13] for the exchange-correlation (XC) functional. The plane-wave cutoff energy is set to 100 Ry, while the convergence threshold is set to  $10^{-3}$  eV/Å for the ionic force, and to the value of  $10^{-4}$  eV for energy. The  $k$ -points are sampled using an equally-spaced Monkhorst-Pack grid [14] in the transport direction and 1  $k$ -point in the confined directions. The output of the DFT are dense Hamiltonians localized in energy, but NEGF simulations prefer spatially localized Hamiltonians. Maximally-localized Wannier functions (MLWFs) [15] are used to transform DFT Hamiltonians into a localized basis, which results in much sparser matrices and enables the simulation of devices consisting of thousands of atoms [8,16]. Wannier90 program package [17] is used to obtain the MLWF Hamiltonians. The MLWFs accuracy greatly depends on trial orbitals that are projected on the Bloch manifold. For GeSNRs we choose  $s$ ,  $p_x$ ,  $p_y$ , and  $p_z$  atomic orbitals as trial orbitals for both Ge and S atoms. The MLWF Hamiltonian matrices are then used to construct the total GeSNR channel Hamiltonians of  $\sim 15$  nm long nanoribbons with different GeSNR widths.

Non-equilibrium Green's function (NEGF) formalism is used to directly solve the Schrödinger's equation with open boundary conditions (OBCs). Retarded Green's function,  $G^R$ , of the device is the central quantity of NEGF formalism and can be written as.

$$G^R(E) = [(E + i\eta)I - H - \Sigma_S^R(E) - \Sigma_D^R(E)]^{-1},$$

where  $H$  is the total GeSNR channel Hamiltonian,  $\Sigma$  matrices denote source (S) and drain (D) retarded contact self-energies that account for OBCs, and  $i\eta$  is the infinitesimal positive imaginary convergence constant used to ensure the physically relevant causal result. The NEGF framework is implemented in our in-house code [4,5,10] which is used for the calculation of size-dependent properties of GeSNRs. Contacts are assumed to be ideal, i.e. semi-infinite regions made up of the same material as the channel, with the Sancho-Rubio method [18] employed for a numerically-efficient calculation of S/D contact self-energy matrices.

Electronic and transport properties are calculated using NEGF, including S/D transmission ( $T_{SD}$ ) and density of states (DOS), which are used within the top-of-the-barrier (ToB) model [19] to study the ballistic performance of  $n$ -channel GeSNR MOSFETs. The ToB model provides the thermionic current and the calculations depend on the self-consistent ToB potential that represents the S/D barrier height, source and drain Fermi-Dirac functions, and Fermi levels for charge neutrality in S/D regions, DOS and  $T_{SD}$ . Since only the thermionic current above the ToB potential is calculated, the ToB model is a dependable method for FETs with channel lengths  $>15$  nm where direct S/D tunneling is negligible [19]. Gate oxide has EOT = 1 nm, and S/D doping is set at 0.001 M fraction of the GeS areal density. In all devices, we set a common  $V_{TH}$  of 0.24 V as projected in the International Roadmap for Devices and Systems (IRDS) at the "3 nm" logic node [20]. In turn, this  $V_{TH}$  results in a very low OFF-state current ( $I_{OFF}$ ) of 0.87 nA/ $\mu$ m due to the 60 mV/dec subthreshold slope and ideal gate control over the channel that are assumed in the ToB model. The ballistic ON-state current ( $I_{ON}$ ) is extracted at  $V_{GS} = V_{DS} = 0.7$  V, i.e. when both gate and drain are biased at the supply voltage.

## 2. Results and discussion

Fig. 1 shows the top (Fig. 1a) and side (Fig. 1b) view of a relaxed 1.86 nm-wide armchair GeS nanoribbon structure passivated with H atoms. GeS exhibits buckled orthorhombic structure and after relaxation, a slight shift of the edge Ge and S atoms are observed and visible in Fig. 1a. In Fig. 2 bandgap is shown for various nanoribbon widths. Scaling down nanoribbon width increases the bandgap ( $E_g$ ) from 1.73 eV

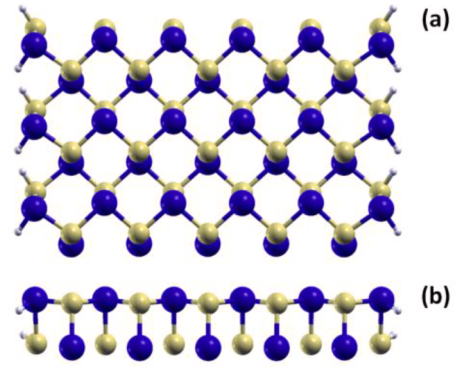


Fig. 1. (a) Top and (b) side view of the monolayer GeS nanoribbon with armchair edges.

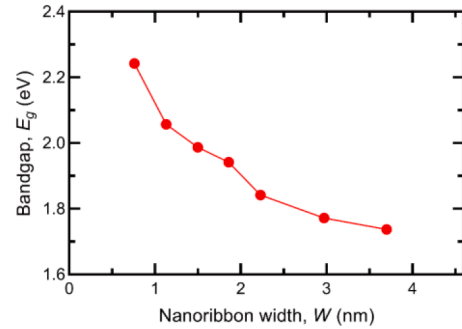


Fig. 2. Impact of width-scaling on the bandgap of armchair GeSNRs.

for  $W = 3.70$  nm to 2.24 eV for  $W = 0.76$  nm. The bandstructure plots for GeSNRs of various widths, reported in Fig. 3, show that  $E_g$  of wider GeSNRs is indirect while scaling down the nanoribbon width below  $W = 2.23$  nm transitions GeSNRs into a direct semiconductor which agrees with the results in [7]. Effective mass ( $m^*$ , in units of  $m_0$ ) of the lowest conduction band is calculated and reported in Fig. 3. Effective mass increases while scaling down nanoribbon width from  $m^* = 0.276$  for  $W = 3.70$  nm to  $m^* = 1.143$  for  $W = 0.76$  nm. The effective mass is high even for the widest nanoribbons when compared to  $m^*$  of the lowest conduction band in 2D GeS alongside armchair direction ( $m^* = 0.2$  was reported in [21]). In Fig. 4 the width-dependence of the ON-state current for armchair GeSNR MOSFETs is shown. The ON-state current decreases monotonically while scaling down the GeSNR width, from  $I_{ON} = 1.20$  mA/ $\mu$ m for  $W = 3.70$  nm to  $I_{ON} = 0.65$  mA/ $\mu$ m for  $W = 0.76$  nm. The performance of GeSNR FETs is directly related to the channel bandstructure along nanoribbon transport direction, as reported in Fig. 3 since mobile charge density depends on the density of states (DOS), and the transmission function determines transport probability for each conducting mode. Subbands nearest to the conduction band minimum (CBM) have the highest influence on the ON-state current in  $n$ -channel FETs. For nanoribbons with  $W = 2.97$  nm and  $W = 3.70$  nm,  $I_{ON}$  values are approximately the same due to bandstructure similarity near the CBM for both GeSNRs. To further clarify the  $I_{ON} - W$  curve, transmission and DOS are plotted in the  $\sim 200$  meV energy range from the CBM, with CBM shifted to 0 eV for an easier comparison of different GeSNRs as shown in Fig. 5. Nanoribbons with  $W = 3.70$  nm and  $W = 2.97$  nm show DOS and transmission characteristics that match almost perfectly for energies up to 0.11 eV away from the CBM, where the contribution to the current is the highest, thus resulting in the same  $I_{ON}$ . The 2.23 nm-wide GeSNR presents a transitional nanoribbon because the lowest sub-bands nearest to the CBM start moving away from the CBM as  $W$  decreases further (e.g. compare Fig. 3c and d). This subband shift directly translates into the significant  $I_{ON}$  drop while scaling the GeSNR

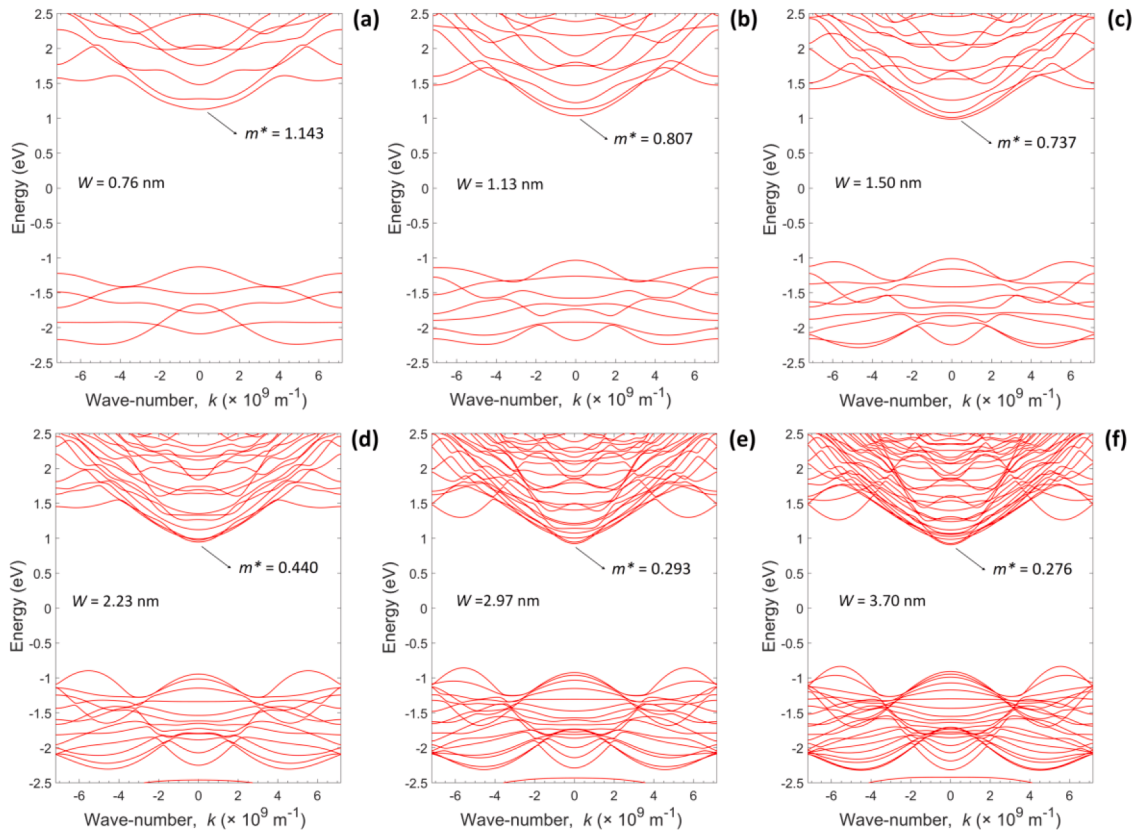


Fig. 3. Bandstructure of GeSNRs with the widths of (a)  $W = 0.76$  nm, (b)  $W = 1.13$  nm, (c)  $W = 1.50$  nm, (d)  $W = 2.23$  nm, (e)  $W = 2.97$  nm, and (f)  $W = 3.70$  nm with extracted effective mass (in units of  $m_0$ ) of electrons in the lowest conduction band.

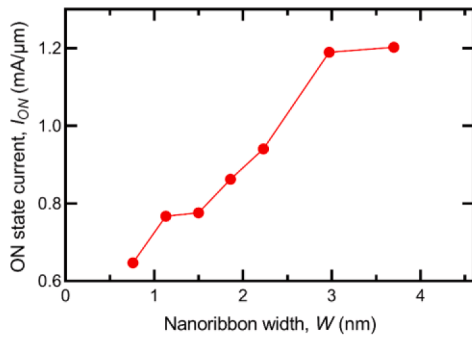


Fig. 4. Width-dependence of the ON-state current extracted at 0.7 V supply voltage in armchair GeSNR FETs.

width from 2.97 nm to 2.23 nm observed in Fig. 4. For GeSNRs with  $W < 2.23$  nm the subband with lower curvature, i.e. higher effective mass, becomes the lowest subband that dominantly determines the overall transport. This property, alongside the lower number of available bands/modes due to the lower number of available orbitals in narrower GeSNRs, further decreases  $I_{ON}$  in ultra-scaled GeSNR FETs. None of the analyzed devices fulfills IRDS specification for  $I_{ON}$  at the “3 nm” node, but the ON-state performance can be somewhat improved by optimizing the EOT, doping, etc., which is beyond the scope of this work. On the other hand,  $I_{ON}/I_{OFF}$  reaches  $\sim 7 \times 10^5$  even in the worst case, indicating good switching capabilities of GeSNR FETs for logic applications.

### 3. Conclusions

We employ NEGF with MLWF Hamiltonians to study the electronic, transport and ballistic device properties of sub-4 nm-wide and  $\sim 15$  nm-

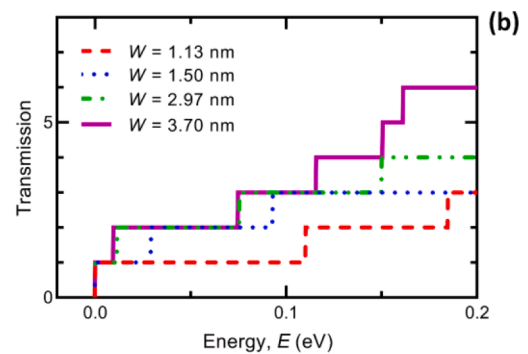
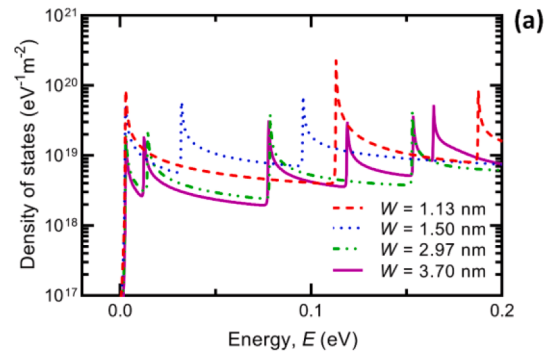


Fig. 5. (a) Density of states and (b) transmission comparison for armchair GeSNRs with the widths of  $W = 1.50$  nm (dotted blue line),  $W = 1.86$  nm (dashed red line),  $W = 2.97$  nm (dot-dot-dashed green line), and  $W = 3.70$  nm (purple line). (For interpretation of the references to colour in this figure legend, the reader is referred to the web version of this article.)



long GeSNRs. The  $I_{ON}/I_{OFF}$  ratio of at least  $\sim 7 \times 10^5$  is observed for ultra-scaled GeSNR FETs, which indicates good switching performance for digital logic devices. The ON-state performance deteriorates as the GeSNR width is scaled down, with the maximum ballistic  $I_{ON}$  of  $\sim 1.20$  mA/ $\mu$ m achieved for the widest analyzed GeSNR FET with  $W = 3.70$  nm. While GeSNR FETs do not meet the IRDS requirements at the “3 nm” CMOS node and beyond, further performance improvement of GeS-based nanodevices is possible by doping and gate-stack engineering. Nevertheless, future work must also consider carrier scattering and dissipative transport for a realistic assessment. [9].

### Declaration of Competing Interest

The authors declare that they have no known competing financial interests or personal relationships that could have appeared to influence the work reported in this paper.

### Data availability

Data will be made available on request.

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## **Publication 5**

### **Validity of the Ballistic Top-of-the-Barrier Model for FETs Based on 2D Material Nanoribbons**

M. Matić and M. Poljak, “Validity of the Ballistic Top-of-the-Barrier Model for FETs Based on 2D Material Nanoribbons,” in *2024 47th MIPRO ICT and Electronics Convention (MIPRO)*, 2024, pp. 1596–1601.

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# Validity of the Ballistic Top-of-the-Barrier Model for FETs Based on 2D Material Nanoribbons

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**Abstract**—We investigate our in-house implementation of the non-equilibrium Green's function (NEGF) formalism in combination with the top-of-the-barrier (ToB) ballistic model, as implemented in our QUDEN (from Quantum-transport Device Engineering in Nanoelectronics) simulator. We calibrate QUDEN on self-consistent NEGF-Poisson simulations of graphene nanoribbon (GNR) field-effect transistor (FET) with ~15 nm channel in the commercial software QuantumATK. It is demonstrated that QUDEN device predicting ability is adequate for nanoribbon-based FETs, except in materials with ultra-low effective mass. QUDEN is then employed to explore monolayer zirconium-disulfide ( $ZrS_2$ ) nanoribbon ( $ZrS_2NR$ ) nFETs, using Hamiltonians from density functional theory (DFT) calculations. We show that  $ZrS_2NR$  nFET exhibits 32% lower ON-state current compared to GNR nFET, which is attributed to 36% higher electron effective mass in  $ZrS_2NR$ s than in GNRs. Our results show that DFT-based Hamiltonians and NEGF-ToB model can be efficiently used for accurate investigation of nanoribbon-based devices.

**Keywords**—Non-equilibrium Green's function (NEGF), top-of-the-barrier (ToB) model, zirconium-disulfide ( $ZrS_2$ ), nanoribbon, density functional theory (DFT), QuantumATK

## I. INTRODUCTION

Research focus on two-dimensional (2D) materials is growing at a fast pace since the discovery of graphene in 2004 [1]. Due to their superior electronic and transport properties, 2D materials are considered as potential candidates to replace silicon in future electronic devices [2], [3]. Recently, more than 1800 2D materials were discovered by *ab initio* calculations [4], with 100 of them studied in a search for the best performing 2D material for future logic field-effect transistors (FETs) [5]. Currently, research focus in the literature is on group-IV monolayers (graphene, silicene, germanene, stanene) [6], [7], [8], group-V monolayers (phosphorene, arsenene, antimonene) [9], [10], and transition metal dichalcogenides (TMDs, e.g.  $MoS_2$ ,  $SnS_2$ ,  $WS_2$ , etc.) [11], [12], [13]. Additionally, 2D materials can be configured in various structures such as nanoribbons [14], nanosheets [15], and nanowires [16], which gives additional degrees of freedom to engineer their properties.

Although many 2D materials have undergone theoretical and numerical studies, most have not yet been successfully experimentally isolated. Given the vast array

of possibilities, advanced modeling and simulation are needed for future development of 2D material-based FETs and other devices [17]. The needed advanced approaches must incorporate the underlying electronic and transport physics of these materials. Currently, the best and most advanced numerical simulators are based on self-consistent solving of the non-equilibrium Green's function (NEGF) formalism equations in combination with solving the 3D Poisson equation, while the materials themselves are described using the *ab initio* density functional theory (DFT) or semiempirical tight-binding (TB) Hamiltonians. However, self-consistent NEGF-Poisson comes at an expense of a very high computational cost and that fact motivated the development of the top-of-the-barrier (ToB) model [18]. The ToB model was applied and investigated previously [19], [20] and it was proven useful for FETs with channel lengths above 15 nm where direct tunneling is negligible.

In this paper, we validate our implementation of the NEGF-ToB numerical model implemented in our MATLAB in-house simulator of nanoribbon FETs designated QUDEN (from Quantum-transport Device Engineering in Nanoelectronics). For a valid assessment of the QUDEN simulator, we compare the performance of a single-gate FET with a 1.11 nm-wide graphene nanoribbon (GNR) obtained in QUDEN with the results obtained by modeling the same device in the commercial software package QuantumATK (QATK) [21] that employs self-consistent NEGF-Poisson calculations. After validating and calibrating QUDEN, we investigate the ballistic performance of zirconium-disulfide ( $ZrS_2$ ) nanoribbon ( $ZrS_2NR$ ) FET with the channel length of ~15 nm and channel width of 1.42 nm.

## II. METHODOLOGY

The assessment of QUDEN starts with the simulation of a single-gate GNR FET in QUDEN and QATK. For a fair comparison we set the same device parameters in both simulators with the GNR Hamiltonian based on the Hancock TB model [22]. After the verification, QUDEN is used to study device performance of a  $ZrS_2NR$  FET and material properties of  $ZrS_2NR$ . The  $ZrS_2NR$  Hamiltonian is obtained using *ab initio* DFT simulations and is then

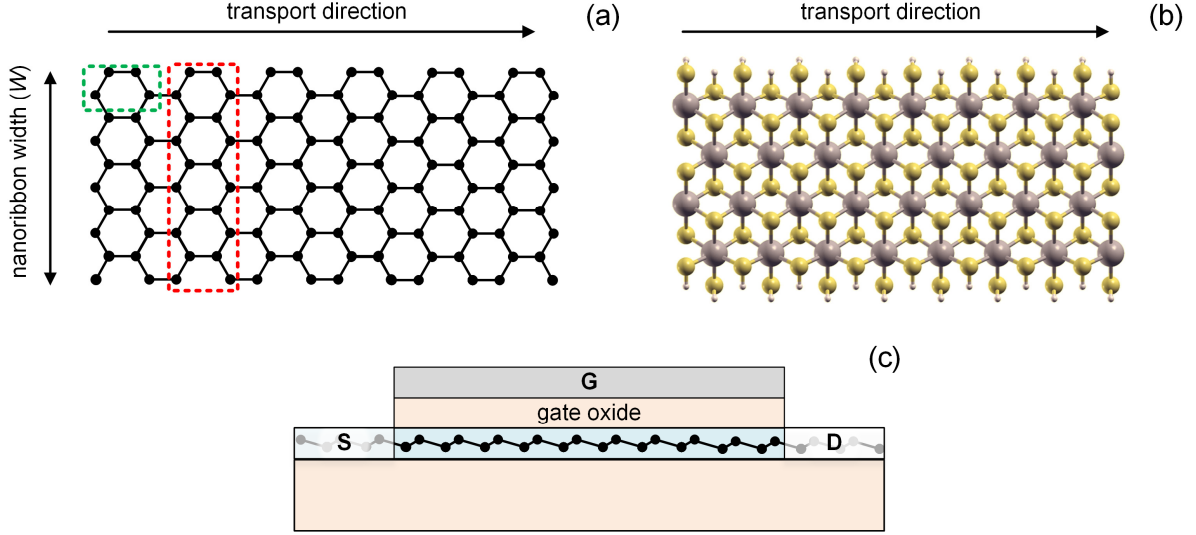


Fig. 1. Top view on the structure of (a) GNR with  $W = 1.11$  nm, and (b)  $\text{ZrS}_2\text{NR}$  with  $W = 1.42$  nm. Panel (a) also marks the unit cells used in the construction of the tight-binding GNR Hamiltonian. (c) Illustration of a single-gate FET with a nanoribbon channel.

transformed into a TB-like basis using the maximally-localized Wannier functions (MLWF) formalism.

#### A. Atomistic Nanoribbon Hamiltonians

The GNR Hamiltonian is constructed using the Hancock TB model with up to the third-nearest-neighbor interaction included, i.e.  $t_1 = 2.7$  eV,  $t_2 = 0.2$  eV, and  $t_3 = 0.18$  eV. Construction of the GNR in QATK is straightforward using a built-in plugin designed to generate nanoribbons. On the other hand, in QUDEN the GNRs are constructed using a 4-atom unit cell (smaller green rectangle in Fig. 1a) that is repeated in the confined direction to construct a super-cell along the GNR width (larger red rectangle in Fig. 1a). To create the total channel Hamiltonian, the super-cell is repeated along the transport direction for the desired nanoribbon length. Later in the text we explore the properties of  $\text{ZrS}_2\text{NR}$  FETs, and the Hamiltonian of the 1.42 nm-wide  $\text{ZrS}_2\text{NR}$  with H-passivated edges (illustrated in Fig. 1b) is obtained by employing the plane-wave DFT, implemented in Quantum Espresso (QE) [23]. Transformation into MLWF Hamiltonians is done using Wannier90 software tool [24], which results in space-localized Hamiltonians suitable for quantum transport simulations. In QE, we use plane augmented wave (PAW) pseudopotential with the Perdew-Burke-Ernzerhof [25] (PBE) exchange-correlation functional. The MLWF localization depends mainly on trial orbitals that are set as follows:  $d$  orbitals for Zr atoms,  $p$  orbitals for S atoms and  $s$  orbitals for H atoms. Other main inputs together with simulation and parameter details are the same as in our previous work on hafnium-disulfide nanoribbons [26].

#### B. Brief Description of QUDEN

The NEGF formalism is used to directly solve the Schrödinger's equation with open boundary conditions for

a system of choice [27], [28], i.e. a FET channel in the form of a nanoribbon in our case. The main term of the NEGF formalism is the energy-dependent retarded Green's function of the device defined as

$$G^R(E) = [(E + i\eta)I - H - \Sigma_S^R(E) - \Sigma_D^R(E)]^{-1}, \quad (1)$$

where  $E$  is the energy,  $\eta$  is an infinitesimal number (convergence constant),  $H$  is total channel Hamiltonian, while interaction with source and drain contacts is represented with retarded contact self-energies, i.e.  $\Sigma_S^R$  and  $\Sigma_D^R$ . Contacts are assumed to be ideal, i.e. made of the same material as the channel, and hence the contact self-energy matrices are calculated using the iterative Sancho-Rubio method [29].

The ToB model [18] is used to assess the ballistic FET performance, with the device illustrated in Fig. 1c. The main inputs of the ToB model from NEGF are transmission and density of states (DOS). Within the ToB model, the transistor is modeled with only three points: top-of-the-barrier potential that represents the barrier height between the source and drain (S/D) regions, and with S/D Fermi levels. In ToB, carrier tunneling is not included and therefore only the thermionic component of current is calculated. Nevertheless, the potential points are calculated self-consistently along with charge density, and charge neutrality of S/D regions is maintained. Therefore, as shown previously [30], [31], [32], the NEGF-ToB approach presents a predictive model only for sufficiently long channels and wide bandgaps.

#### C. Brief Description of Quantum ATK

QATK simulations of GNR FETs are performed using the self-consistent solution of the 3D Poisson equation for electrostatics together with solving 1D NEGF equations for transport. Within QATK, the Poisson equation is

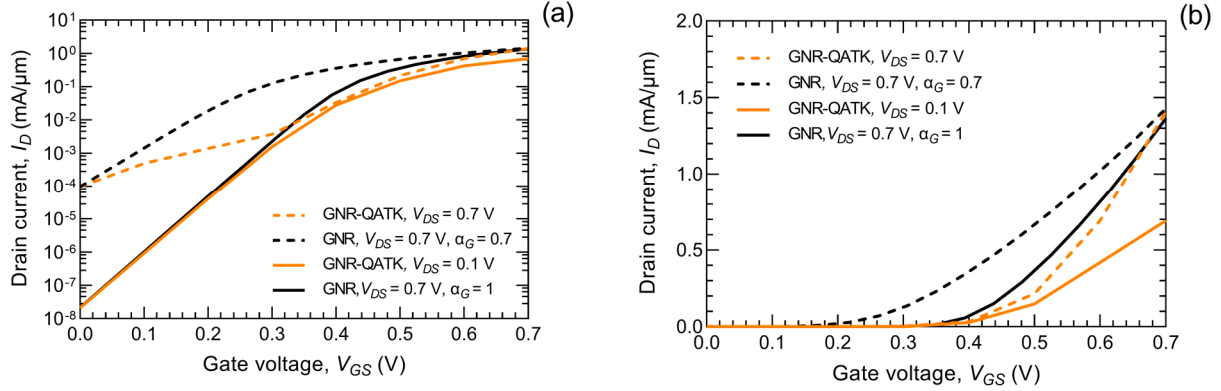


Fig. 2. Transfer characteristics of GNR FET with  $W = 1.11$  nm in (a) logarithmic and (b) linear scale. Comparison is done between the results obtained by the commercial package QATK and by our in-house QU DEN code.

solved using the multigrid Poisson solver with Neuman boundary conditions (BCs) in the confined directions and Dirichlet BCs in the transport direction. The NEGF equations are calculated by separation into the equilibrium and non-equilibrium parts, with the equilibrium part being solved using a semi-circle double-contour on the imaginary axis method [33], [34], whereas the non-equilibrium part is solved on the real axis with a dense energy grid of  $dE = 0.027$  eV.

### III. RESULTS AND DISCUSSION

An identical single-gate GNR FET is defined in QATK and in our in-house QU DEN simulator. For all devices we set the same parameters as follows: channel length of  $\sim 15$  nm, oxide thickness ( $t_{ox}$ ) of 1 nm with  $\epsilon_r = 3.9$  (for  $\text{SiO}_2$ ), and S/D doping is set to 0.01 molar fraction of the areal atom density of the channel material, i.e.  $N_D = 4.3 \times 10^{12} \text{ cm}^{-2}$ . To compare QU DEN to QATK, in Fig. 2 we report the transfer characteristics in the logarithmic and linear scale.

The GNR FET is simulated in QATK for  $V_{DS}$  set to 0.1 V and 0.7 V. For  $V_{DS} = 0.1$  V we obtain a near ideal subthreshold swing (SS) of 62 mV/dec, while for  $V_{DS} = 0.7$  V the SS increases significantly and reaches  $\sim 200$  mV/dec. The observed very high SS is a result of significant increase of the drain current for gate bias below  $V_{GS} = 0.3$  V due to direct and band-to-band tunneling (BTBT), which also results in a very high OFF-state current ( $I_{OFF}$ ) of  $\sim 10^{-7}$  A/μm.

In the first QU DEN simulation we set the ideal gate control within the ToB model, as defined by parameter  $\alpha_G$  [18], i.e.  $\alpha_G = 1$ , while the OFF-state current is set to the value obtained for QATK-GNR at  $V_{DS} = 0.1$  V. This assumption is viable because under the threshold voltage ( $V_{th}$ ) the BTBT is negligible and results in near ideal SS, as expected in the idealized ballistic ToB model. Comparison of the transfer characteristics of GNR FETs at  $V_{DS} = 0.7$  V in QU DEN (with  $\alpha_G = 1$ ) and QATK demonstrates the same  $V_{th}$  of 0.33 V, if calculated by the

IRDS definition [35]. A great mismatch between QU DEN and QATK is clearly visible for  $V_{GS} < 0.3$  V in Fig. 2a, and this is caused by stronger tunneling at higher drain bias, and QU DEN does not account for any type of tunneling. However, for  $V_{GS} > 0.3$  V the transfer characteristics in Fig. 2b (full black line and dashed orange line) show near-perfect match for  $V_{GS}$  between 0.6 V and 0.7 V, i.e. in the ON-state current ( $I_{ON}$ ). This bias range is the most relevant region because all future CMOS nodes are expected to feature the supply voltage values in the 0.6 - 0.7 V span. In the ON-state at  $V_{DS} = V_{GS} = 0.7$  V, QATK simulation gives  $I_{ON} = 1.41$  mA/μm, while QU DEN provides a somewhat lower  $I_{ON}$  of 1.37 mA/μm, i.e. a difference of 3% compared to QATK.

For the second QU DEN simulation, we set the OFF-state current to that obtained by QATK at  $V_{DS} = 0.7$  V, i.e. increased leakage visible in Fig. 2a, and find the  $\alpha_G$  needed for the QU DEN simulation to match both the ON- and OFF-state current from the QATK simulation. We find  $\alpha_G = 0.7$ , and this value sets the correct  $I_{OFF}$  of  $\sim 10^{-7}$  A/μm, but also results in an unrealistically low SS of 85 mV/dec, much lower than  $\sim 200$  mV/dec obtained in QATK. Furthermore, setting the  $\alpha_G$  to 0.7 shifts the transfer characteristic current value up, which consequently lowers the threshold voltage from 0.33 V to 0.16 V, as seen in Fig. 2b. Nevertheless, for devices with similar bandgaps and effective transport mass, the choice of  $\alpha_G = 0.7$  should result in similar BTBT and  $I_{OFF}$ . Therefore, the resulting ON-OFF current ratio, needed to assess the logic device switching performance, can be considered reliable. Finally, simulation wall-time to obtain a single 8-point  $I$ - $V$  curve in QATK is 3 hours, while QU DEN provides the same in less than a minute, when the simulation is run on the same 8-core CPU. We argue that even for a FET with a very sparse Hamiltonian, as in the case of tight-binding GNR Hamiltonians, computational burden in QATK is very high. Additionally, simulation of devices in QATK with materials defined by DFT, which is also possible within the QATK package, would require prohibitive resources for our computational cluster.

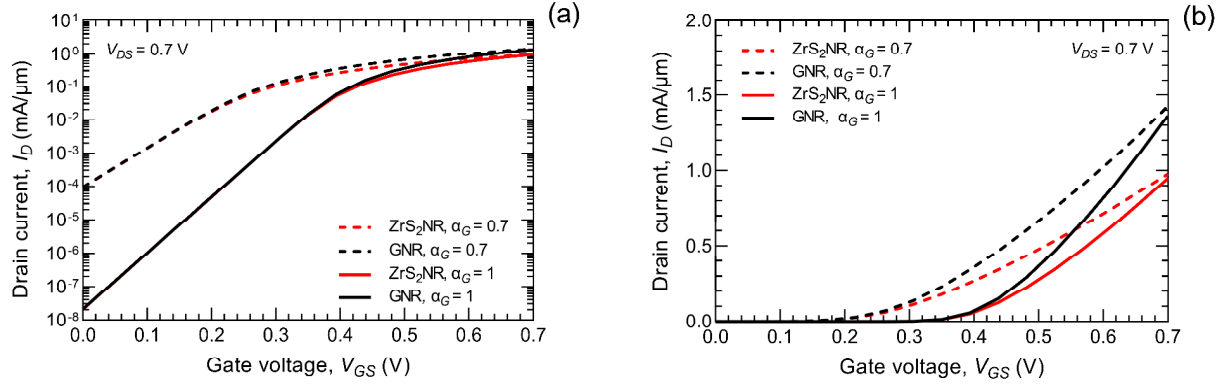


Fig. 3. Transfer characteristics of the ZrS<sub>2</sub>NR FET with  $W = 1.42$  nm and the GNR FET with  $W = 1.11$  nm simulated in QUDEX. Logarithmic scale is used in (a), while a linear scale is shown in (b).

Now that we have shown that QUDEX can be used for the assessment of FETs with nanoribbon channels in the ON-state, we employ it to study the ZrS<sub>2</sub>NR and the corresponding FET. The 2D material ZrS<sub>2</sub> is chosen since it has shown promise for 2D FETs in [5], whereas the one-dimensional counterparts such as ZrS<sub>2</sub>NRs have not yet been studied. The ZrS<sub>2</sub>NR width of 1.42 nm is chosen to have the same band gap as the previously mentioned and studied 1.11 nm-wide GNR. In Fig. 3 we compare the current-voltage characteristics of the ZrS<sub>2</sub>NR FET with GNR FET simulated in QUDEX. Both devices are numerically investigated for two cases, i.e. two sets of  $I_{OFF}$  and  $\alpha_G$  values discussed earlier. In the sub-threshold region, ZrS<sub>2</sub>NR FET and GNR FET characteristics match perfectly for both  $\alpha_G$  values, as shown in Fig. 3a. However, above  $V_{th}$  the ZrS<sub>2</sub>NR FET performs worse than GNR FET with a 32% lower ON-state current in the ZrS<sub>2</sub>NR FET than GNR FET. Similarly to GNR FETs, in the ZrS<sub>2</sub>NR FET we also obtain a 3% higher  $I_{ON}$  for  $\alpha_G = 0.7$  (0.978 mA/μm) compared to  $I_{ON} = 0.95$  mA/μm when  $\alpha_G = 1$ . Threshold voltage is the same for the ZrS<sub>2</sub>NR FET and GNR FET, with  $V_{th} = 0.33$  V for  $\alpha_G = 1$  and lower  $V_{th} = 0.16$  V for  $\alpha_G = 0.7$  as previously discussed. Finally, we calculate the  $I_{ON}/I_{OFF}$  ratio for the ZrS<sub>2</sub>NR FET and obtain  $10^4$  and  $4.5 \times 10^7$  for  $\alpha_G$  of 0.7 and 1, respectively. These results show that ZrS<sub>2</sub>NR FETs can fulfil IRDS requirements on the switching ratio if gate control over the channel is strong, i.e. if  $\alpha_G$  is close to unity, which is feasible due to the quasi-one-dimensional nature of ZrS<sub>2</sub>NRs.

Further insight into the material properties of the 1.42 nm-wide ZrS<sub>2</sub>NR is obtained by plotting the band structure, density of states (DOS), and transmission. The band structure of studied GNR and ZrS<sub>2</sub>NR is shown in Fig. 4. Both nanoribbons exhibit a direct bandgap ( $E_G$ ) with  $E_G = 0.95$  eV for the ZrS<sub>2</sub>NR and  $E_G = 0.91$  eV for the GNR. Bandstructure effective mass ( $m^*$ ), extracted using a parabolic approximation, of the dominant (lowest) subband in the conduction band (CB) is  $0.25m_0$  for the ZrS<sub>2</sub>NR, while for the GNR we get  $m^* = 0.16m_0$ . The very

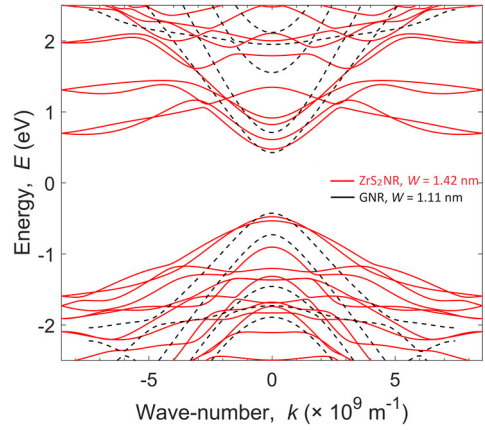


Fig. 4. Comparison of the bandstructure of the 1.42 nm-wide ZrS<sub>2</sub>NR and 1.11 nm-wide GNR.

low bandstructure effective mass in the GNR is the main reason for high BTBT at high drain bias in QATK simulations that account for tunneling. Due to the higher  $m^*$  and  $E_G$  in the ZrS<sub>2</sub>NR, the tunneling in the ZrS<sub>2</sub>NR FETs will be lower in ZrS<sub>2</sub>NR FETs [5]. Hence, lower BTBT will result in much higher  $I_{ON}/I_{OFF}$  in ZrS<sub>2</sub>NR FETs than in GNR FETs, with  $I_{ON}/I_{OFF}$  closer to the maximum  $I_{ON}/I_{OFF}$  of  $\sim 4.5 \times 10^7$  obtained for FET with an ideal electrostatic gate control over the channel.

Finally, we report the transmission and DOS in the conduction band of the 1.42 nm-wide ZrS<sub>2</sub>NR and the 1.11 nm-wide GNR in Fig. 5a and b, respectively. In Fig. 5, the conduction band minimum (CBM) is set at 0 eV. Transmission is unity for both the GNR and ZrS<sub>2</sub>NR up to the energy CBM + 0.13 eV, while for higher energies the ZrS<sub>2</sub>NR exhibits higher transmission with the maximum of four for energies above CBM+0.2 eV. However, up to CBM + 0.1 eV, which presents the most important energy range for carrier transport, transmission is the same in both devices. Clearly, higher conducting subbands are not activated in ZrS<sub>2</sub>NRs because GNR FET

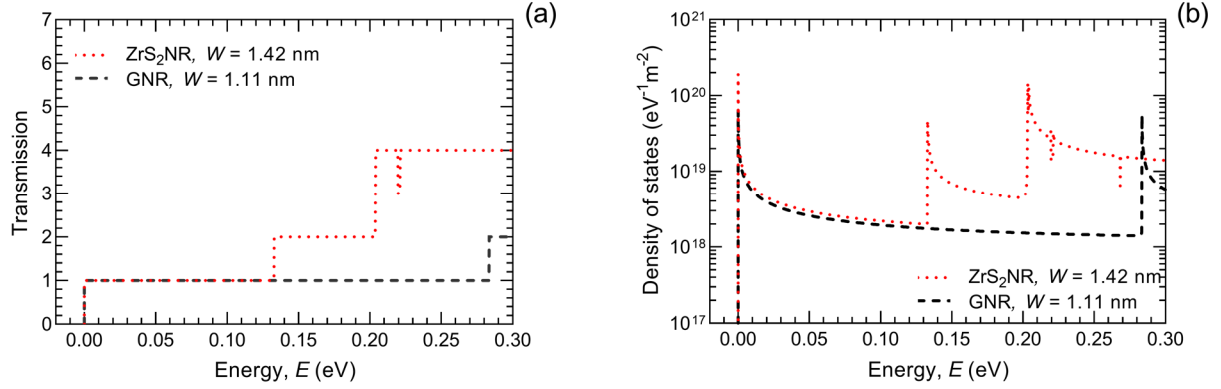


Fig. 5. (a) Transmission, and (b) density of states in the conduction band of ZrS<sub>2</sub>NR with  $W = 1.42$  nm and GNR with  $W = 1.11$  nm. Conduction band minimum is set at 0 eV.

exhibits higher drain current than ZrS<sub>2</sub>NR FET (see e.g. Fig. 3b). Additionally, we explore DOS in Fig. 5b in which the ZrS<sub>2</sub>NR shows higher DOS generally near the CBM with a higher number of Van Hove singularities when compared to the GNR. While higher DOS leads to a higher density of conducting electrons and higher currents, the higher DOS in the ZrS<sub>2</sub>NR (Fig. 5b) is also directly connected to the higher curvature of the lowest electronic subband, i.e. higher electron effective mass (Fig. 4). The lower ON-state performance of the ZrS<sub>2</sub>NR FET can be attributed to the larger effective transport mass of electrons in the 1.42 nm-wide ZrS<sub>2</sub>NR with respect to the GNR with  $W = 1.11$  nm. We note that even though the ON-state performance of ZrS<sub>2</sub>NR FETs is lower, the higher  $m^*$  in ZrS<sub>2</sub>NRs can be beneficial for the applicability of the ToB model. Namely, larger effective transport mass decreases tunneling probability, thus suppressing the influence of BTBT, which enables NEGF-ToB to be a predictive tool over a wider range of biases.

#### IV. CONCLUSIONS

We assess the validity of our in-house implementation of the NEGF-ToB approach in QUDEN on a single-gate GNR FET by comparing it to the commercial software package QuantumATK. Transfer characteristics exhibit an excellent match for gate bias above 0.6 V, which indicates that QUDEN can properly assess the ON-state performance of nanoribbon devices with the gate-control parameter from the ToB model being  $\alpha_G = 1$ , while the OFF-state leakage can be adequately addressed with  $\alpha_G = 0.7$  since the ToB model does not account for direct tunneling or BTBT. The verified QUDEN is then employed to explore the properties of the ZrS<sub>2</sub>NR FET, in which the nanoribbon is 1.42 nm wide and with the same bandgap ( $\sim 0.9$  eV) as the GNR. We report a 32% lower ON-state current of the ZrS<sub>2</sub>NR FET compared to the GNR FET, which we attribute mainly to the 36% higher effective electron mass in the ZrS<sub>2</sub>NR. Nevertheless, a high  $I_{ON}/I_{OFF}$  of  $4.5 \times 10^7$  is achievable in the ZrS<sub>2</sub>NR FET, which makes it a plausible device for efficient digital switching according to IRDS requirements. Finally, our results on the GNR and ZrS<sub>2</sub>NR

FETs show that (1) DFT-MLWF Hamiltonians and NEGF are properly implemented in QUDEN, (2) predicting the subthreshold performance for materials with ultra-low effective mass is limited without adjusting the ToB model parameters, but (3) QUDEN can be used to determine the ON-state performance of nanoribbon-based FETs efficiently and accurately.

#### ACKNOWLEDGMENTS

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## **Publication 6**

### **Transport Properties and Device Performance of Quasi-One-Dimensional MoS<sub>2</sub> FETs**

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– 5 pages

# Transport Properties and Device Performance of Quasi-One-Dimensional MoS<sub>2</sub> FETs

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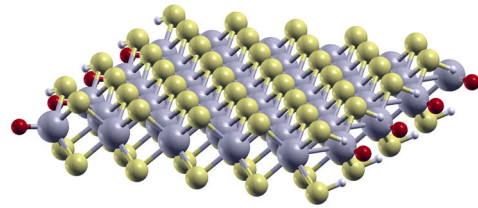
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**Abstract**—We investigated the bandstructure, transport and device properties of semiconducting MoS<sub>2</sub> nanoribbons (MoS<sub>2</sub>NR) with hybrid OH-passivated armchair edges using orbitally-resolved *ab initio* Hamiltonians and quantum transport simulations based on Green's functions. The impact of MoS<sub>2</sub>NR width scaling on the bandstructure, transmission, bandgap, injection velocity, charge density and ON-state current are analyzed in detail using the ballistic FET model. We find that sub-3 nm-wide and ~15 nm-long MoS<sub>2</sub>NR FETs offer low driving currents under 0.43 mA/μm for nFETs and under 0.6 mA/μm for pFETs. Moreover, the current is only weakly modulated by nanoribbon width downscaling due to immunity of the MoS<sub>2</sub>NR bandstructure to quantum confinement effects.

**Keywords**—MoS<sub>2</sub>, molybdenum disulfide, quasi-one-dimensional, nanoribbon, quantum transport, Green's function, NEGF, *ab initio*, DFT, MLWF

## I. INTRODUCTION

Since the discovery of graphene in 2004, research focus on two-dimensional (2D) materials as potential candidates to replace silicon in future electronic devices is growing exponentially [1]–[3]. Atomically-thin and dangling-bond-free surfaces along with near-ballistic transport properties of some 2D materials are ideal for future field-effect transistors (FETs). After graphene, monolayer molybdenum disulfide (MoS<sub>2</sub>) is one of the most studied 2D materials which showed promise due to high stability, compatibility with graphene, and exceptionally high ON/OFF current ratio > 10<sup>8</sup> [4]. The MoS<sub>2</sub> monolayer is a transition metal disulfide (TMD) with a sandwiched S-Mo-S structure, as shown in Fig. 1. Electronic, transport, and device properties of MoS<sub>2</sub> monolayer devices have been studied extensively and it is often used as a benchmark for other 2D materials [5]–[7]. On the other hand, patterning MoS<sub>2</sub> into quasi-one-dimensional (quasi-1D) nanoribbons, which are illustrated in Fig. 1, enables the tuning of electronic and transport properties, with a potential for beneficial adjustment of device properties as well. Although MoS<sub>2</sub> nanoribbons (MoS<sub>2</sub>NRs) in armchair and zigzag directions have been studied previously [8]–[10], due to high influence of edge atoms on the device performance and wide range of possible edge passivation atoms, there are still interesting configurations that have not been explored such as MoS<sub>2</sub>NRs with hybrid OH-



**Figure 1.** Illustration of an MoS<sub>2</sub> nanoribbon with OH-passivated armchair edges (Mo, S, O and H atoms are represented by grey, yellow, red and white balls, respectively).

passivated edges. Electronic properties study in [11] of the hybrid OH-passivated MoS<sub>2</sub>NRs showed that this edge configuration is the most stable among all studied edge passivation configurations and, therefore, presents an interesting choice for future MoS<sub>2</sub> based nanodevices once fabrication becomes mature enough. Therefore, in this work we study the device performance of the hybrid OH-passivated MoS<sub>2</sub>NRs.

Advanced modeling and simulations are used in this study to investigate MoS<sub>2</sub> nanoribbons and MoS<sub>2</sub>NR FETs at an atomic level, which is necessary due to inherently strong quantum effects in 2D material nanostructures. Electronic band structure is calculated using the *ab initio* density functional theory (DFT) and, afterwards, maximally-localized Wannier functions (MLWFs) are employed to transform DFT Hamiltonians into a localized basis. The localized MLWF Hamiltonians are much sparser, thus enabling the simulations of realistically sized nanodevice. Quantum transport in such nanostructures is calculated by using the non-equilibrium Greens function (NEGF) formalism. In this paper, we analyze the electronic, transport and device properties of MoS<sub>2</sub>NR and MoS<sub>2</sub>NR FETs with OH-passivated edges by employing our in-house DFT-NEGF-MLWF solver [12], [13]. We report only a weak impact of MoS<sub>2</sub>NR width scaling from ~3.0 nm to ~0.8 nm on the ballistic performance, which results in small degradation and robust performance of ultra-scaled MoS<sub>2</sub>NR FETs.

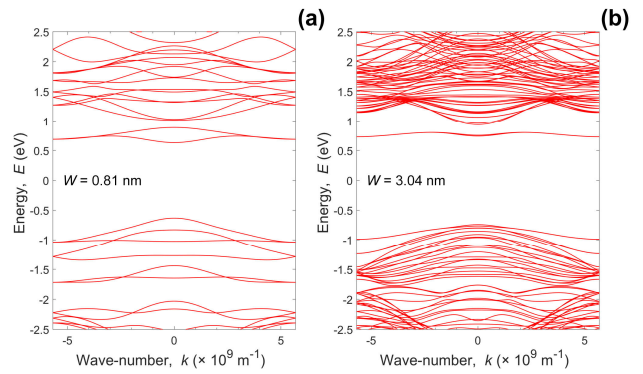
## II. METHODOLOGY

The MoS<sub>2</sub>NR structure of various widths ranging from ~0.8 nm to ~3.0 nm is constructed along the armchair

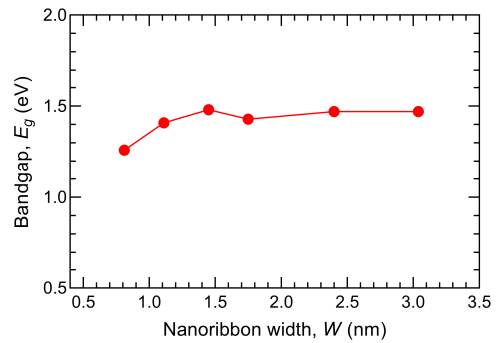
direction from a MoS<sub>2</sub> unit-cell obtained from Materials Cloud [14] and passivated with OH, as shown in Fig. 1. The Mo edge atoms are passivated with O atoms, while S atoms are passivated with H atoms. Plane-wave DFT is used to obtain highly accurate Hamiltonians of MoS<sub>2</sub> nanostructures investigated in this work. Since DFT calculations assumes periodicity in all three directions, we add a vacuum region of 20 Å in confined directions to exclude any interaction between adjacent layers. For DFT calculations we employ Quantum Espresso [15] with Perdew-Burke-Ernzerhof generalized gradient approximation (PBE-GGA) [16] exchange-correlation (XC) functional and projector augmented wave (PAW) pseudopotentials. The Brillouin zone (BZ) is sampled using an 15-point equally-spaced Monkhorst-Pack grid [17] in the transport direction and a single point in the confined directions. The plane-wave cutoff energy is set to 100 Ry, whereas the convergence threshold is set to 10<sup>-3</sup> eV/Å for the ionic force and to 10<sup>-4</sup> eV for energy.

Dense DFT Hamiltonians are localized in energy and are, therefore, not suitable for NEGF quantum transport simulations which prefer sparser matrices, i.e. space-localized Hamiltonians. Transformation into a space-localized basis is performed using the maximally-localized Wannier functions (MLWFs) [18] which results in tight-binding-like sparse matrices. To obtain MLWF Hamiltonians, we use the Wannier90 [19] program. The main inputs of Wannier90 are the trial orbital projections on Bloch manifold, and in this work the trial orbitals for MoS<sub>2</sub>NRs are *d* orbitals for Mo atoms and *p* orbitals for O and S atoms. For all MoS<sub>2</sub>NR widths the Wannier spread smaller than 2.5 Å<sup>2</sup> per atom is obtained. For each nanoribbon width, MLWF Hamiltonians of a MoS<sub>2</sub>NR unit-cell are scaled in the transport direction to construct ~15 nm-long MoS<sub>2</sub>NRs.

For quantum transport simulations we use the NEGF formalism [20]–[22], as implemented in our in-house code [12], [13], [23], [24]. Within NEGF, device is modeled with ideal contacts i.e. semi-infinite regions of the same material as the channel using the recursive Sancho-Rubio method [25]. Top-of-the-barrier (ToB) model [26] is used in combination with NEGF to assess ballistic device performance of ultra-scaled MoS<sub>2</sub>NR FETs with n- and p-type channels. In ToB ballistic FET simulations, gate equivalent oxide thickness (EOT) is set to 1 nm, while source/drain (S/D) region doping levels are set at 0.01 molar fraction of the MoS<sub>2</sub>NR areal atomic density. In all devices we set a common OFF-state current (*I*<sub>OFF</sub>) of 10 nA/μm as projected in the International Roadmap for Devices and Systems (IRDS) for high-performance (HP) devices in future CMOS technology nodes [27]. Gate control over the channel in the ToB model devices is assumed ideal and, since no tunneling is included, ideal 60 mV/dec subthreshold slope is obtained in all devices. The ballistic ON-state current (*I*<sub>ON</sub>) is extracted when both gate and drain are biased at the supply voltage, i.e.  $V_{GS} = V_{DS} = 0.7$  V.



**Figure 2.** Bandstructure of armchair MoS<sub>2</sub>NRs with the widths of (a) 0.81 nm and (b) 3.04 nm.

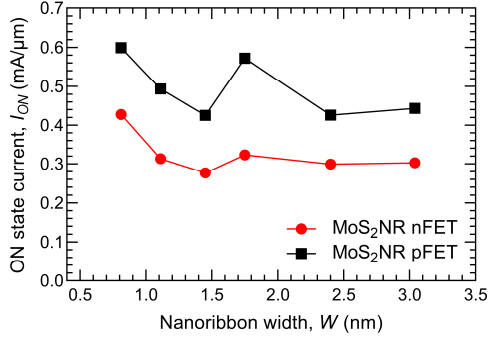


**Figure 3.** Impact of nanoribbon width scaling on the bandgap of armchair MoS<sub>2</sub>NRs.

### III. RESULTS AND DISCUSSION

In Figure 2 we plot the bandstructure of the widest (Fig. 2a) and the narrowest (Fig. 2b) analyzed MoS<sub>2</sub>NR with the widths of  $W = 3.04$  nm and  $W = 0.81$  nm, respectively. Bandstructure plots contain two subbands that are isolated from the rest of the conduction band (CB). These subbands are isolated due to the influence of edge atoms, which also shift the bandgap from indirect to direct with no conclusive pattern. Scaling down nanoribbon width from 3.04 nm to 0.81 nm results in the separation of these two subbands in CB near the  $\Gamma$  point, which also results in higher curvature, i.e. lower electron effective mass, near CB minimum (CBM) for  $W = 0.81$  nm. On the other hand, in the valence band (VB) a higher number of available bands in wider MoS<sub>2</sub>NR results in higher number of bands near the VB maximum (VBM), but the narrowest MoS<sub>2</sub>NR exhibits a higher curvature and lower hole effective mass in the dominant subband near VBM.

Width-dependence of the bandgap ( $E_g$ ), extracted from the bandstructure of MoS<sub>2</sub>NRs of various widths, is reported in Fig. 3. The plot show a nearly constant bandgap of ~1.47 eV for MoS<sub>2</sub>NRs with  $W > 1.4$  nm, while scaling down the width below 1.4 nm results in a sharp  $E_g$  decrease to 1.26 eV in the 0.81 nm-wide MoS<sub>2</sub>NR. The OH-passivated MoS<sub>2</sub>NRs exhibit a similar bandgap compared to 2D monolayer MoS<sub>2</sub> for which we obtain the bandgap of 1.7 eV. This value is in line with



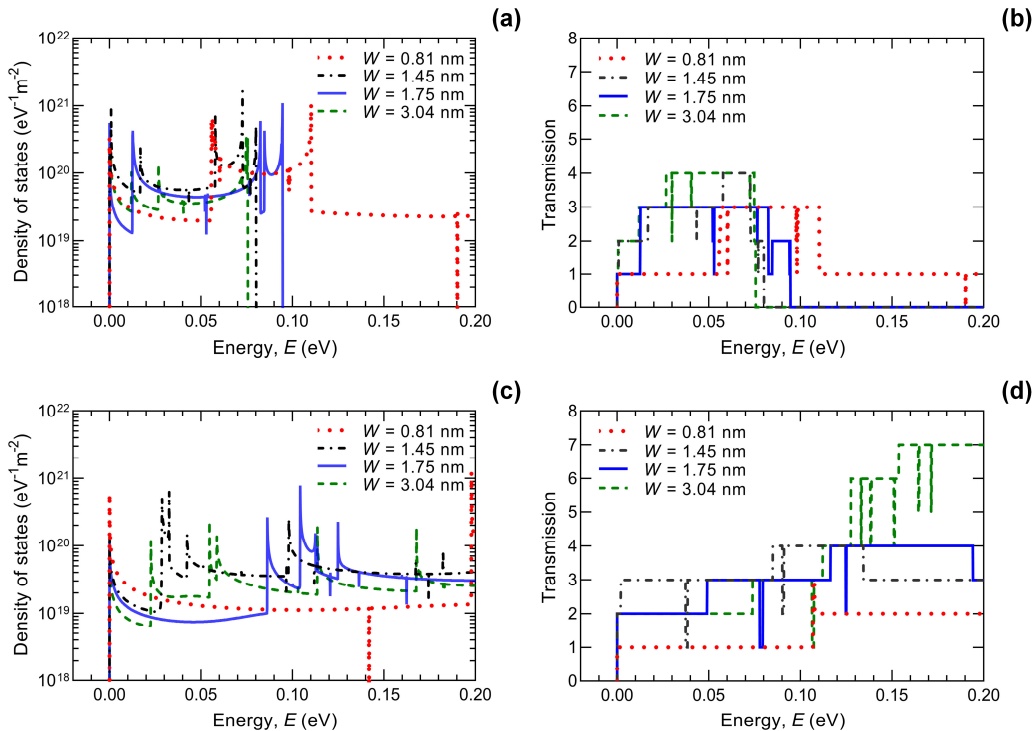
**Figure 4.** Width-dependence of the ON-state current in n- and p-type MoS<sub>2</sub>NR FETs.  $I_{ON}$  extracted at  $V_{GS} = V_{DS} = V_{DD} = 0.7$  V, with a common  $I_{OFF} = 10$  nA set for all devices.

$E_g = 1.67$  eV reported in [11] with the main difference coming from the isolated edge-state bands in the CB.

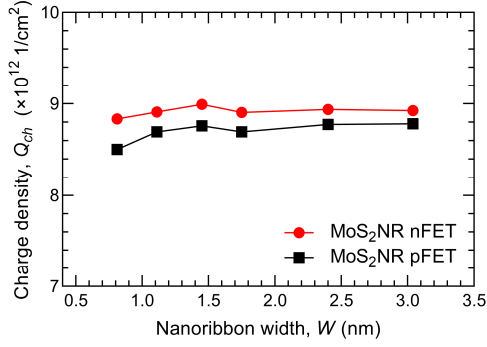
In order to assess the scaling and confinement effects on device performance, we plot the ON-state current in Fig. 4 for different widths and both device types. Both n- and pFETs exhibit similar scaling laws of  $I_{ON}$  with width-downscaling. Qualitatively, we can separate the plot into two groups or two width ranges. The first group includes MoS<sub>2</sub>NR FETs with channel widths from  $W = 3.04$  nm to  $W = 1.75$  nm, which shows increase of  $I_{ON}$  while scaling down MoS<sub>2</sub>NR width. The second group starts with  $W = 1.45$  nm where the  $I_{ON}$  shows a sharp decrease compared to the  $W = 1.75$  nm case, while further width downscaling results in an increase of  $I_{ON}$  down to the 0.81 nm-wide MoS<sub>2</sub>NR FET. The maximum  $I_{ON}$  for both n- and pFETs is obtained for 0.81 nm-wide MoS<sub>2</sub>NR

transistor with  $I_{ON} = 0.43$  mA/μm for the nFET and  $I_{ON} = 0.60$  mA/μm for the pFET. Comparing the obtained  $I_{ON}$  results for MoS<sub>2</sub>NR FETs to IRDS requirements at the “3 nm” and “2.1 nm” nodes, we conclude that the  $I_{ON}$  goal set at 1.9 mA/μm is fulfilled by none of the MoS<sub>2</sub>NR devices explored in this paper.

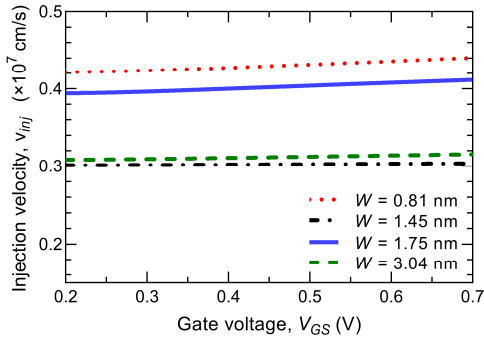
To further understand the behavior of the ON-state current we plot density of states (DOS), transmission, the ON-state charge density ( $Q_s$ ) and injection velocity ( $v_{inj}$ ) at ToB, and the ON-state current energy-density. The DOS and transmission characteristics, plotted separately for electrons and holes i.e. in the CB and VB, are shown in Fig. 5. The DOS near the CBM is similar for all MoS<sub>2</sub>NRs up to ~0.08 eV after which, due to the existence of isolated edge-state bands, there are no free states and DOS goes to zero. There is an exception for  $W = 0.81$  nm where we previously in Fig. 2a observed the broadening of the isolated band near the  $\Gamma$  point. This band broadening results in a nonzero DOS in a broader energy range in comparison to wider nanoribbons. Transmission exhibits similar characteristics as DOS in the CB. At the CBM, transmission equals 1 for the widths of 0.81 nm and 1.75 nm, and sharply increases to 2 at an energy ~20 meV away from the CBM. Interestingly, these MoS<sub>2</sub>NRs have a direct bandgap and show highest drain current of all the simulated MoS<sub>2</sub>NR nFETs. On the other hand, the 1.45 nm-wide and 3.04 nm-wide MoS<sub>2</sub>NRs have a higher transmission equal to 2 at the CBM. This is because these MoS<sub>2</sub>NRs have an indirect bandgap with a lower curvature of the CB dispersion, which results in lower  $I_{ON}$ . On the other hand, in VB we observe that scaling down nanoribbon width decreases the number of Van Hove



**Figure 5.** Comparison of DOS (panels on the left) and transmission (panels on the right) in (a, b) CB and (c, d) VB of MoS<sub>2</sub>NRs of various widths.



**Figure 6.** Width-dependence of the channel charge density at ToB in n- and p-type MoS<sub>2</sub>NR FETs. The  $Q_s$  is extracted in the ON-state, i.e.  $V_{GS} = V_{DS} = V_{DD} = 0.7$  V.



**Figure 7.** Hole injection velocity dependence on gate bias in MoS<sub>2</sub>NR pFETs with various channel widths.  $V_{DS} = V_{DD} = 0.7$  V.

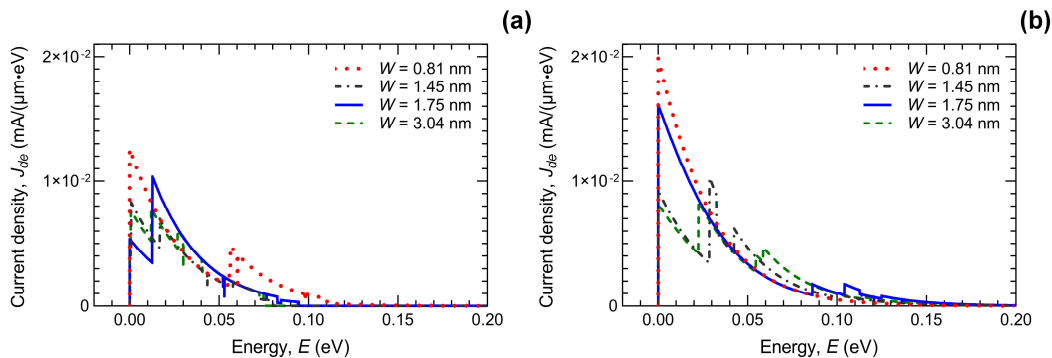
singularities (VHS) in the hole DOS near the VBM due to the lower number of available subbands in narrower MoS<sub>2</sub>NRs. For the same reason, transmission near the VBM decreases while scaling down MoS<sub>2</sub>NR width. When comparing the transport of electrons and holes, we see that holes generally exhibit a higher transmission probability than electrons over the 200 meV energy range away from the VBM or CBM, respectively, which is partly responsible for the higher  $I_{ON}$  in p-type than in n-type MoS<sub>2</sub>NR FETs reported in Fig. 4.

The DOS and transmission exhibit complex characteristics and are unable to provide a clear insight into FET performance. The influence of width scaling on the ON-state charge density at the ToB is plotted in Fig. 6. Despite considerable variations in the DOS, similar values

of  $Q_s$  are obtained for all MoS<sub>2</sub>NR nFETs and pFETs. On average over all nanoribbon widths, electron density is  $\sim 8.9 \times 10^{12} \text{ cm}^{-2}$ , while hole density is somewhat lower and equals  $\sim 8.7 \times 10^{12} \text{ cm}^{-2}$ . The impact of scaling and confinement is visible only in the 0.81 nm-wide MoS<sub>2</sub>NRs that show slightly lower electron and hole density at  $8.8 \times 10^{12} \text{ cm}^{-2}$  and  $8.5 \times 10^{12} \text{ cm}^{-2}$ , respectively. This decrease is due to setting the common  $I_{OFF}$  value, because MoS<sub>2</sub>NR with the width of 0.81 nm has the smallest bandgap and, therefore, the lowest applied bias is needed to set  $I_{OFF}$  which results in slightly lower  $Q_s$  at ToB.

Within the ballistic ToB model, we have  $I_{ON} = Q_s \cdot v_{inj}$  at ToB in the ON-state and, hence, the peculiar  $I_{ON} - W$  characteristic in Fig. 4 is a consequence of the injection velocity behavior [13], [26]. In Fig. 7 we plot the gate bias dependence of  $v_{inj}$  in pFETs, with gate voltage ranging from the threshold voltage ( $\sim 0.2$  V) to supply voltage (0.7 V). Only the  $v_{inj}$  in pFETs is plotted because nFETs do not show any noticeable velocity modulation with the applied gate voltage. On the other hand, hole injection velocity in MoS<sub>2</sub>NR pFETs with the widths of 0.81 nm and 1.75 nm show a slight increase of  $v_{inj}$  with increasing gate bias. The modulation is rather weak, equaling around 5% increase with maximum value obtained in the ON-state of  $0.41 \times 10^7 \text{ cm/s}$  and  $0.44 \times 10^7 \text{ cm/s}$ , respectively. With the proportional relationship of the ON-state current to  $v_{inj}$  and  $Q_s$ , and  $v_{inj}$  showing similar scaling laws as  $I_{ON}$  while  $Q_s$  being of the similar value for all MoS<sub>2</sub>NR widths we determine that ON-state performance is dominantly determined by  $v_{inj}$ . In comparison to other contending 2D materials, MoS<sub>2</sub>NR FETs exhibit significantly lower  $v_{inj}$  that deteriorates up to  $\sim 9\times$  in comparison to graphene nanoribbons, and  $\sim 1.5\times$  when compared against conventional Si MOSFETs [28]. Hence, it is no surprise that the  $I_{ON}$  of MoS<sub>2</sub>NR FETs is lower than in other 2D material devices [28]–[31].

Finally, the ON-state current energy-density ( $J_{de}$ ) for MoS<sub>2</sub>NR nFET (Fig. 8a) and pFET (Fig. 8b) shows that the current flows mostly in the  $\sim 100$  meV energy range above/under the CBM/VBM. This range coincides with the energy range of isolated bands in the CB and, therefore, only the isolated edge-state bands in the CB determine the performance of nFETs. On the other hand, VB offers higher number of available bands in the same energy



**Figure 8.** Current energy-density at ToB in the ON-state for MoS<sub>2</sub>NR (a) nFETs and (b) pFETs with different nanoribbon channel widths.

range, which results in higher  $J_{de}$ , i.e. maxima of  $1.2 \times 10^{-2}$  mA/(eV· $\mu$ m) for nFETs and  $2 \times 10^{-2}$  mA/(eV· $\mu$ m) for pFETs, with both values reached at the CBM and VBM, respectively. Hence, any improvement of MoS<sub>2</sub>NR nFET performance depends on the effective turn-off of the isolated band contribution.

#### IV. CONCLUSIONS

We studied the electronic, transport and ballistic device characteristics of sub-3 nm-wide and ~15 nm-long quasi-1D MoS<sub>2</sub> nanostructures with OH-passivated edges. We employed DFT and MLWFs to obtain the electronic structure, and NEGF simulations with the ToB model to assess the ballistic performance of armchair MoS<sub>2</sub>NR FETs. We found that nFET is limited by the two isolated bands in the CB, which exist due to edge configuration or edge states. The analysis revealed that  $Q_s$  is similar for all MoS<sub>2</sub>NR widths, and that  $I_{ON} - W$  dependence is mainly determined by the features of  $v_{inj}$ . The maximum ON-state current of 0.43 mA/ $\mu$ m is obtained for nFETs and 0.6 mA/ $\mu$ m for pFETs. Therefore, MoS<sub>2</sub>NR FETs passivated with OH do not meet IRDS requirements for advanced nodes unless a method of eliminating edge states and associated isolated bands in the CB is found.

#### ACKNOWLEDGMENTS

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## **Publication 7**

### **Tunneling Attenuation and Leakage Current in MoS<sub>2</sub> Nanoribbon MOSFETs**

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# Tunneling Attenuation and Leakage Current in MoS<sub>2</sub> Nanoribbon MOSFETs

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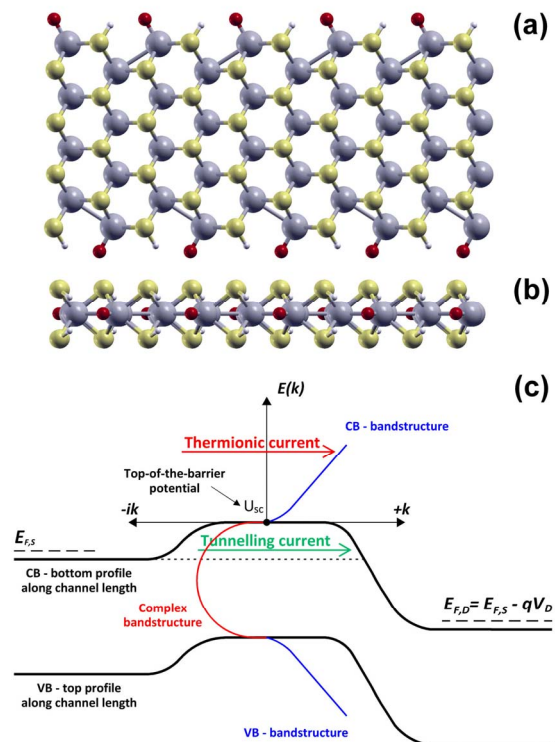
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**Abstract**—We study the OFF-state leakage current in quasi-one-dimensional MoS<sub>2</sub> nanoribbon (MoS<sub>2</sub>NR) FETs using *ab initio* Hamiltonians and quantum transport simulations based on Green's functions. Complex band structure is computed for these devices and the energy-dependent tunneling attenuation inside the bandgap is obtained. We investigate the tunneling component of the OFF-state leakage for sub-20 nm long and sub-3 nm wide MoS<sub>2</sub>NR FETs, using the under-the-barrier (UTB) and top-of-the-barrier (ToB) ballistic models. We report that using the parabolically-approximated attenuation overestimates the OFF-state leakage significantly. Furthermore, we demonstrate that all MoS<sub>2</sub>NR FETs show good tunneling suppression due to high attenuation even for the shortest devices where the OFF-state leakage is under 16.5 nA/μm for nFETs and lower than 22 nA/μm for pFETs.

**Keywords**—MoS<sub>2</sub>, molybdenum disulfide, leakage current, complex bandstructure, tunneling, quasi-one-dimensional, nanoribbon, quantum transport, NEGF, *ab initio*, DFT

## I. INTRODUCTION

Monolayer molybdenum disulfide (MoS<sub>2</sub>), alongside graphene, is one of the most promising two-dimensional (2D) materials for future field-effect transistors (FETs) due to high stability and very high ON-OFF current ratio [1]. The 2D MoS<sub>2</sub> is a transition metal dichalcogenide (TMD) that exhibits a sandwiched S-Mo-S structure as illustrated in Fig. 1a and b. The electronic, transport, and device properties of devices with 2D MoS<sub>2</sub> monolayer were comprehensively studied previously [2]–[4], however, patterning MoS<sub>2</sub> into quasi-one-dimensional (quasi-1D) structures such as nanoribbons provides an additional degree of freedom. This nanostructure enables the tuning of electron and transport properties via quantum confinement effects and allows a strong influence of edge atoms on the characteristics of MoS<sub>2</sub> nanoribbons (MoS<sub>2</sub>NRs). Consequently, a high number of possible MoS<sub>2</sub>NR configurations exists and many of them have been studied previously in both armchair and zigzag directions [5]–[7]. Nevertheless, there are some interesting configurations, such as MoS<sub>2</sub>NRs with hybrid OH-passivated edges shown in Fig. 1a and b, whose transport and device properties have not yet been explored. Electronic properties of hybrid OH-passivated MoS<sub>2</sub>NRs were studied in [8] where this configurations was proven



**Fig. 1.** (a) Top and (b) side view of MoS<sub>2</sub>NR with OH passivation (explained in the text). (c) Conduction and valence band profiles along the channel length with an illustration of real and complex bandstructure used in UTB and TOB calculations.

to be one of the most stable edge passivation configurations for future MoS<sub>2</sub>-based nanodevices.

In addition to stability, low OFF-state leakage current ( $I_{OFF}$ ) is one of the critical requirements for future low power/high density devices. However,  $I_{OFF}$  has not yet been studied in ultra-scaled FETs with channels made of MoS<sub>2</sub>NRs with hybrid OH passivation. In this paper, we present a study on  $I_{OFF}$  of MoS<sub>2</sub>NR FETs using our in-house non-equilibrium Green's function (NEGF) formalism based quantum transport solver [9], [10]. The NEGF calculations are employed in conjunction with top-of-the-barrier (ToB) model [11] for the ballistic thermionic current and with the under-the-barrier (UTB) model [12],[13] that accounts for intra-band tunneling, as indicated in Fig. 1c. Highly accurate space-localized



Hamiltonians are obtained from *ab initio* plane-wave density functional theory (DFT) calculations using maximally-localized Wannier functions (MLWFs). We report strong suppression of tunneling for all the studied MoS<sub>2</sub>NRs even in transistors with 5 nm-long channels, which indicates a robust performance and low  $I_{OFF}$  in ultra-scaled MoS<sub>2</sub>NR FETs.

## II. METHODOLOGY

Armchair MoS<sub>2</sub> nanoribbons passivated with OH of various widths ( $W$ ) ranging from ~0.8 nm to ~3.0 nm are constructed for *ab initio* calculations. For example, the 1.11 nm-wide MoS<sub>2</sub>NR is shown in the top (Fig. 1a) and side view (Fig. 1b) with the transport direction along the horizontal orientation. The hybrid OH passivation is achieved by terminating the edge Mo atoms with O atoms and S atoms with H atoms. Plane-wave DFT is employed in combination with transformation to tight-binding-like sparse matrices using MLWFs [14] that are suitable for NEGF simulations. Quantum Espresso [15] is used for DFT calculations, where a vacuum region of 20 Å is added in the confined directions due to the nature of DFT to assume periodicity in all three directions. The Brillouin zone (BZ) is sampled using an  $1 \times 15 \times 1$  Monkhorst-Pack grid [16], where 15 points are used in the transport direction. Perdew-Burke-Ernzerhof generalized gradient approximation (PBE-GGA) [17] exchange-correlation (XC) functional is used along projector augmented wave (PAW) pseudopotentials. The plane-wave cutoff energy is set to 1360 eV, whereas the convergence threshold is set to  $10^{-3}$  eV/Å for the ionic force and to  $10^{-4}$  eV for energy. Wannier90 program [18] is employed to transform the DFT Hamiltonians into the space-localized basis while preserving the accuracy of the DFT. The accuracy of transformation using MLWFs greatly depends on the trial projections on the Bloch manifold. In this work, for OH-passivated MoS<sub>2</sub>NRs,  $d$  orbitals are chosen as trial orbitals for Mo atoms and  $p$  orbitals for S and O atoms. During wannierization, we obtain a Wannier spread lower than 2.5 Å<sup>2</sup> per atom for all MoS<sub>2</sub>NR widths, which indicates successful transformation. After MLWF Hamiltonians of a MoS<sub>2</sub>NR unit-cell are obtained, where the unit-cell designates a super-cell along the entire nanoribbon width, the cell is scaled in the transport direction to construct the total MLWF Hamiltonian of the given MoS<sub>2</sub>NR with lengths ( $L$ ) ranging from ~5 nm to ~20 nm.

The main topic of this paper is the study of  $I_{OFF}$  of n- and p- type MoS<sub>2</sub>NR MOSFET devices with ideal contacts. The  $I_{OFF}$  consists of the thermionic (above barrier) and tunneling (under barrier) current components, as shown in Fig. 1c. The thermionic current is calculated using the ToB model that depends on the density of states (DOS) and transmission spectra obtained using the NEGF simulations [19]–[21], as implemented in our in-house code [9], [10], [22], [23]. Furthermore, UTB model [13] is employed to calculate the tunneling current through the bandgap of the S/D potential barrier. For the UTB model,

tunneling attenuation is needed, which can be obtained from the complex bandstructure. While using real wave-vector  $k$  leads to dispersion of propagating electron waves, setting imaginary values of the wave-vector  $k$  and calculating the dispersion results in tunneling attenuation  $\kappa(E)$  that describes evanescent electron waves. Transmission probability is calculated according to the Wentzel-Kramers-Brillouin (WKB) approximation

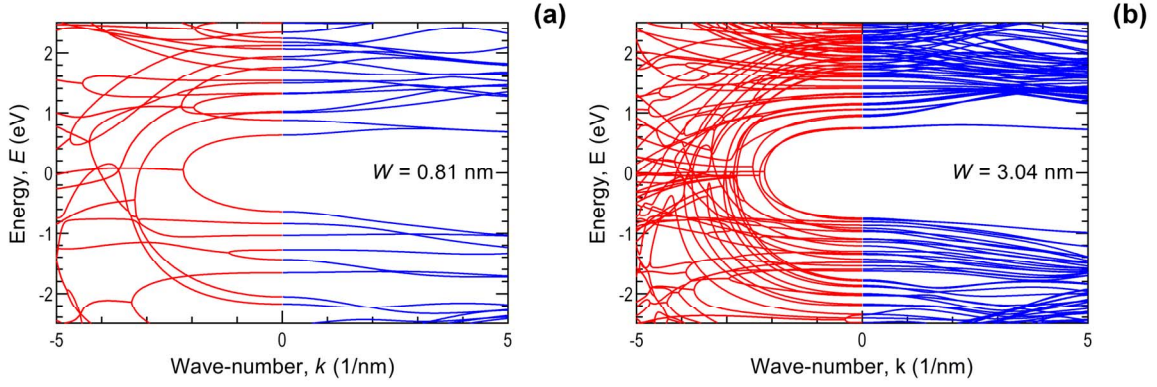
$$T_{WKB} = \sum_n \exp[-2l(E)\kappa(E)] \quad (1)$$

where  $n$  represents the number of complex subbands included in the calculation, while  $l(E)$  is an energy-dependent tunneling barrier length. For simplicity, the potential barrier between the source and drain (S/D) is approximated with a parabolic function. Tunneling current is calculated using the Landauer formula that depends on WKB transmission, barrier height and Fermi-window, i.e. difference between S/D Fermi functions.

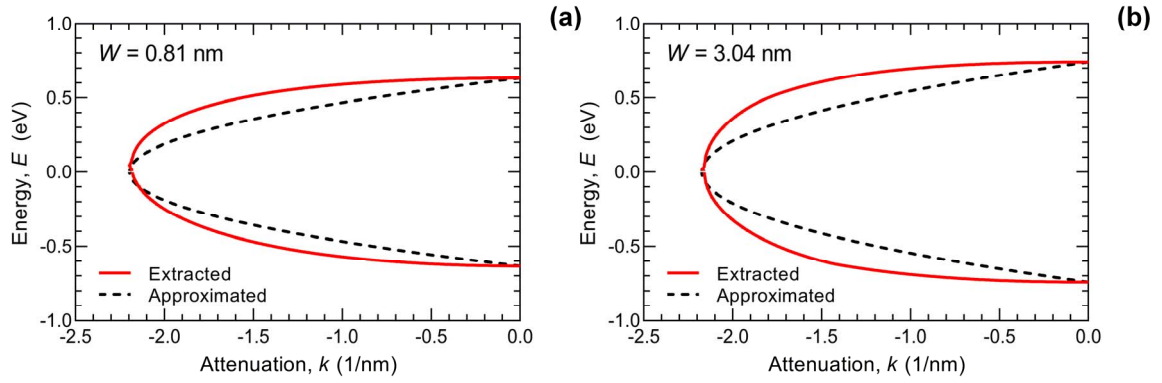
In order to provide meaningful comparison between various MoS<sub>2</sub>NR devices we set a common ToB  $I_{OFF}$  of 10 nA/μm as defined in the International Roadmap for Devices and Systems (IRDS) for future high-performance (HP) CMOS nodes [24]. The  $I_{OFF}$  is set by a proper gate work function, which modifies the flat-band voltage, and accordingly lowers the OFF-state ToB potential that is used in the UTB model. Gate equivalent oxide thickness (EOT) is set to 1 nm and S/D doping is set at 0.01 molar fraction of the MoS<sub>2</sub>NR areal atom density. Device OFF-state performance is studied when the tunneling attenuation  $\kappa(E)$  is extracted directly from the complex bandstructure, and when  $\kappa(E)$  is approximated with a parabolic function as is originally done in the literature [13]. The parabolic  $\kappa(E)$  is defined by the maximum attenuation, occurring usually near the mid-gap, and the bandgap value. Furthermore, nanoribbon width and length scaling effects on the tunneling component of  $I_{OFF}$  are studied because the thermionic current is ballistic and, hence, independent of nanoribbon length.

## III. RESULTS AND DISCUSSION

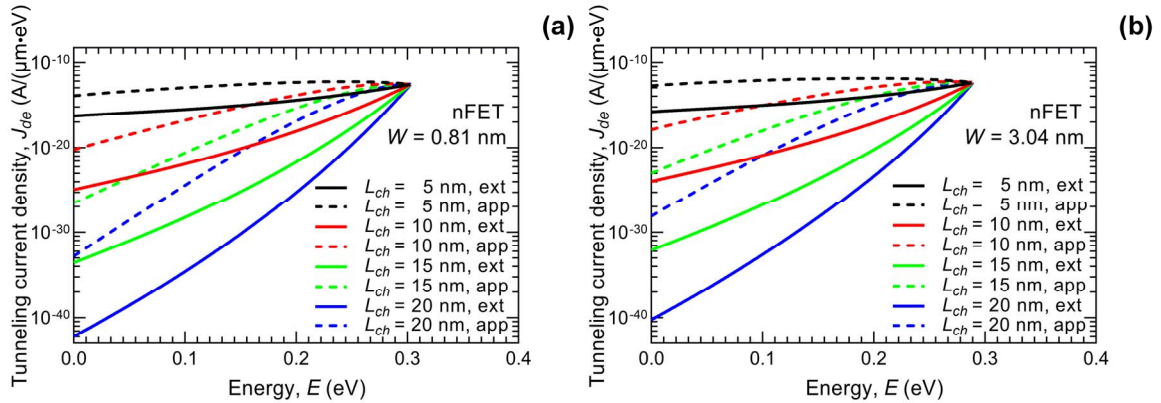
Figure 2 reports the bandstructure consisting of the complex part for imaginary  $k$  as negative values, and the real part for real  $k$  as positive values, for  $W = 0.81$  nm (Fig. 2a) and  $W = 3.04$  nm (Fig. 2b). Scaling down the nanoribbon width decreases the number of subbands and, consequently, the number of complex subbands inside the bandgap also decreases. While scaling down the width generally decreases the bandgap, i.e. from 1.5 eV for  $W = 3.04$  nm to 1.25 eV for the 0.81 nm-wide nanoribbon, the attenuation curves of the dominant subband do not change as much. We observe that the two attenuation characteristics exhibit qualitatively similar behavior with maximum attenuation of  $\sim 2$  nm<sup>-1</sup> being equal for both MoS<sub>2</sub>NRs in Fig. 2.



**Fig. 2.** Complex and real bandstructure of MoS<sub>2</sub>NRs with the widths of (a)  $W = 0.81$  nm, and (b)  $W = 3.04$  nm. Real part is on the right-hand-side for positive  $k$ , and the complex part (attenuation) is on the left-hand-side for negative  $k$ .



**Fig. 3.** Extracted and approximated attenuation characteristics of the dominant (with the lowest attenuation) complex subband for (a) 0.81 nm- and (b) 3.04 nm-wide MoS<sub>2</sub>NRs.



**Fig. 4.** Tunneling current energy density for MoS<sub>2</sub>NR nFETs calculated with the exact extracted (ext) and approximated (app) attenuation for (a)  $W = 0.81$  nm, and (b)  $W = 3.04$  nm, and for four channel lengths equal to 5 nm, 10 nm, 15 nm and 20 nm.

The first subband belonging to evanescent waves, which connects the highest valence band with the lowest conduction band, can be extracted and then approximated with a parabola. Although using the approximation is much simpler to implement in the simulation environment, a large difference in attenuation is observed when comparing the extracted and approximated attenuation. The difference is reported in Fig. 3a for the 0.81 nm-wide nanoribbon, and an even larger mismatch is observed for  $W = 3.04$  nm in Fig. 3b. Attenuation is the lowest near the conduction band minimum (CBM) and valence band

maximum (VBM) which means that the tunneling OFF-state current is dominantly determined in the energy regions near the CBM for nFETs, and near the VBM for pFETs. Going towards mid-gap, the attenuation increases in both MoS<sub>2</sub>NRs and reaches  $\sim 2.2$  nm<sup>-1</sup>, which turns off significant tunneling in this energy range.

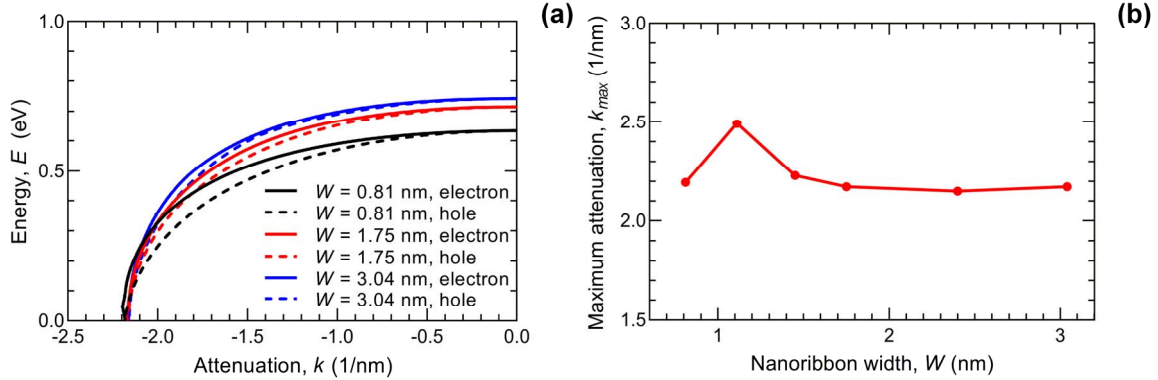
In order to assess the differences in using the extracted and approximated attenuation curves, the tunneling current energy density ( $J_{de}$ ), hereafter current density, is shown in Fig. 4 for various MoS<sub>2</sub>NRs nFETs, with four different

channel lengths in the range from  $\sim 5$  nm to  $\sim 20$  nm, and the widths of  $W = 0.81$  nm (Fig. 4a) and  $W = 3.04$  nm (Fig. 4b). The tunneling transport occurs between  $E = 0$  eV (mid-gap) and  $E \sim 0.3$  eV (CBM). The current density calculated with the approximated attenuation is up to 12 orders of magnitude higher than the current density calculated using the exact extracted attenuation, which demonstrates the inadequacy of the parabolic approximation for quantitative prediction of the tunneling component of  $I_{OFF}$ . In both attenuation models,  $J_{de}$  increases while scaling down MoS<sub>2</sub>NR channel length from 20 nm to 5 nm due to decreasing tunneling length. When the extracted  $\kappa(E)$  is used, the maximum  $J_{de}$  occurs at the top of the barrier for all channel lengths. On the other hand,  $J_{de}$  calculated using the parabolic  $\kappa(E)$  exhibits a maximum at the top of the barrier only for channels longer than  $\sim 15$  nm. As shown in Fig. 4, for shorter channels the  $J_{de}$  maximum shifts towards the mid-gap, which is clearly unphysical. Significant difference in  $J_{de}$  magnitude and the shift of the maximum show that the approximated parabolic  $\kappa(E)$  model is not appropriate to assess the OFF-state performance and, therefore, in further calculations only the extracted  $\kappa(E)$  is used.

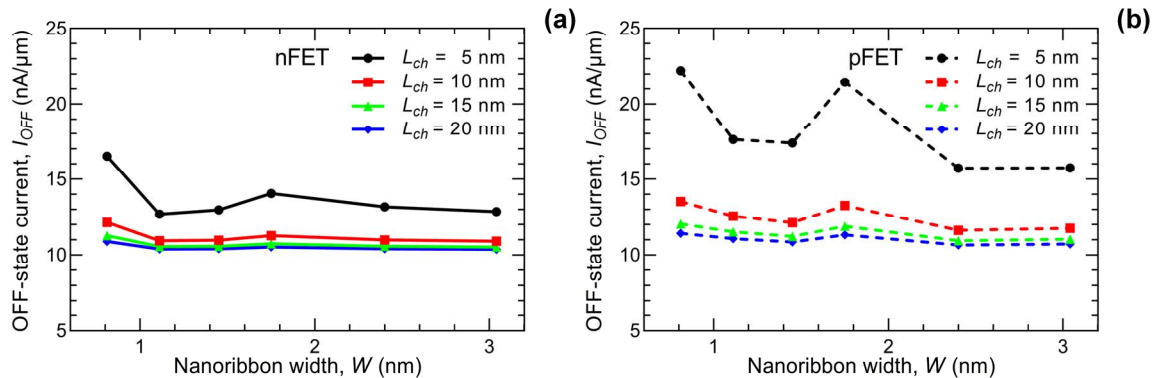
The extracted attenuation exhibits differences between electron and hole attenuation characteristics, i.e.  $\kappa(E)$  curves from the mid-gap towards either CBM or VBM, as

shown in Fig. 5a. In turn, nFET and pFET devices with MoS<sub>2</sub>NR channels are expected to have different tunneling characteristics. Scaling down MoS<sub>2</sub>NR width increases the mismatch between the electron and hole attenuations, with hole  $\kappa(E)$  being lower than the electron  $\kappa(E)$ . This difference points to a higher OFF-state current for pFET devices generally, and the difference is expected to increase as  $W$  decreases. Maximum attenuation equals  $\sim 2.2$  nm<sup>-1</sup> for all MoS<sub>2</sub>NRs with the exception for  $W = 1.11$  nm where the maximum  $\kappa(E)$  is slightly higher at  $\sim 2.5$  nm<sup>-1</sup>, as reported in Fig. 5b.

The total OFF-state current per nanoribbon width is calculated for various MoS<sub>2</sub>NR widths and channel lengths in the range from 20 nm to 5 nm and is shown in Fig. 6. The total  $I_{OFF}$  is a sum of the tunneling current, calculated by integrating the current density  $J_{de}$  over the Fermi window, and of the  $L$ -independent thermionic current, set to 10 nA/ $\mu$ m for all devices in ToB simulations. Scaling down channel length results in a significant increase of  $I_{OFF}$  in both nFETs (Fig. 6a) and pFETs (Fig. 6b), especially in 5 nm-long devices with the shortest S/D tunnel barrier. The total  $I_{OFF}$  is of the same magnitude for all n- and p- type MoS<sub>2</sub>NR FETs with  $L \geq 10$  nm, while a considerable difference is observed only for  $L = 5$  nm. For nFETs with the 5 nm-long channel, maximum  $I_{OFF}$  of 16.5 nA/ $\mu$ m is observed for  $W = 0.81$  nm and minimum



**Fig. 5.** (a) Extracted attenuation characteristics for electrons and holes for various widths of the MoS<sub>2</sub>NR. The energy range spans from mid-gap at 0 eV to band minimum or maximum. (b) Dependence of the maximum attenuation of the dominant complex subband on the MoS<sub>2</sub>NR width.



**Fig. 6.** Impact of MoS<sub>2</sub>NR width scaling on total OFF-state current for (a) nFET and (b) pFET for various channel lengths ranging from 5 nm to 20 nm.

$I_{OFF}$  of 12.7 nA/ $\mu\text{m}$  for the nFET with the 1.11 nm-wide MoS<sub>2</sub>NR channel. On the other hand, pFET with the channel length of 5 nm shows the maximum  $I_{OFF}$  of 22 nA/ $\mu\text{m}$  for  $W = 0.81$  nm and the minimum  $I_{OFF}$  of 15.7 nA/ $\mu\text{m}$  for  $W = 3.04$  nm. These results show that a direct consequence of the lower hole attenuation compared to electron  $\kappa(E)$  is the higher tunneling current in pFETs that ranges from 5.7 to 12 nA/ $\mu\text{m}$  in pFETs, in comparison to 2.7 to 6.5 nA/ $\mu\text{m}$  in nFETs. Finally, we note that the general increase and non-monotonic dependence of  $I_{OFF}$  on  $W$  reported in Fig. 6 is a consequence of non-monotonic features of  $\kappa(E)$  (see Fig. 5b) and width-normalization of the drain current.

#### IV. CONCLUSIONS

Some features of NEGF calculations combined with the UTB and ToB models are used to calculate the tunneling and thermionic OFF-state currents in ultra-scaled MoS<sub>2</sub>NR FETs with n- and p-type channels. Regarding the UTB model, we report a significant overestimation of tunneling leakage when a simple parabolic approximation of  $\kappa(E)$  is used, rendering it useless for quantitative predictions about tunneling in ultra-scaled MoS<sub>2</sub> nanostructures. We report that scaling down channel length results in the expected growth of the tunneling current that is especially evident for sub-10 nm-long MoS<sub>2</sub>NRs n- and pFETs. Due to weaker attenuation pFETs exhibit larger tunneling leakage, i.e. for  $L = 5$  nm the total  $I_{OFF}$  is lower than 16.5 nA/ $\mu\text{m}$  for nFETs and under 22 nA/ $\mu\text{m}$  for pFETs. Generally, all MoS<sub>2</sub>NRs show strong attenuation that ensures an appropriate suppression of tunneling in sub-3 nm-wide and sub-20 nm-long MoS<sub>2</sub>NR FETs.

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# Biography

Mislav Matic was born in 1995 in Zagreb, Croatia, where he completed primary and secondary school. In 2018, he graduated from the BS degree program in Electrical Engineering and Information Technology at the Faculty of Electrical Engineering and Computing, University of Zagreb (UNIZG-FER). In June 2020, he graduated from the same institution with a MS in Electronics *cum laude* (4.92 GPA). Since October 2020, he has been working as a research assistant in the Department of Electronics, Microelectronics, Computer and Intelligent Systems (ZEMRIS) at UNIZG-FER on the CONAN2D project (Computational design of nanotransistors based on novel 2D materials, Grant. No. UIP-2019-04-3493, sponsored by the Croatian Science Foundation) under the supervision of Assoc. Prof. Mirko Poljak, PhD. During his PhD studies, he participated in the SiNANO 2022 summer school in Glasgow, UK, and the European School On Nanosciences and Nanotechnologies (ESONN) 2023 in Grenoble, France. In addition, he was a visiting researcher at IHP-Frankfurt, Germany, twice for two weeks in 2022 and 2023 as part of the bilateral Croatia-Germany project GRONGER led by Assoc. Prof. Mirko Poljak and Dr. Mindaugas Lukosius. His research efforts focus on the development of advanced atomistic simulation software to predict the performance of nanotransistors based on 2D materials. To date, he has authored or co-authored 12 journal papers and 14 conference papers.

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# Životopis

Mislav Matić rođen je 1995. godine u Zagrebu, Hrvatska, gdje je završio osnovnu i srednju školu. Godine 2018. završio je preddiplomski studij elektrotehnike i informacijske tehnologije na Fakultetu elektrotehnike i računarstva Sveučilišta u Zagrebu (UNIZG-FER). U lipnju 2020. diplomirao je *cum laude* na istoj instituciji u području elektronike (prosjeak ocjena 4,92). Od listopada 2020. godine radi kao doktorand u Zavodu za elektroniku, mikroelektroniku, računalne i inteligentne sustave (ZEMRIS) na UNIZG-FER-u na projektu CONAN2D (Computational design of nanotransistors based on novel 2D materials, Grant. No. UIP-2019-04-3493, pokrovitelj Hrvatska zaklada za znanost) pod mentorstvom izv. prof. dr. sc. Mirka Poljaka. Tijekom doktorskog studija sudjelovao je na ljetnoj školi SiNANO 2022 u Glasgowu, Ujedinjeno Kraljevstvo, i European School on Nanosciences and Nanotechnologies (ESONN 2023) u Grenobleu, Francuska. Osim toga, bio je gostujući istraživač na IHP-Frankfurt, Njemačka, dva puta po dva tjedna u 2022. i 2023. godini u sklopu bilateralnog hrvatsko-njemačkog projekta GRONGER pod vodstvom izv. prof. dr. sc. Mirka Poljaka i dr. sc. Mindaugasa Lukosiusa. Njegovi istraživački interesi usmjereni su na razvoj naprednog softvera za atomističku simulaciju za predviđanje performansi nanotranzistora temeljenih na 2D materijalima. Autor je ili koautor na 12 radova u časopisima i 14 radova na konferencijama.